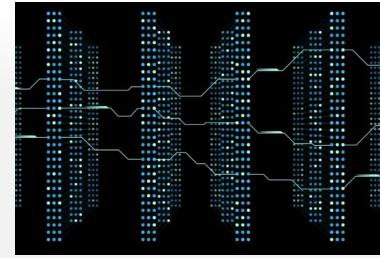
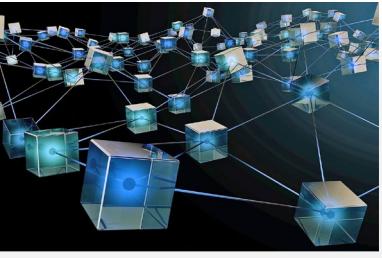
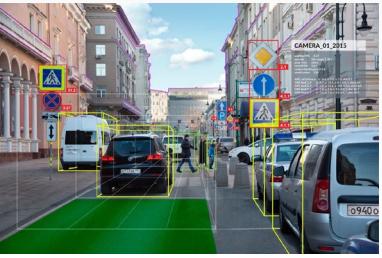
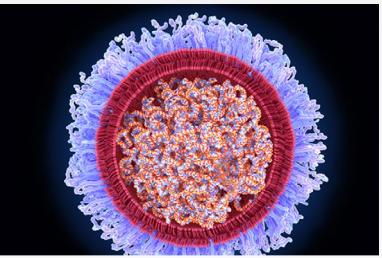


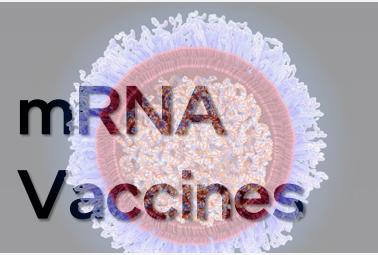
This event includes forward-looking statements about future products and other topics, which are based on our current expectations and subject to risks and uncertainties. Please refer to the press release for this event and our SEC filings at intc.com for more information on the risk factors that could cause actual results to differ materially.



Architecture Day

2021





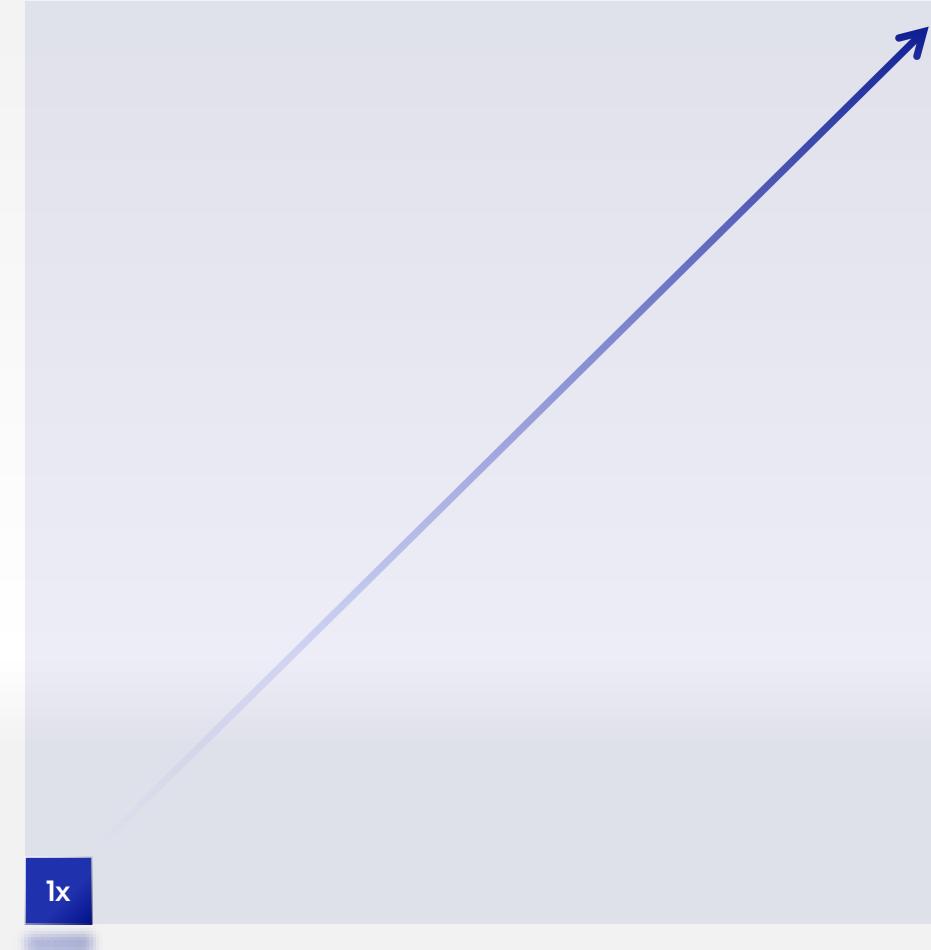
1000x

by 2025



1000x

by 2025



1000x
by 2025

=

(Moore's Law)⁵

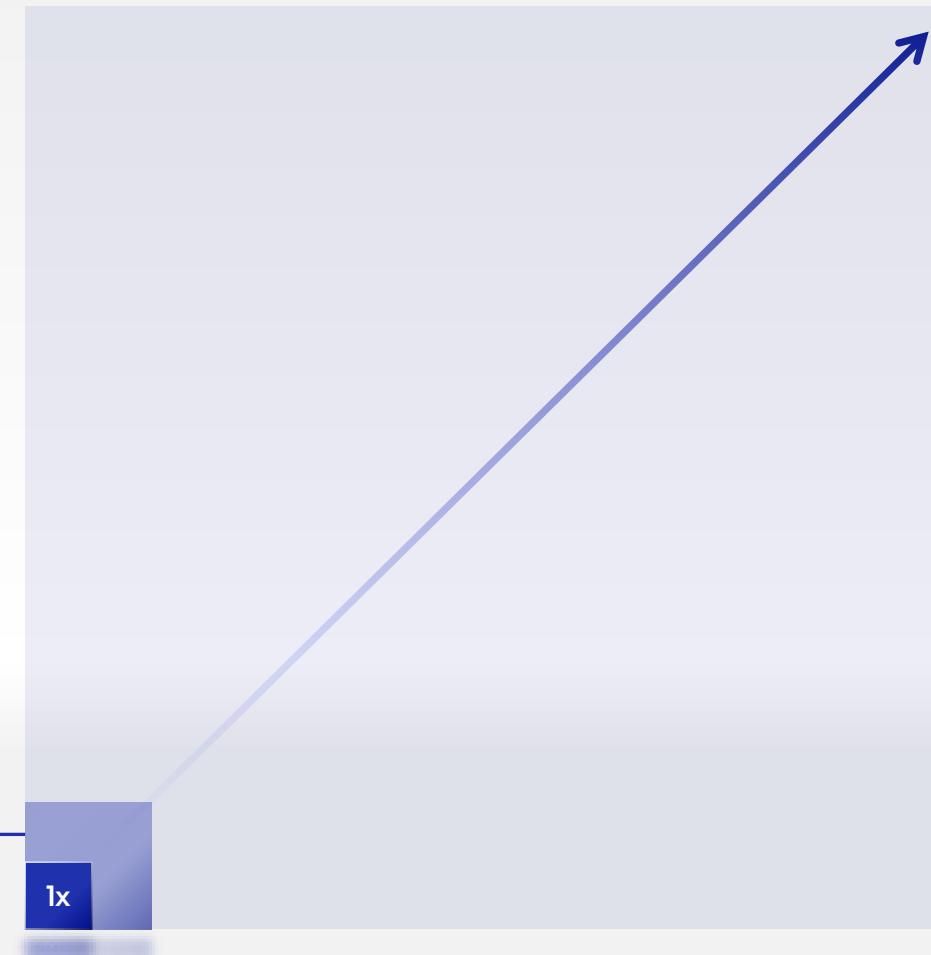
1x

1000x

by 2025

Process & Packaging —

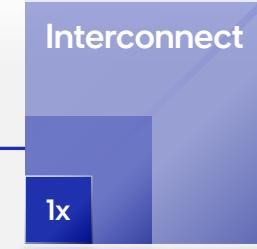
1x



1000x

by 2025

Process & Packaging —



1000x

by 2025

Process & Packaging

Memory

Interconnect

1x



1000x

Architecture

Software

Memory

Interconnect

Process & Packaging

1x

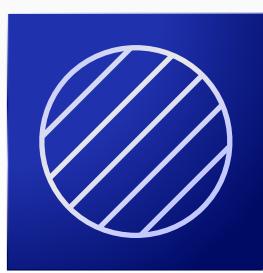
Scalar



Scalar



Vector



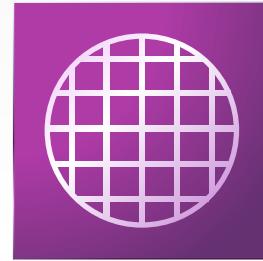
Scalar



Vector



Matrix



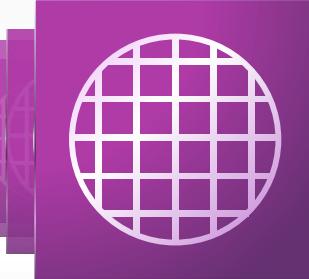
Scalar



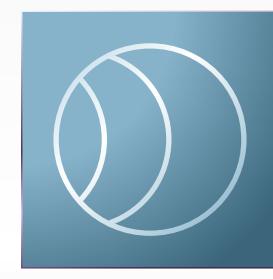
Vector



Matrix



Spatial



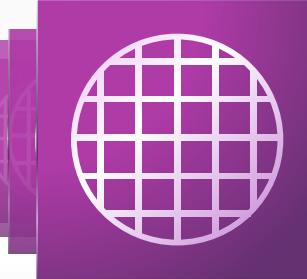
Scalar



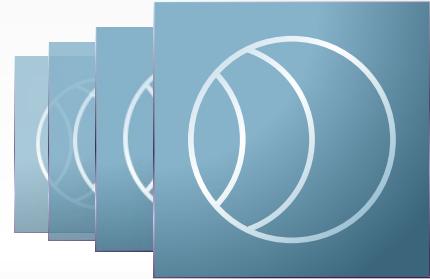
Vector



Matrix



Spatial



Hybrid Computing Architectures



Hybrid Computing Architectures

Process

Packaging

Caches

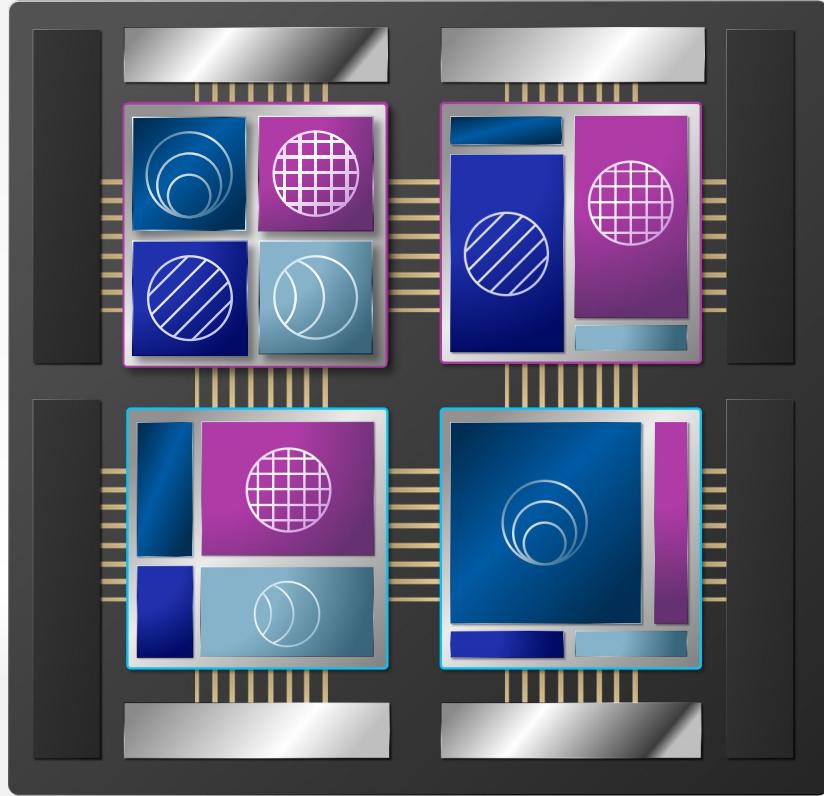
Memory

Interconnect



Hybrid Compute Cluster

in a Package



Performance
Core

Efficient
Core

Intel
Thread
Director

X^e - core

Sapphire
Rapids

X^e HPC &
Ponte
Vecchio

Alder
Lake

AMX

X^e HPG

Mount Evans

Performance
Core

AMX

Alder
Lake

**Efficient
Core**

Intel
Thread
Director

X^e SS

X^e HPG

X^e - core

Sapphire
Rapids

Mount Evans

X^e HPC &
Ponte
Vecchio

Efficient x86 Core

Stephen Robinson

Microarchitecture Goals

Highly Scalable Architecture To Address the Throughput Efficiency Needs For the Next Decade of Compute



Intel's Most Efficient Performant CPU



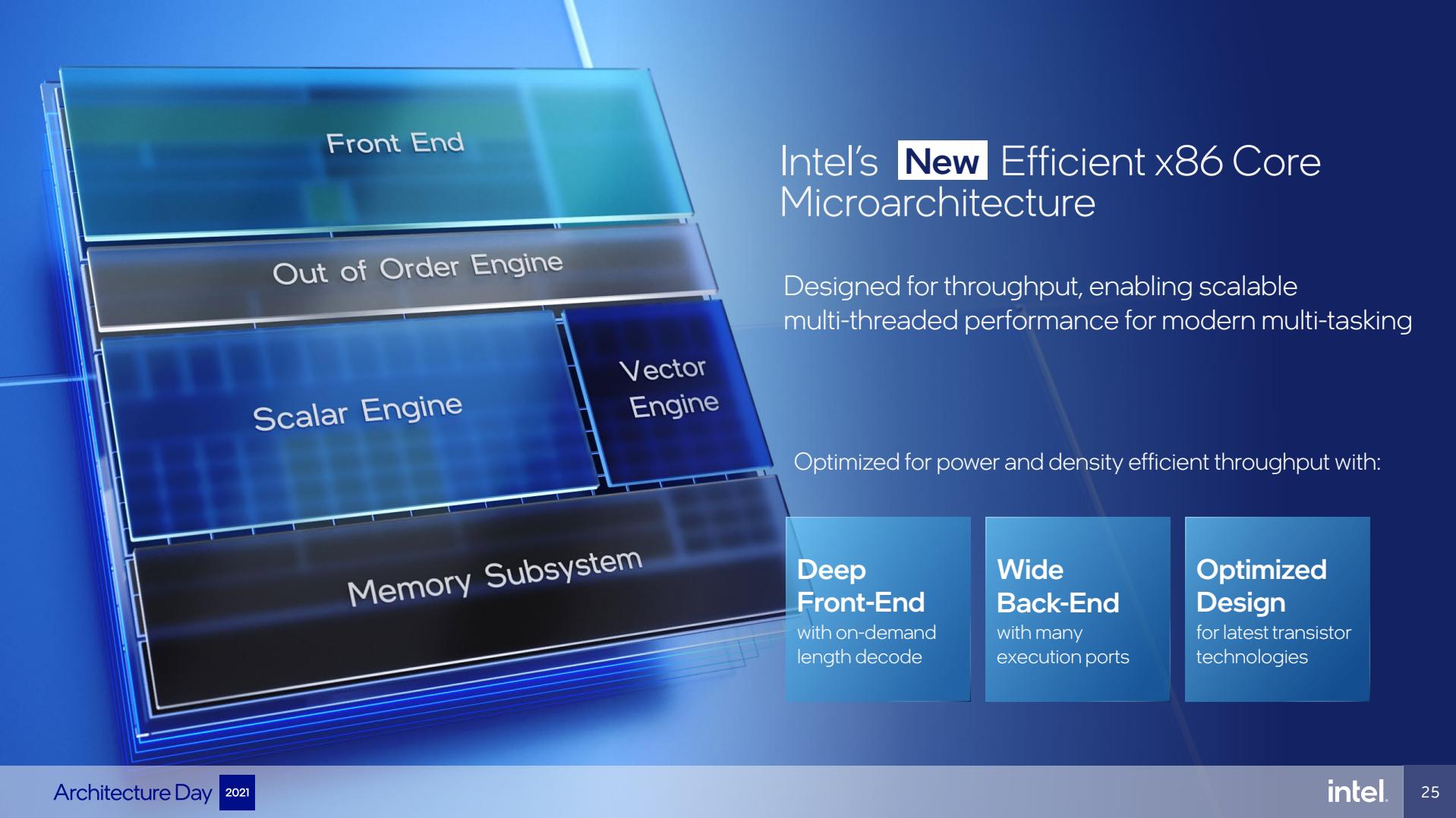
Dense & Highly Scalable



Vector and AI Instruction Support



Wide Dynamic Range



Intel's **New** Efficient x86 Core Microarchitecture

Designed for throughput, enabling scalable multi-threaded performance for modern multi-tasking

Optimized for power and density efficient throughput with:

Deep Front-End
with on-demand length decode

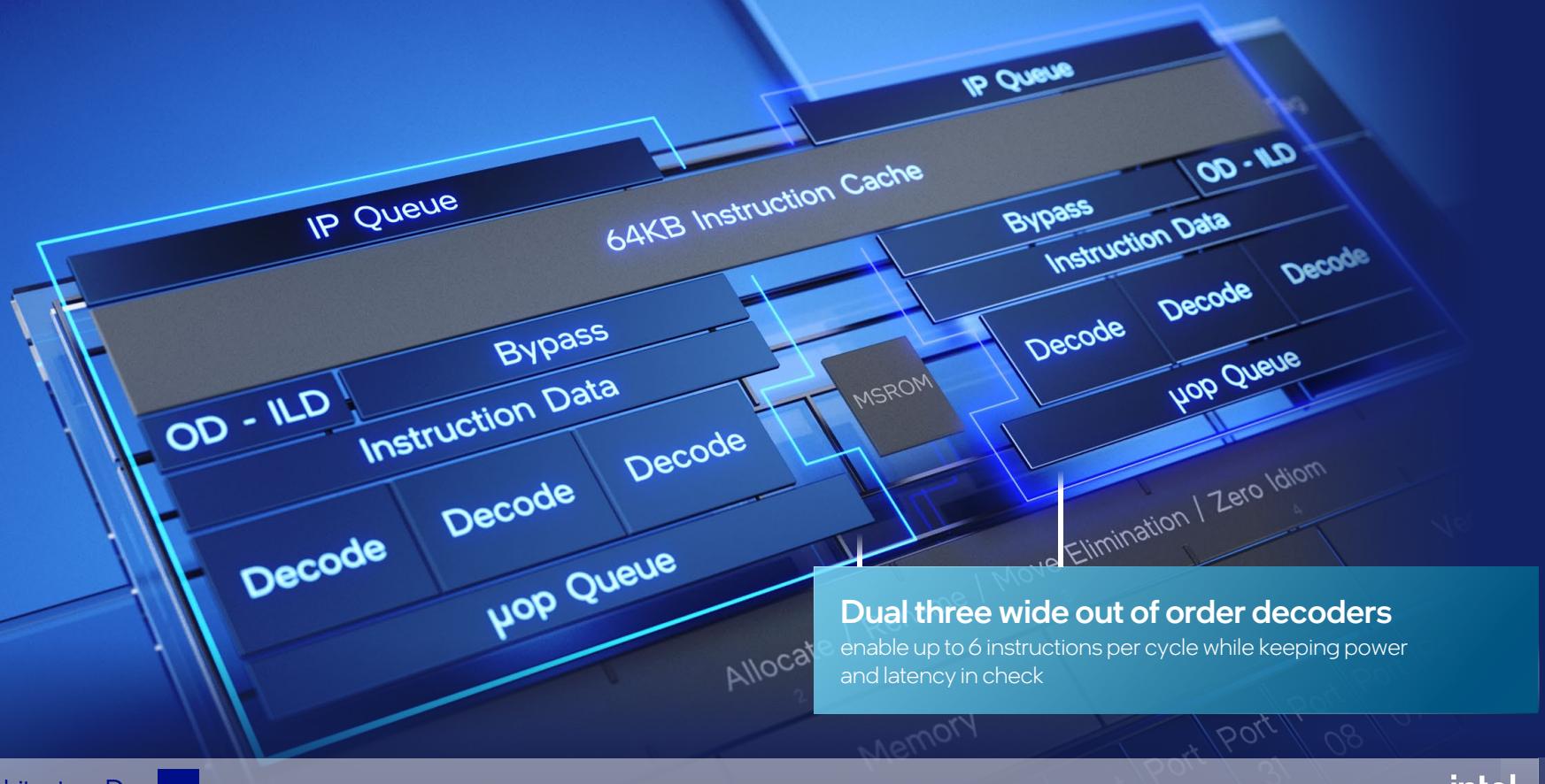
Wide Back-End
with many execution ports

Optimized Design
for latest transistor technologies

Instruction Control



Instruction Control



Data Execution

**Five-wide allocation
with eight-wide retire**

**256 entry
out of order window**

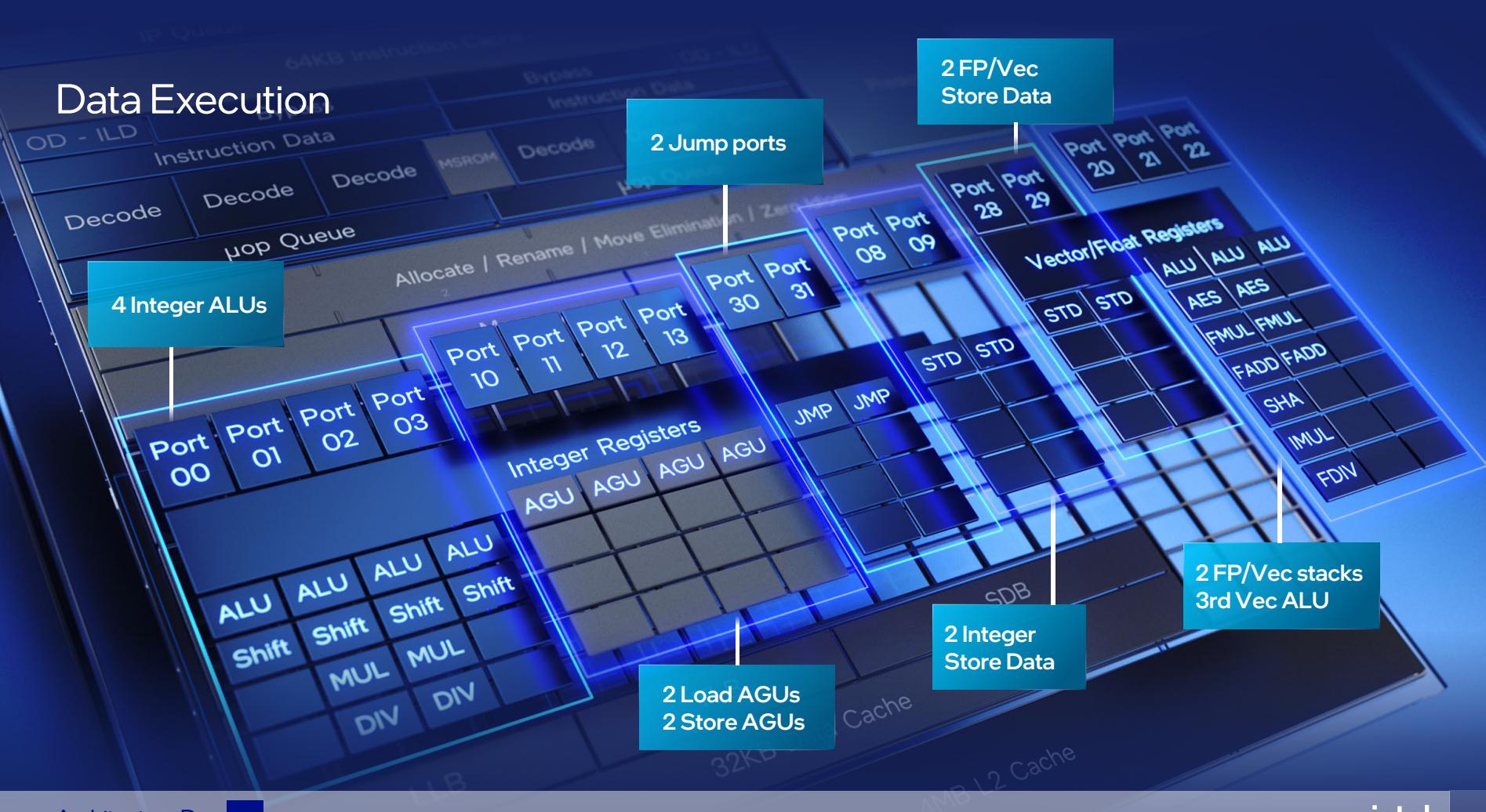
Discovers data parallelism

**Seventeen
execution ports**

Executes data parallelism



Data Execution



Memory Subsystem

Dual Load + Dual Store

Up to 4MB L2

shared among four cores
with 64 Bytes/cycle bandwidth in 17 cycles of latency

Deep buffering

supporting 64 outstanding misses

Advanced Prefetchers

at all cache levels to detect a wide variety of streams

Intel® Resource Director Technology

enables software to control fairness among the cores
and between different software threads



Modern Instruction Set

Security

Intel® Control-flow Enforcement Technology designed to improve defense in depth

Intel® VT-rp
(Virtualization Technology redirect protection) Supported

Advanced speculative execution validation methodology

Support for **Advanced Vector Instructions** with AI extensions

Wide Vector Instruction Set Architecture

Floating point multiply-accumulate (FMA) instructions for 2x throughput

Key instruction additions to enable integer AI throughput (VNNI)



Efficiency in Both Power and Performance per Transistor

Intense focus on feature selection and design implementation costs

to maximize area efficiency, which in turns enables core count scaling

Low switching energy per instruction

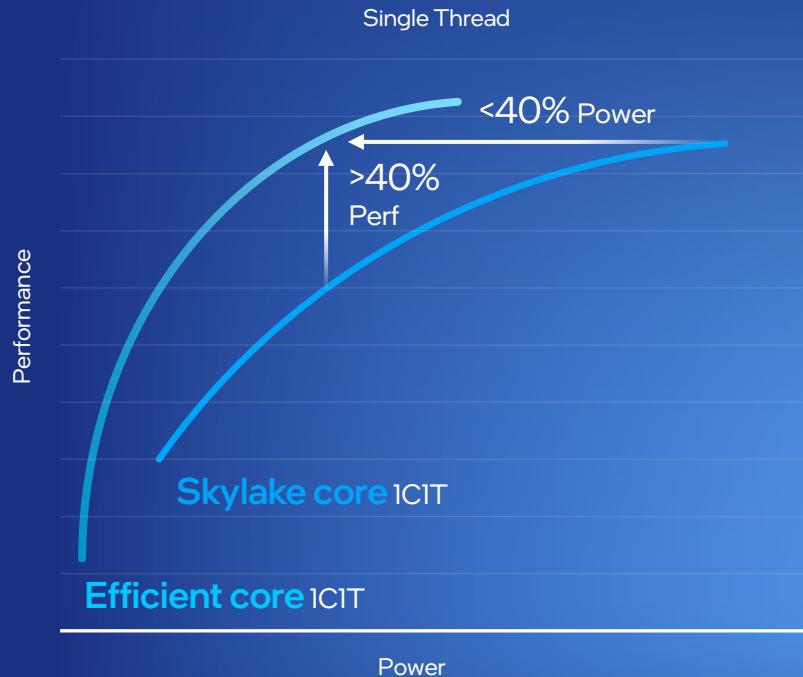
to maximize power constrained throughput, key for today's throughput-driven workloads

Reduced operating voltage required for all frequencies

saving power while extending the performance range

$$P = C \times F \times V^2$$

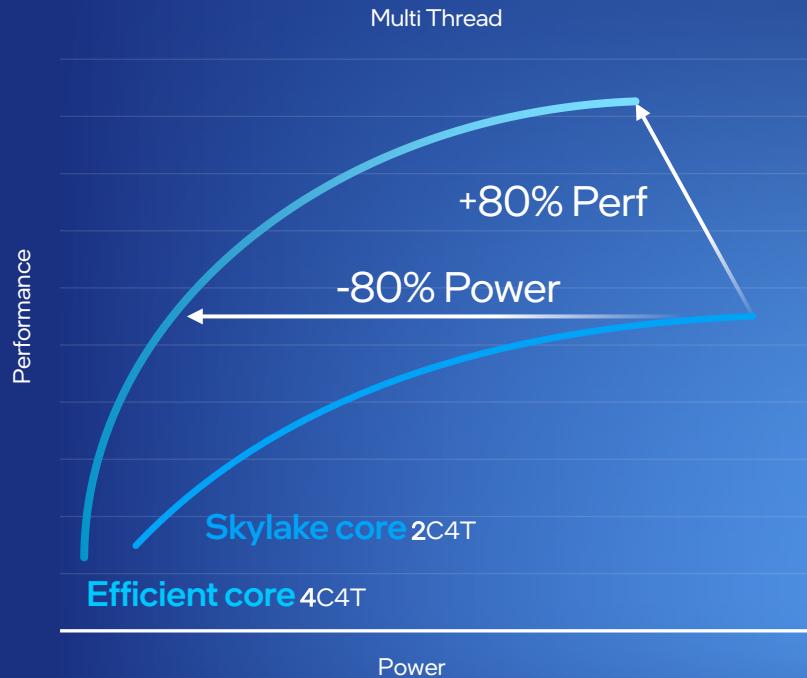
Latency Performance



SPECrate2017_int_base estimates using an open source compiler, iso-binary.
For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.



Throughput Performance



SPECrate2017_int_base estimates using an open source compiler, iso-binary
For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.





Intel's **New** Efficient x86 Core Microarchitecture

Designed for throughput, enabling scalable multi-threaded performance for modern multi-tasking

Optimized for power and density efficient throughput with:

Deep Front-End
with on-demand length decode

Wide Back-End
with many execution ports

Optimized Design
for latest transistor technologies

Performance Core



Architecture Day

2021

New Architectural Foundations

Alder
Lake

X^e HPG

AMX

X^e SS

Intel
Thread
Director

X^e - core

Sapphire
Rapids

Mount Evans

X^e HPC &
Ponte
Vecchio

Performance x86 Core

Adi Yoaz



Performance

x86 Core

Architecture Goals

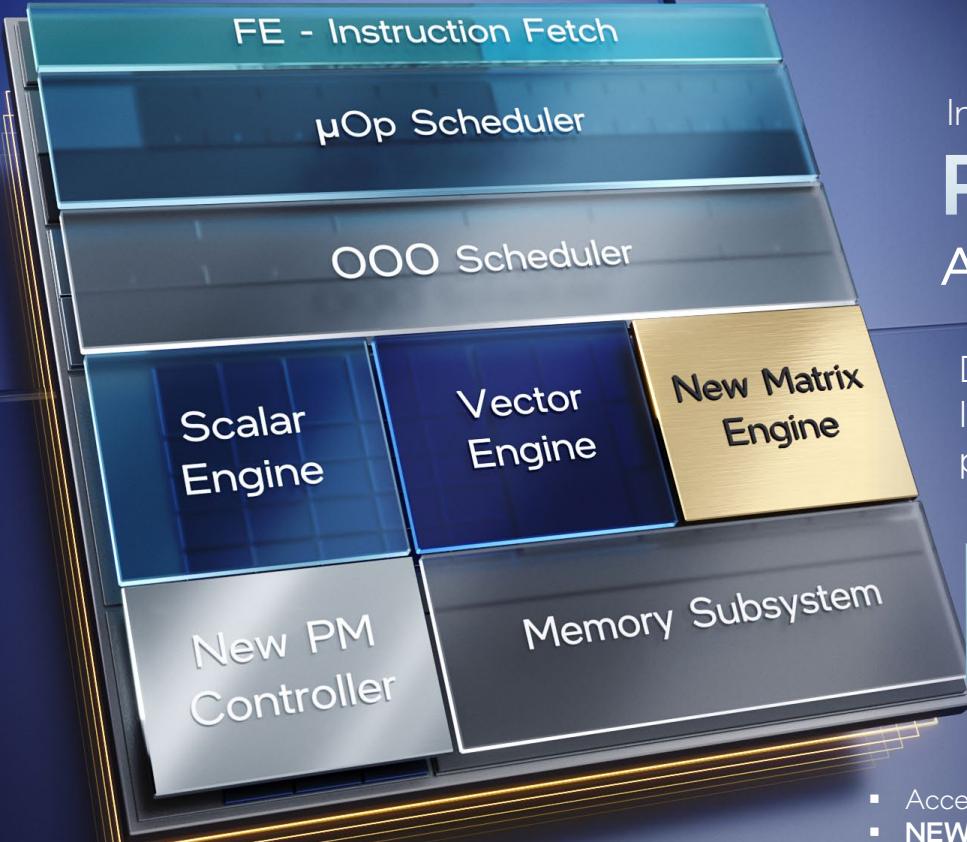
A Step Function in CPU Architecture
Performance For the Next Decade of Compute

All in a tailored scalable architecture to serve the
full range of Laptops to Desktops to Data Centers

Deliver a step function
in general purpose CPU performance

Advance the Arch/uArch with new features
for evolving trends of workload patterns

Innovate with next disruption in
AI performance acceleration



Intel's New

Performance x86 Core Architecture

Designed for speed, pushing the limits of low latency and single threaded application performance via:

Wider

Deeper

Smarter

- Acceleration of workloads with large code footprint & large data sets
- **NEW** AI acceleration technology via coprocessor for matrix multiplication
- **NEW** smart PM controller for fine grain power budget management

Front-End

Fetch instructions and decodes them into μ ops

Large Code

- 128→256 4K iTLB, 16→32 2M/4M iTLB
- Enhanced code prefetch
- 5K→12K branch targets

Wider

- 16B→32B length decode
- 4→6 decoders
- 6→8 μ op/cyc from μ op\$

Smarter

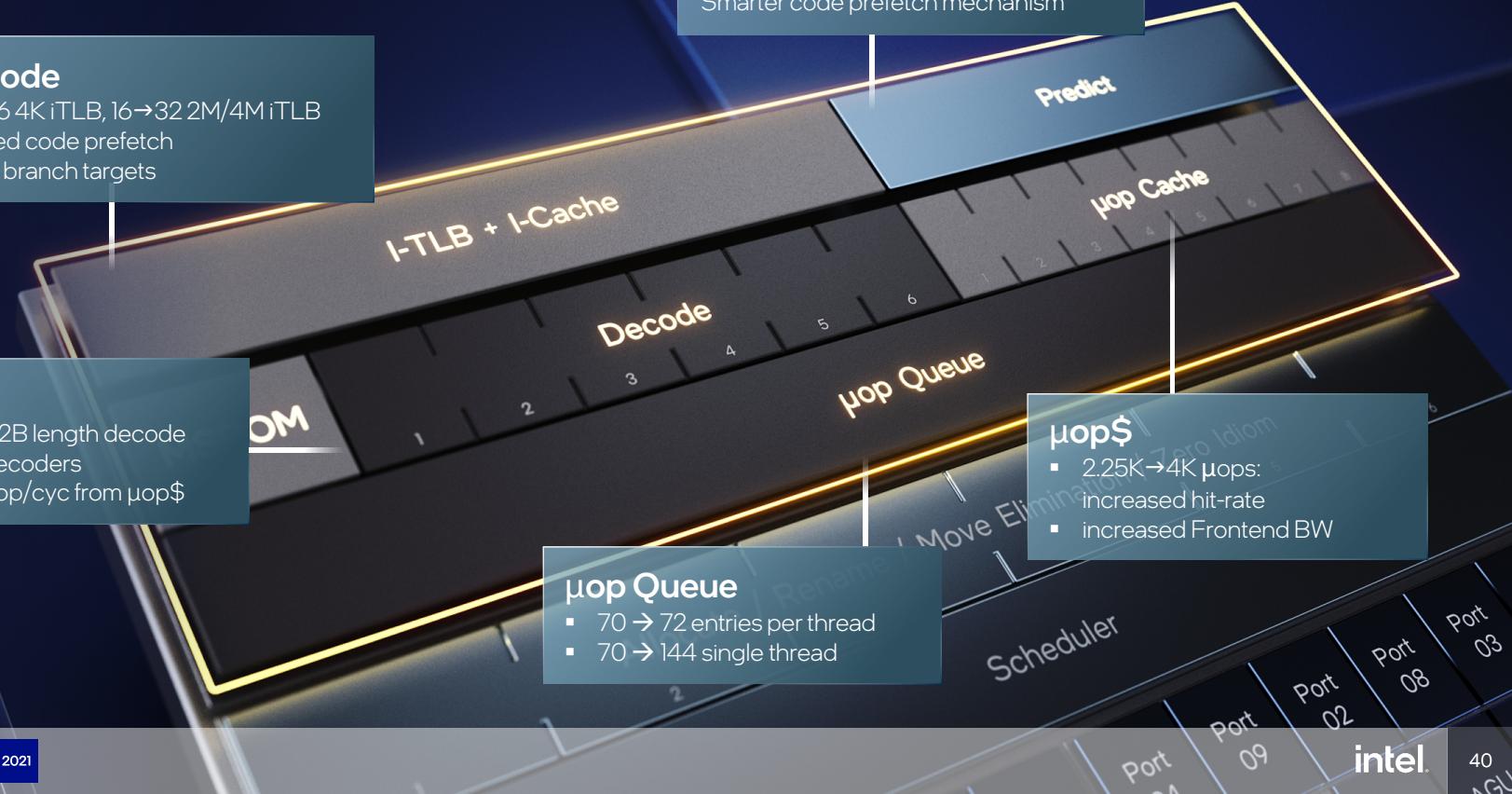
Improved branch prediction accuracy
Smarter code prefetch mechanism

μ op Queue

- 70 → 72 entries per thread
- 70 → 144 single thread

μ op\$

- 2.25K→4K μ ops:
 - increased hit-rate
 - increased Frontend BW



Out of Order Engine

Track μop dependencies and dispatch ready μops to execution units

Wider

5 → 6 wide allocation
10 → 12 execution ports

Deeper

512-entry Reorder-Buffer and larger Scheduler sizes

Smarter

More instructions “executed” at rename / allocation stage



Integer Execution Units

5th Integer execution port /
ALU added

1-cycle LEA on all 5 ports

Used also for arithmetic calculations



Vector Execution Units

New Fast Adder (FADD):

Power efficient, low latency

FMA units support FP16 data type

FP16 added to Intel® AVX512 including complex numbers support



L1 Cache & Memory Subsystem

Wider

- 2 → 3 load ports:
- 3×256bit loads
- 2×512bit loads

Smarter

- Reduced effective Load Latency
- Faster Memory Disambiguation resolution

Deeper

- Deeper Load Buffer and Store Buffer expose more memory parallelism

Large Data

- DTLB 64 → 96
- L1D\$: 12 → 16 fill buffers
- L1D\$ enhanced prefetcher
- 2 → 4 page walkers



L2 Cache & Memory Subsystem

Bigger

L2\$: 1.25MB (client) or 2MB (data center)

Faster

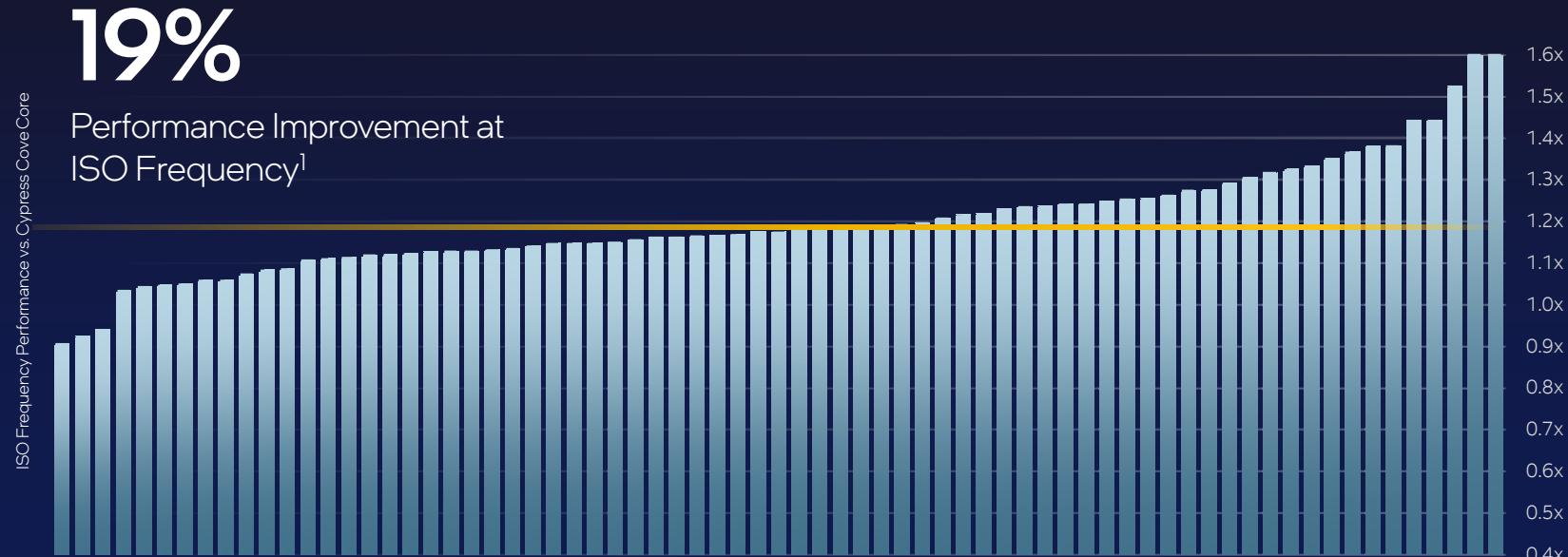
Max demand misses 32 → 48

Smarter

- L2\$ pattern-based multi-path prefetcher
- Feedback-based prefetch throttling
- Full-line-write predictive bandwidth optimization – reduces DRAM reads



General-Purpose Performance Vs. 11th Gen Intel® Core™



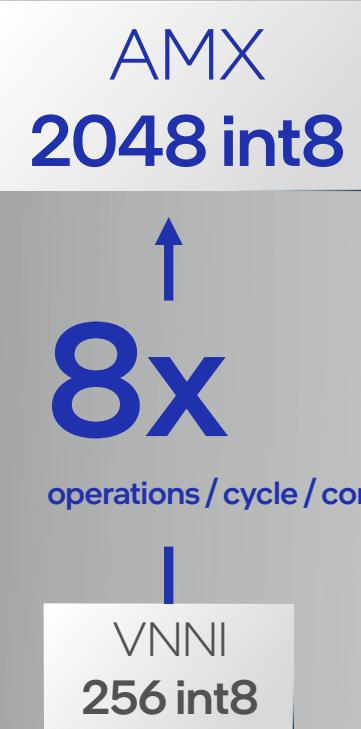
SPEC CPU 2017, SYSmark 25, Crossmark, PCMark 10, WebXPRT3, Geekbench 5.4.1

¹Geomean of Performance core (ADL) vs. Cypress Cove (RKL) Core @ ISO 3.3GHz Frequency

For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Intel® Advanced Matrix Extensions (Intel® AMX)

Tiled Matrix Multiplication Accelerator - Data Center



Intel® Advanced Matrix Extensions (Intel® AMX)

Tiled Matrix Multiplication Accelerator - Data Center

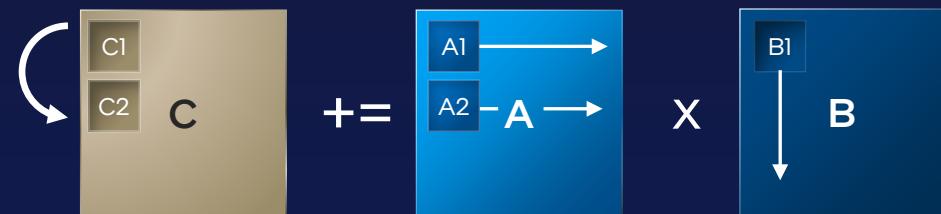
AMX architecture has two components:

Tiles

- A new expandable 2D register file – 8 new registers, 1Kb each: T0-T7
- Register file supports basic data operators – load/store, clear, set to constant, etc.
- TILES declares the state and is OS-managed by XSAVE architecture

TMUL

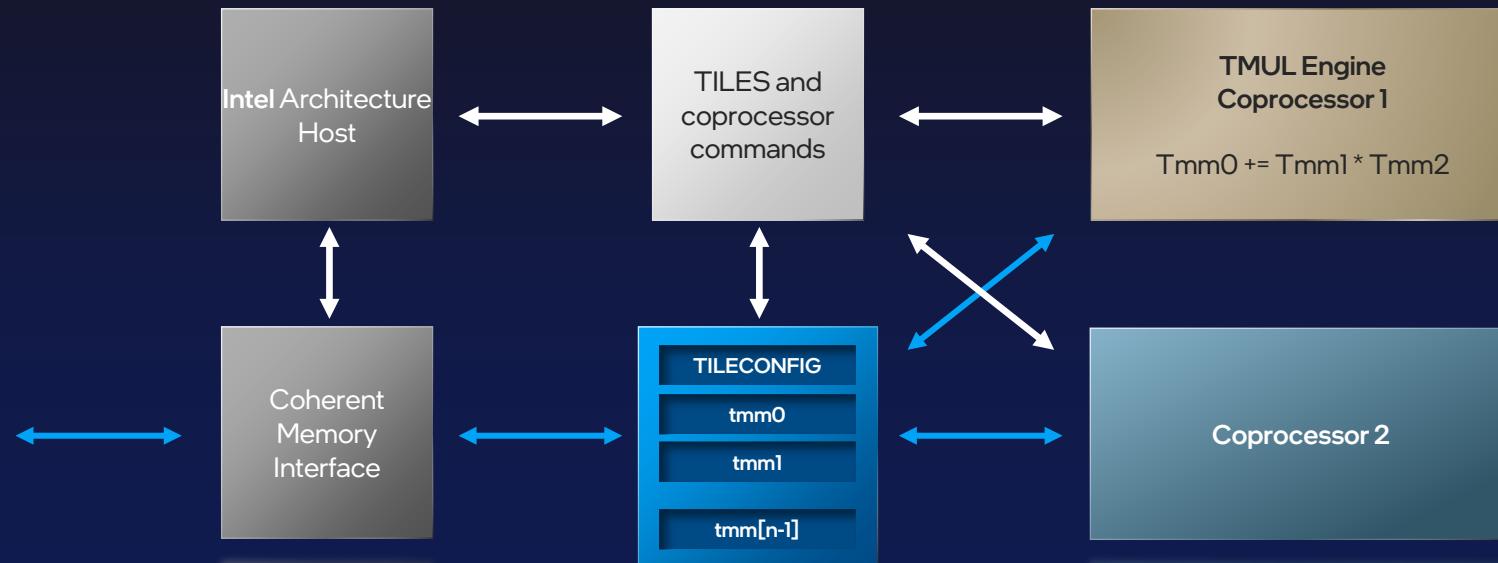
- Set of matrix multiplication instructions, the first operators on TILES
- A MAC computation grid calculates 'tiles' of data
- TMUL – performs Matrix ADD-Multiplication ($C = A * C + B$) using three Tile registers ($T_2 = T_1 * T_0$)
- TMUL requires TILE to be present



Express more work per instruction and per µop –
save power for fetch/decode/OOO

Intel® Advanced Matrix Extensions (Intel® AMX)

Architecture



■ New state to be managed by OS

■ Commands and status delivered synchronously via TILE/accelerator instructions

■ Dataflow – accelerators communicate to host through memory



New

Performance

x86 Core

A Step Function in CPU Architecture
Performance For the Next Decade of Compute

A significant IPC boost at high power efficiency

Wider

Deeper

Smarter

Better supports large data set and large code footprint applications

Enhanced power management improves frequency and power

Machine Learning Technology: Intel® AMX – Tile Multiplication

All in a tailored scalable architecture to serve the full range of Laptops to Desktops to Data Centers

Architecture Day

2021

New Architectural Foundations



Intel Thread Director

X^e - core

Sapphire Rapids

X^e SS

Mount Evans

X^e HPG

Alder Lake

X^e HPC & Ponte Vecchio

Scalar Architecture Roadmap

Coves



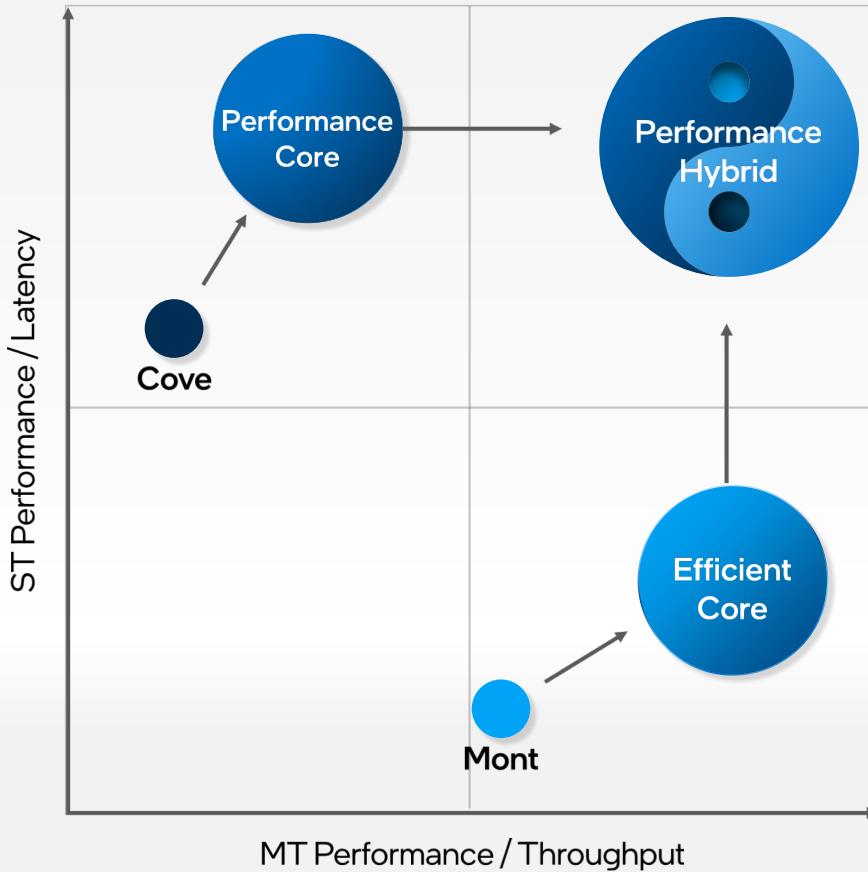
Monts



2019

Today

2021



Graph is for conceptual illustration purposes only.

Intel Thread Director

Rajshree Chabukswar

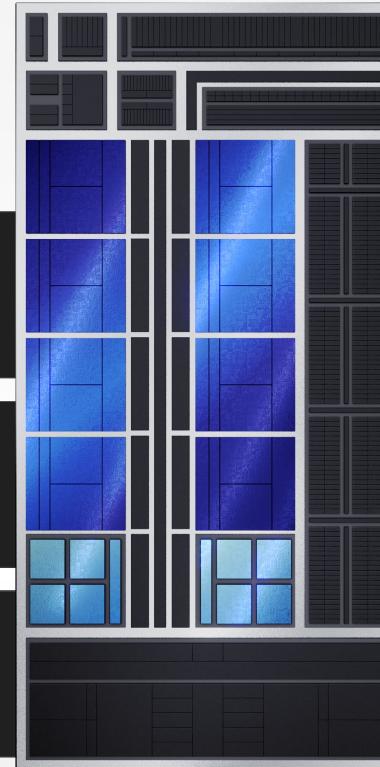
Performance Hybrid

Scheduling Goals

Software Transparent

Real-Time Adaptive

Scalable from Mobile to Desktop



Introducing

Intel Thread Director

Intelligence built directly into the core

Monitors the runtime instruction mix

of each thread and as well as the state of each core – with nanosecond precision

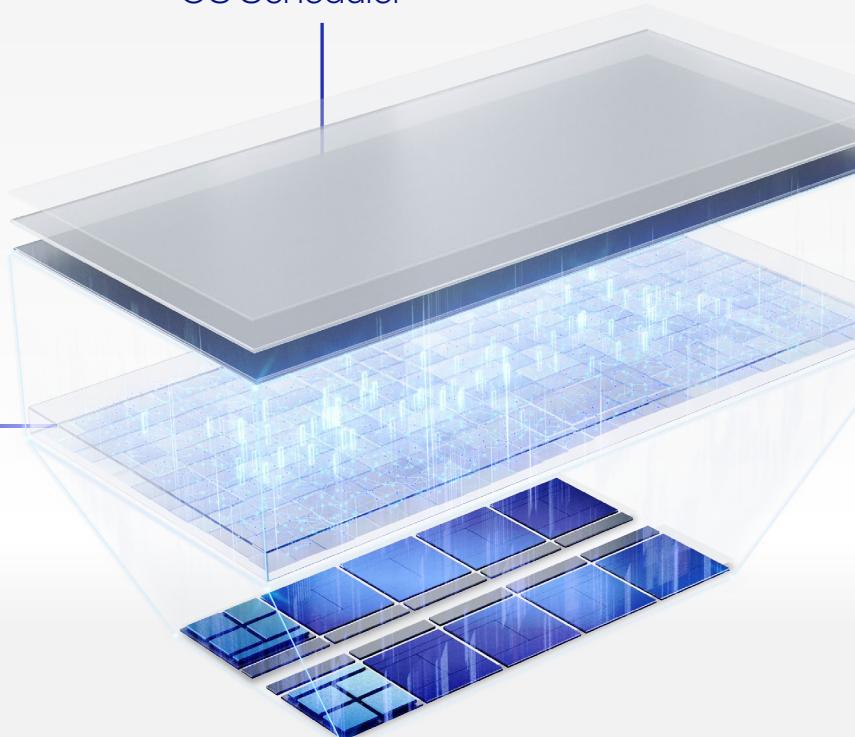
Provides runtime feedback to the OS

to make the optimal scheduling decision for any workload or workflow

Dynamically adapts guidance

based on the thermal design point, operating conditions, and power settings – without any user input

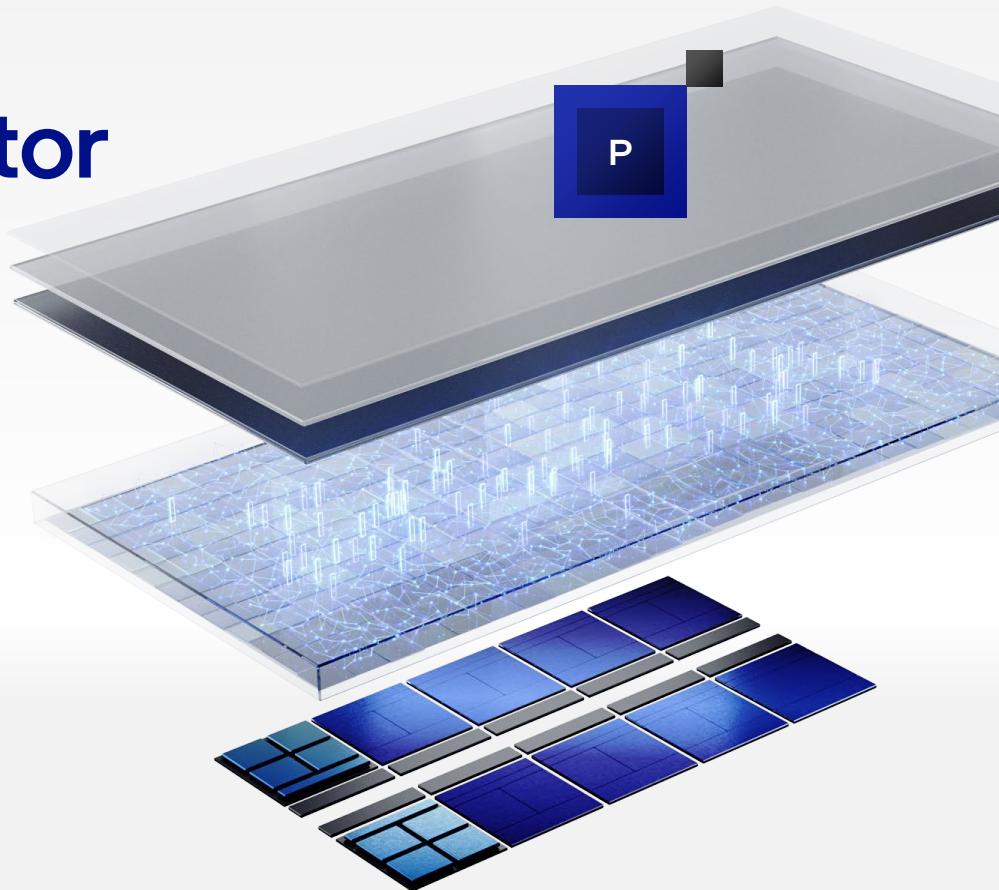
OS Scheduler



Introducing

Intel Thread Director

Scheduling Examples



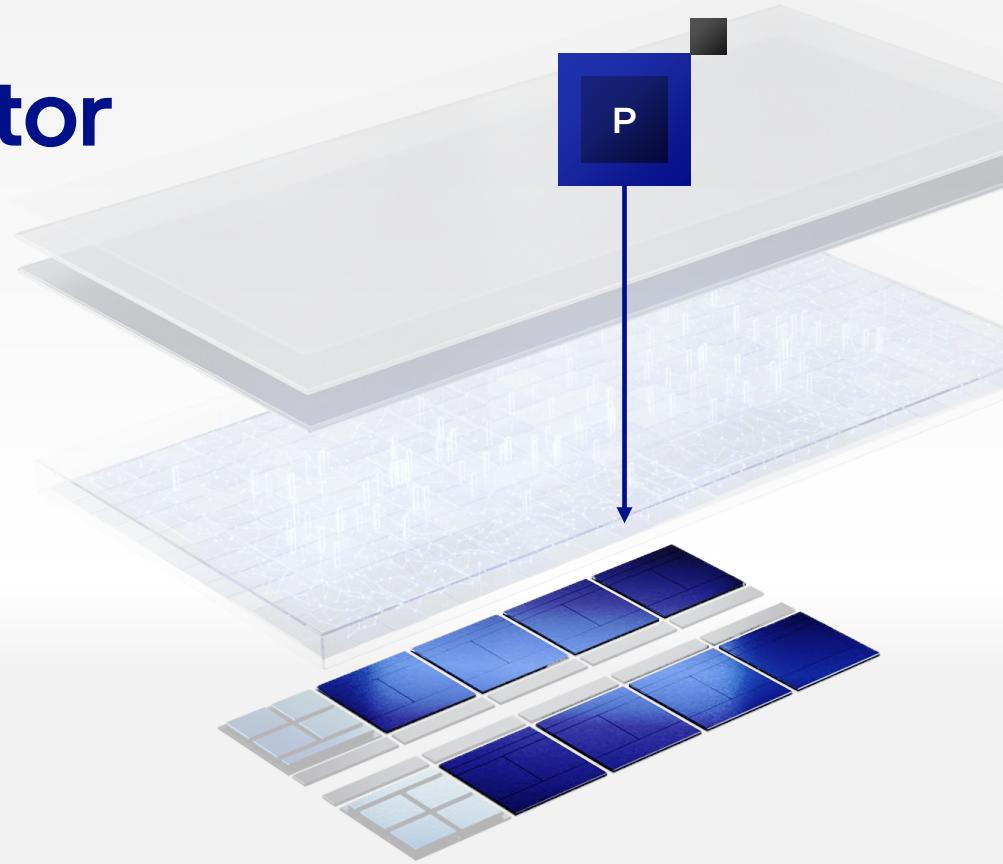
Introducing

Intel Thread Director

Scheduling Examples

1

Priority tasks scheduled on P-cores



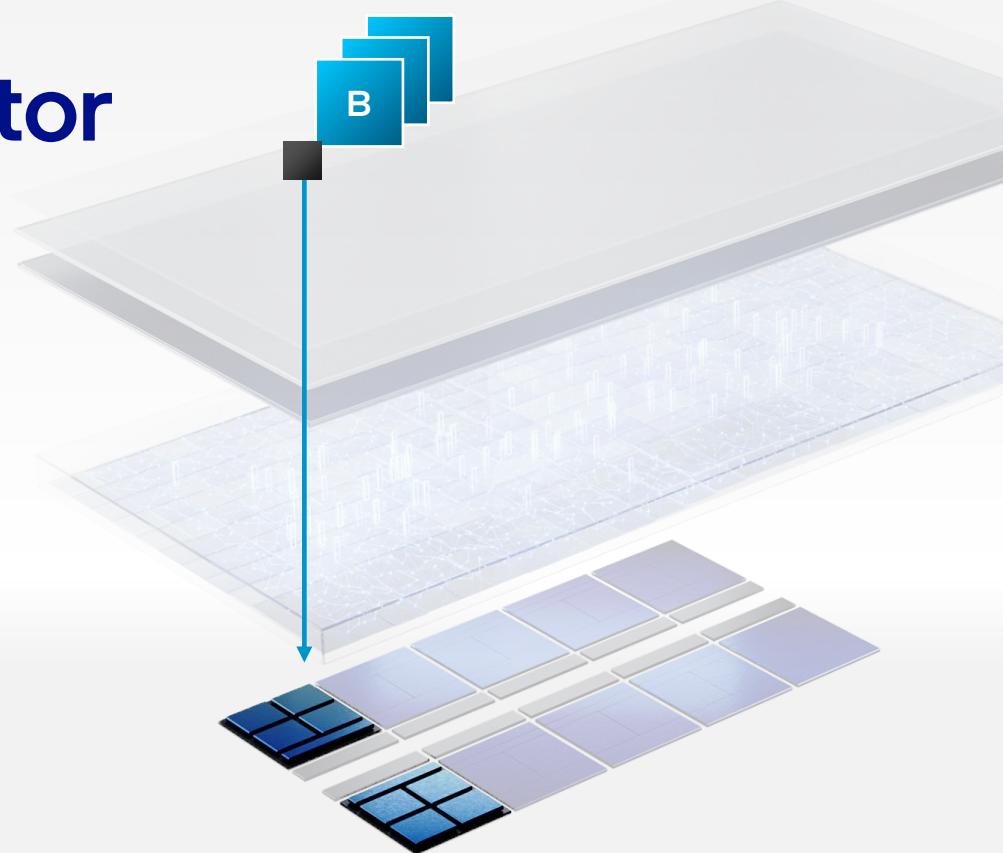
Introducing

Intel Thread Director

Scheduling Examples

1 Priority tasks scheduled on P-cores

2 Background tasks scheduled on E-cores



Introducing

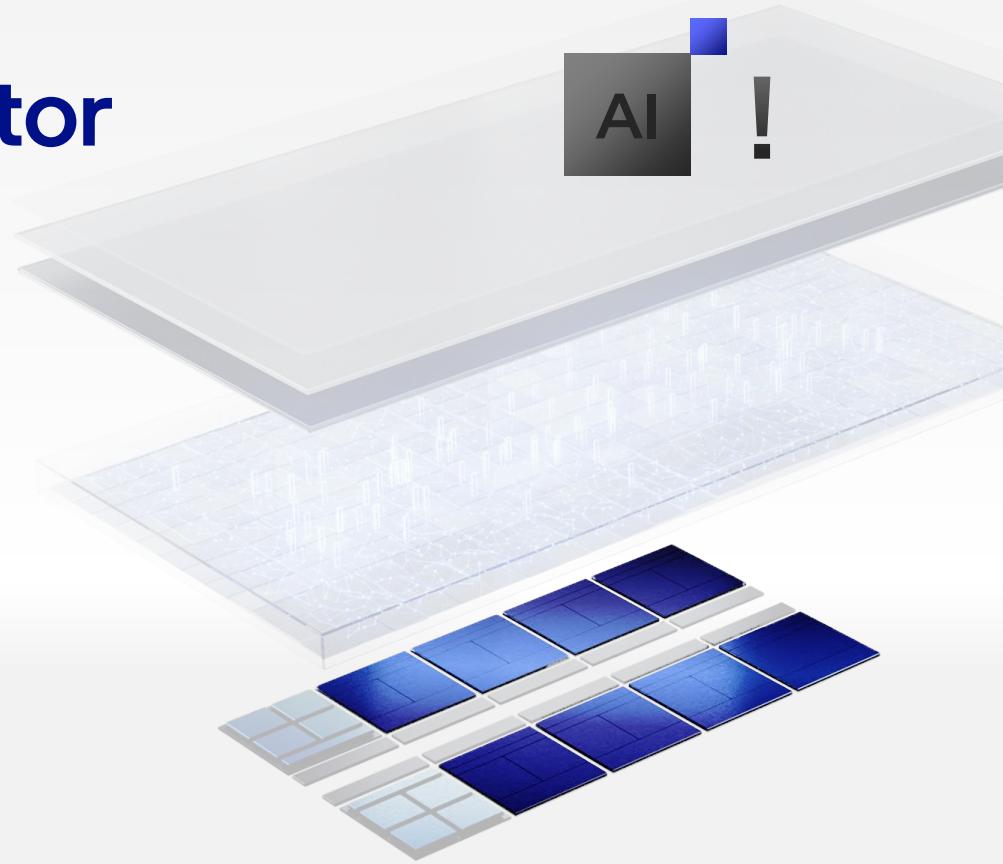
Intel Thread Director

Scheduling Examples

1 Priority tasks scheduled on P-cores

2 Background tasks scheduled on E-cores

3 New AI thread ready



Introducing

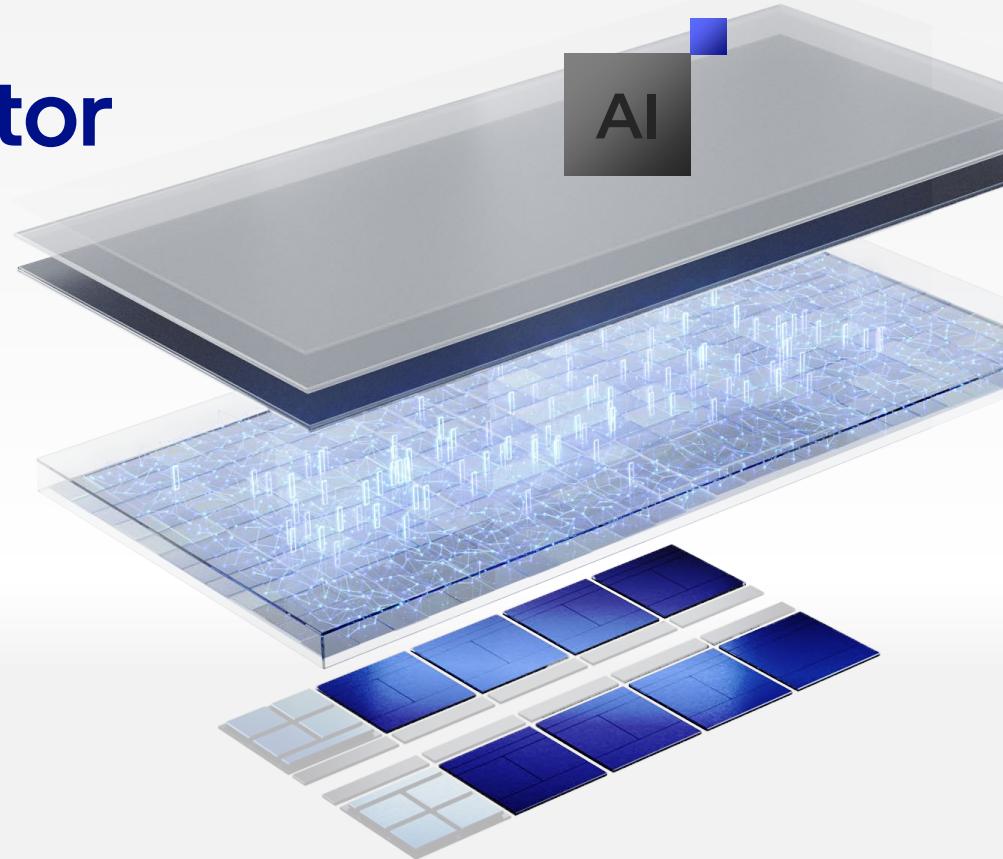
Intel Thread Director

Scheduling Examples

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2 Background tasks scheduled on E-cores

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Introducing

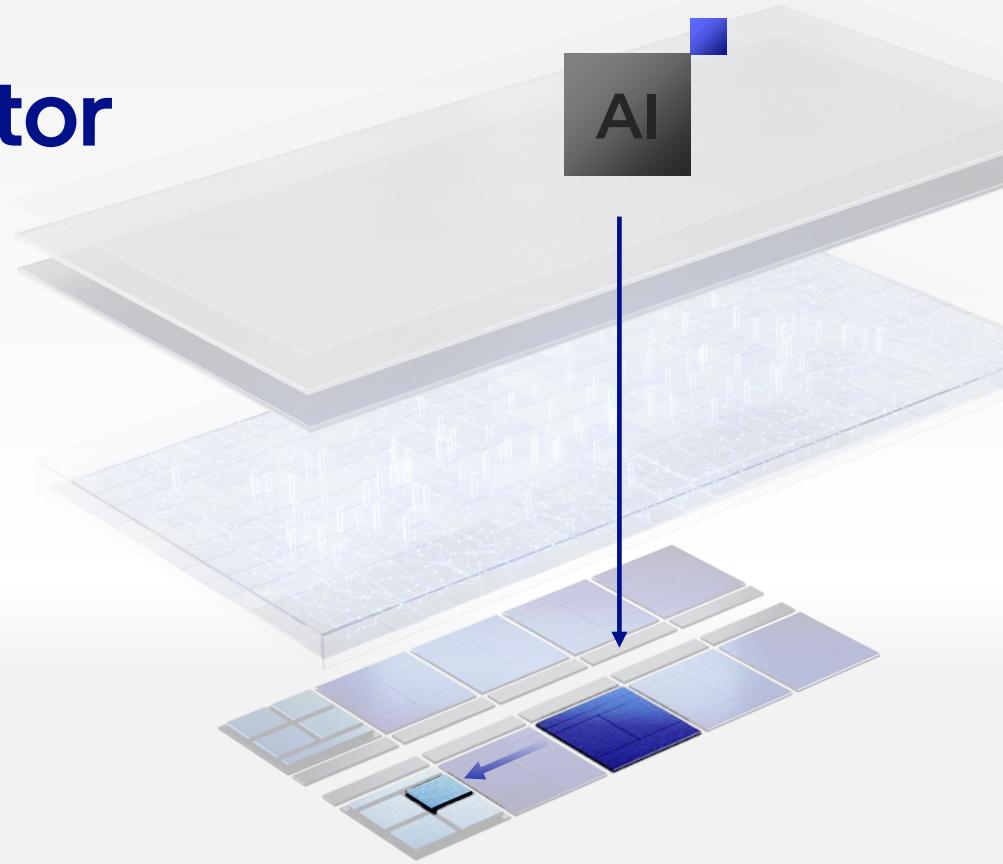
Intel Thread Director

Scheduling Examples

1 Priority tasks scheduled on P-cores

2 Background tasks scheduled on E-cores

3 AI thread prioritized on P-core



Introducing

Intel Thread Director

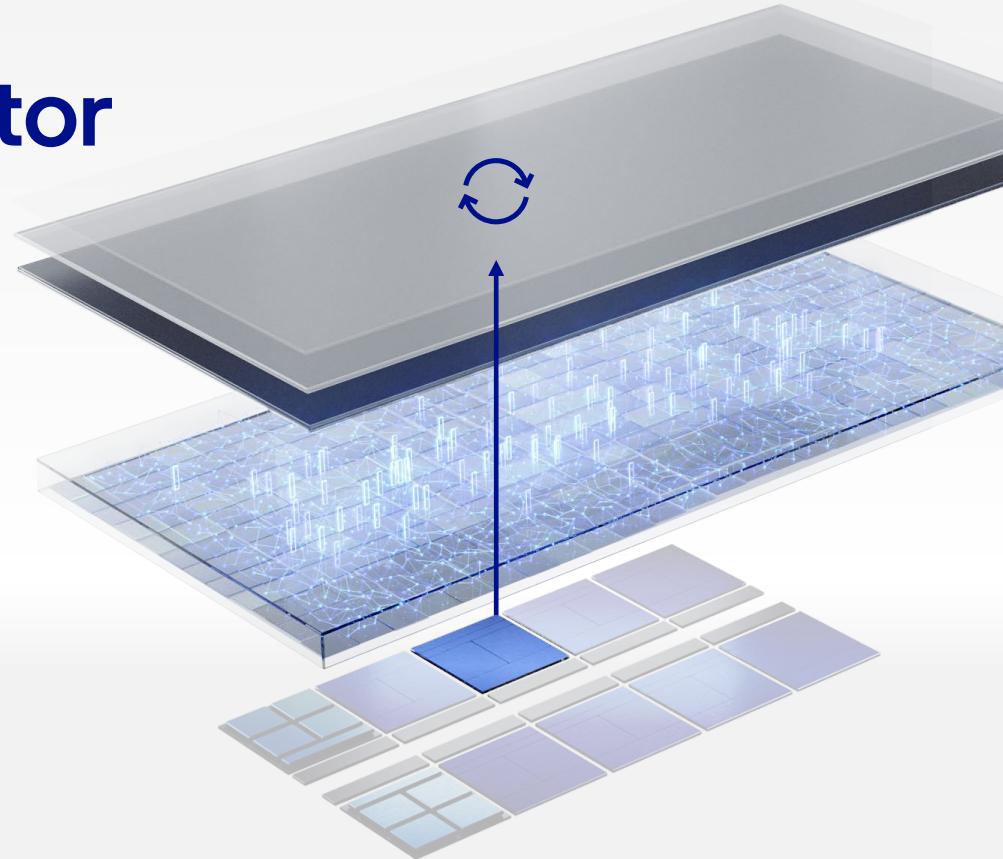
Scheduling Examples

1 Priority tasks scheduled on P-cores

2 Background tasks scheduled on E-cores

3 AI thread prioritized on P-core

4 Spin loop wait moved from P to E-core



Introducing

Intel Thread Director

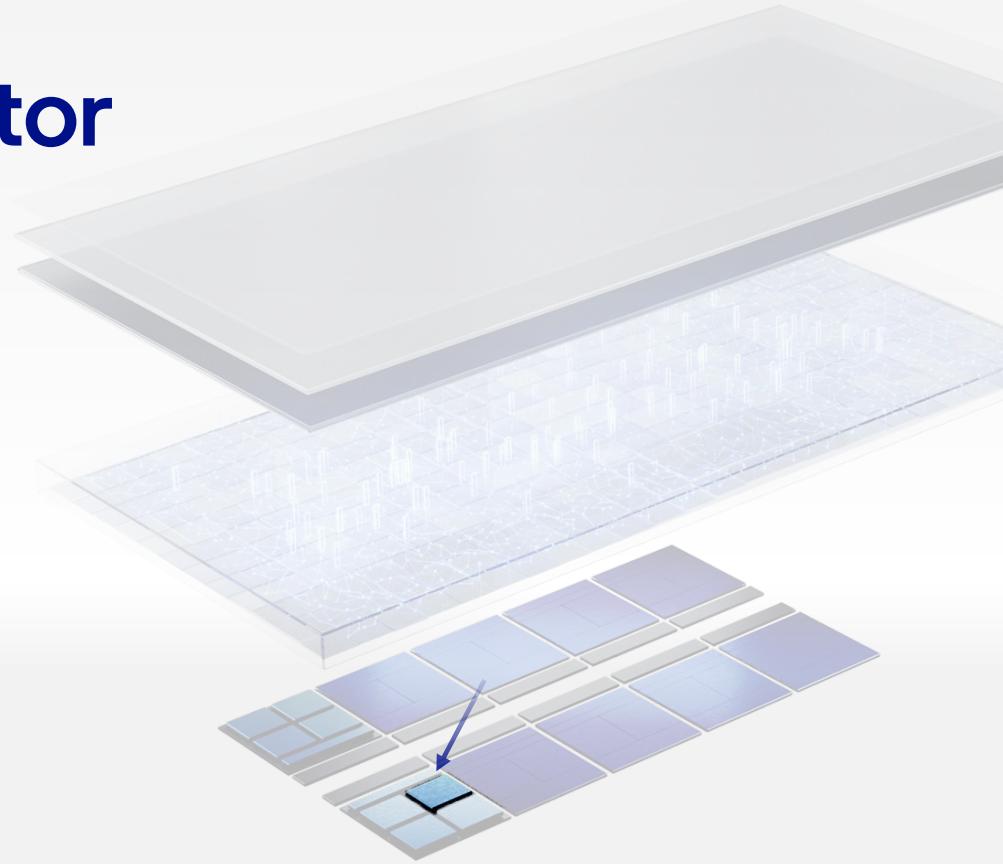
Scheduling Examples

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2 Background tasks scheduled on E-cores

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Introducing

Intel Thread Director

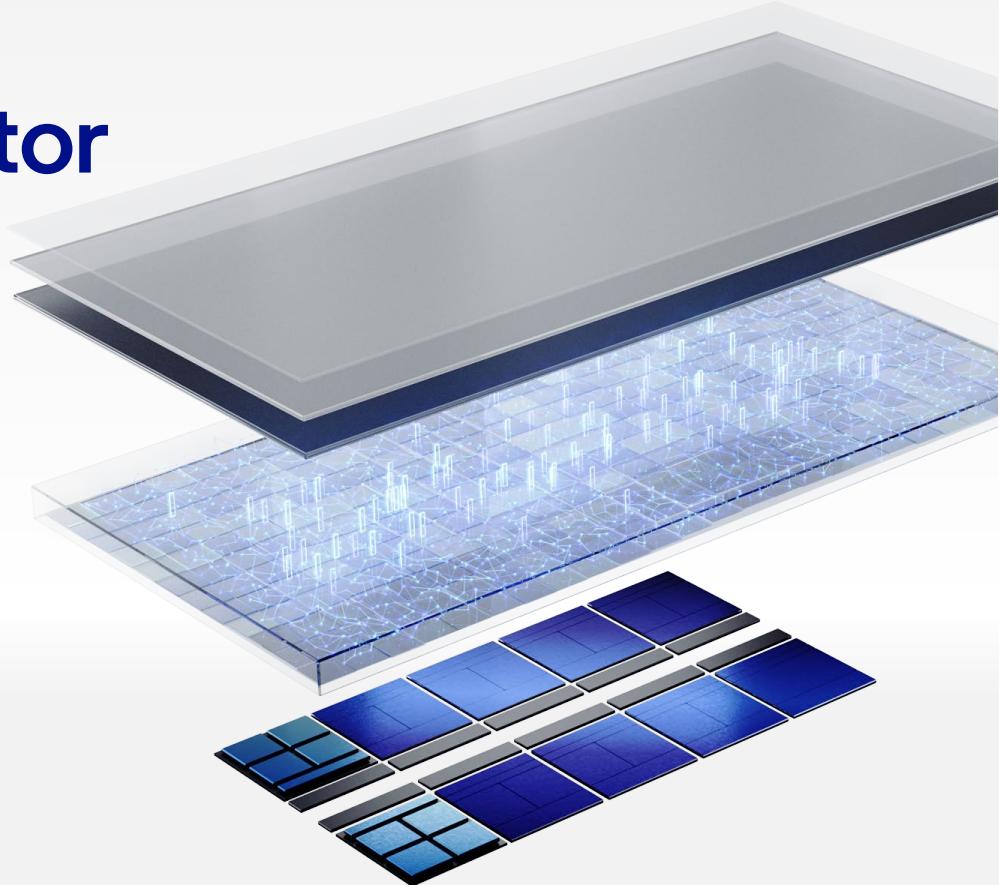
Scheduling Examples

1 Priority tasks scheduled on P-cores

2 Background tasks scheduled on E-cores

3 AI thread prioritized on P-core

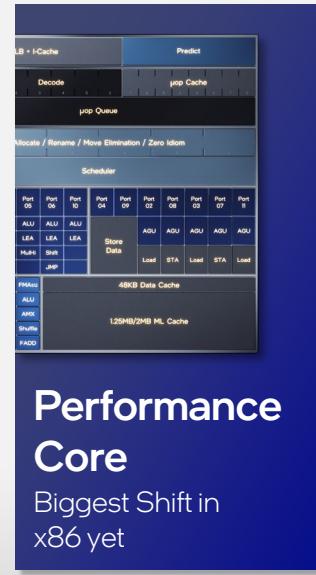
4 Spin loop wait moved from P to E-core



Architecture Day

2021

New Architectural Foundations



X^e - core

Sapphire
Rapids

X^e HPC &
Ponte
Vecchio

AMX
Advanced Matrix Extension - Engine

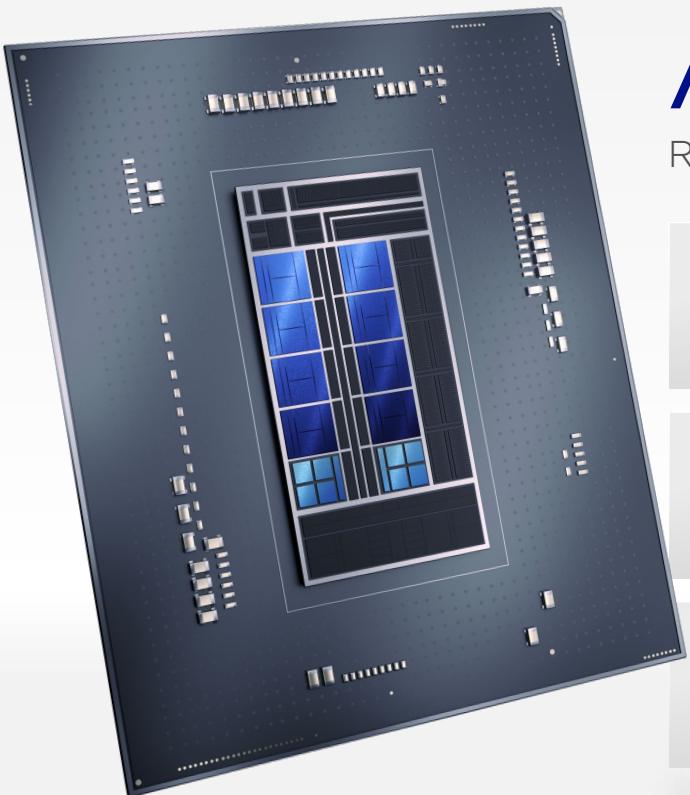
Alder
Lake

X^e HPG

Mount Evans

Alder Lake

Arik Gihon



Introducing

Alder Lake

Reinventing Multi Core Architecture

Single, Scalable SoC Architecture

All Client Segments – 9W to 125W – built on Intel 7 process

All-New Core Design

Performance Hybrid with Intel Thread Director

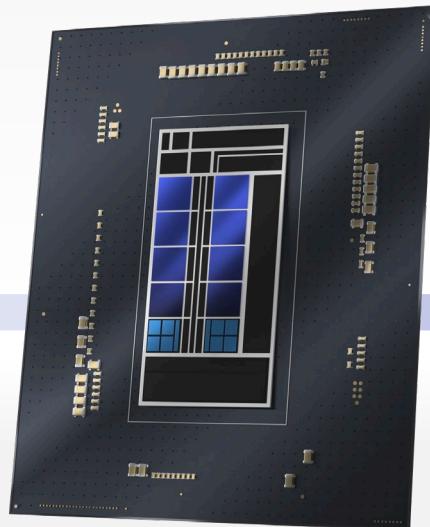
Industry-Leading Memory & I/O

DDR5, PCIe Gen5, Thunderbolt™ 4, Wi-Fi 6E

Scalable Client Architecture

Desktop

LGA 1700
Socket



Mobile

BGA Type3
50 x 25 x 1.3 mm



Ultra Mobile

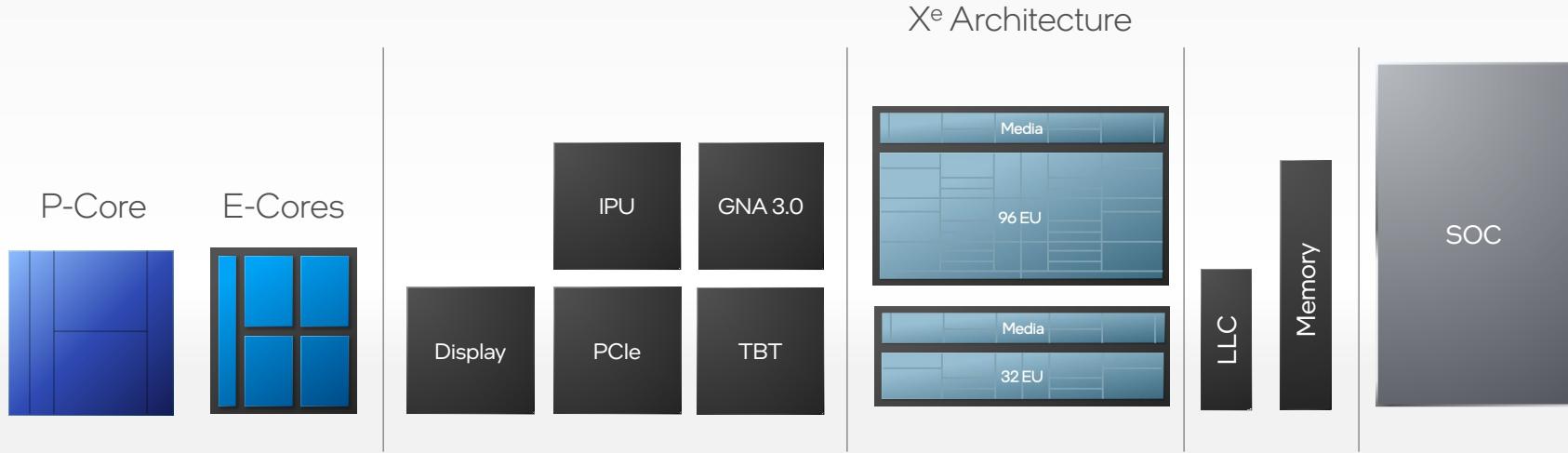
BGA Type4 HDI
28.5 x 19 x 1.1 mm



Visit www.intel.com/ArchDay21claims for details

Alder Lake

Building Blocks



Desktop

Mobile

Ultra Mobile



Building Blocks



P-Core



E-Cores



Display



PCIe



TBT



GNA 3.0



IPU



LLC

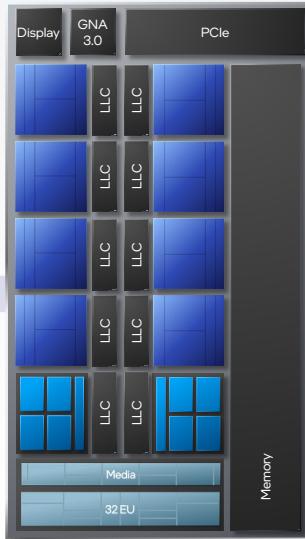


Memory



SOC

Desktop



Mobile

Ultra Mobile



Building Blocks



P-Core



E-Cores



Display



PCIe



TBT



GNA 3.0



IPU



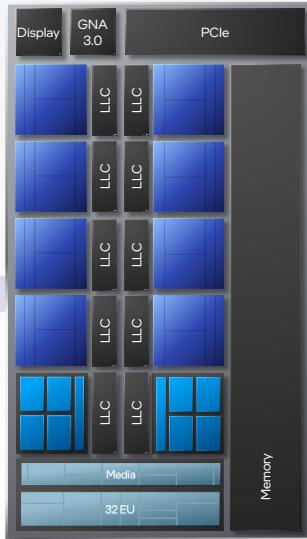
LLC



Memory

SOC

Desktop



Mobile



Ultra Mobile



Building Blocks



P-Core



E-Cores



Display



PCIe



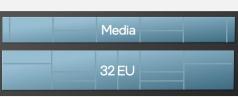
TBT



GNA 3.0



IPU



Media
32 EU



LLC

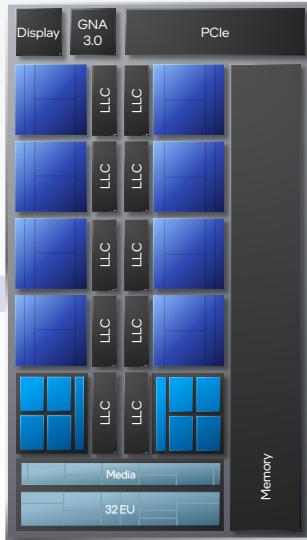


Memory



SOC

Desktop



Mobile



Ultra Mobile



Building Blocks



P-Core



E-Cores



Display



PCIe



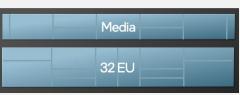
TBT



GNA 3.0



IPU



Media

32 EU



Media

96 EU



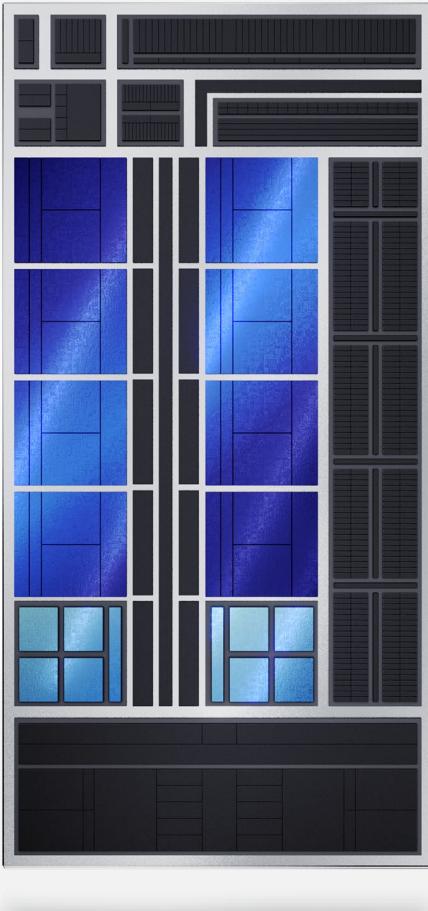
LLC



Memory



SOC



Alder Lake

Core/Cache

Up To

16 Cores

8 Performance
8 Efficient

Up To

24 Threads

2T per P-core
1T per E-core

Up to

30 MB

Non-inclusive
LL Cache

Alder Lake

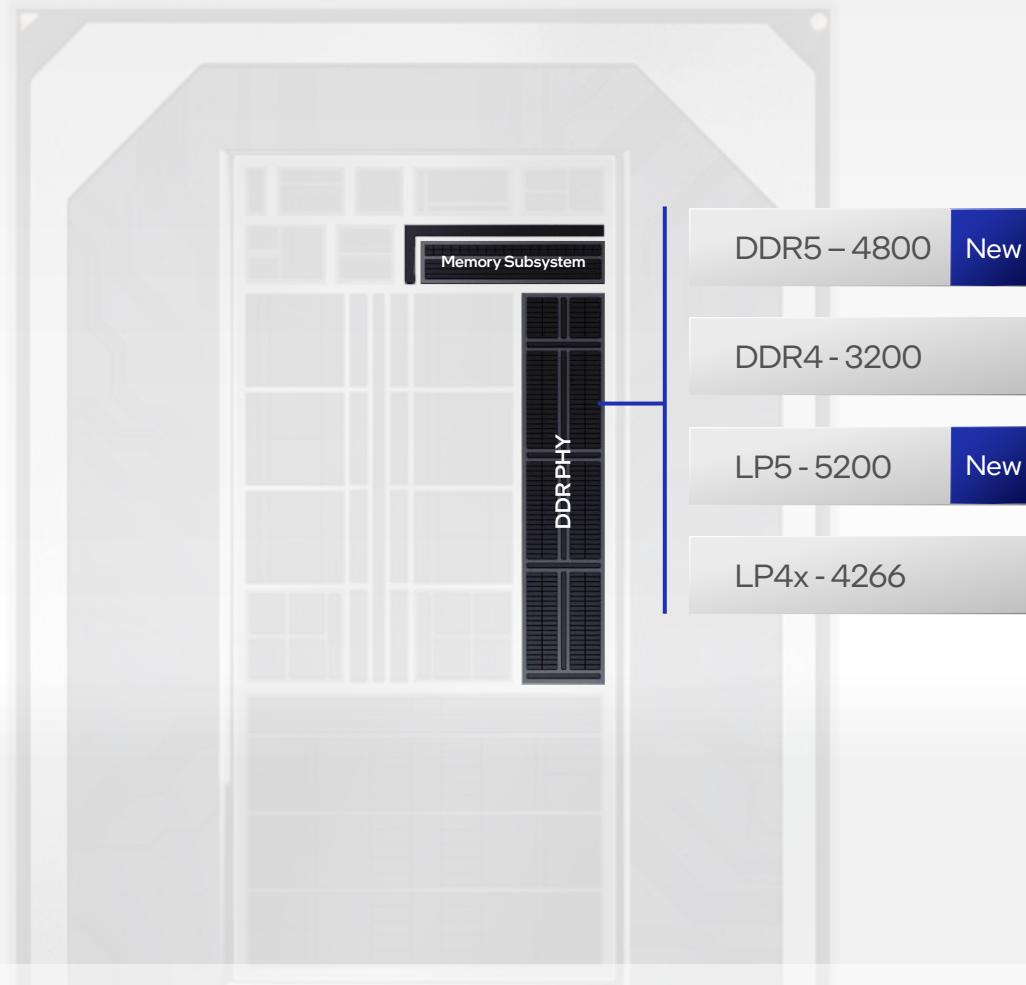
Memory

Leading the industry
transition to DDR5

Support for all four major memory
technologies

Dynamic voltage-frequency scaling

Enhanced overclocking support

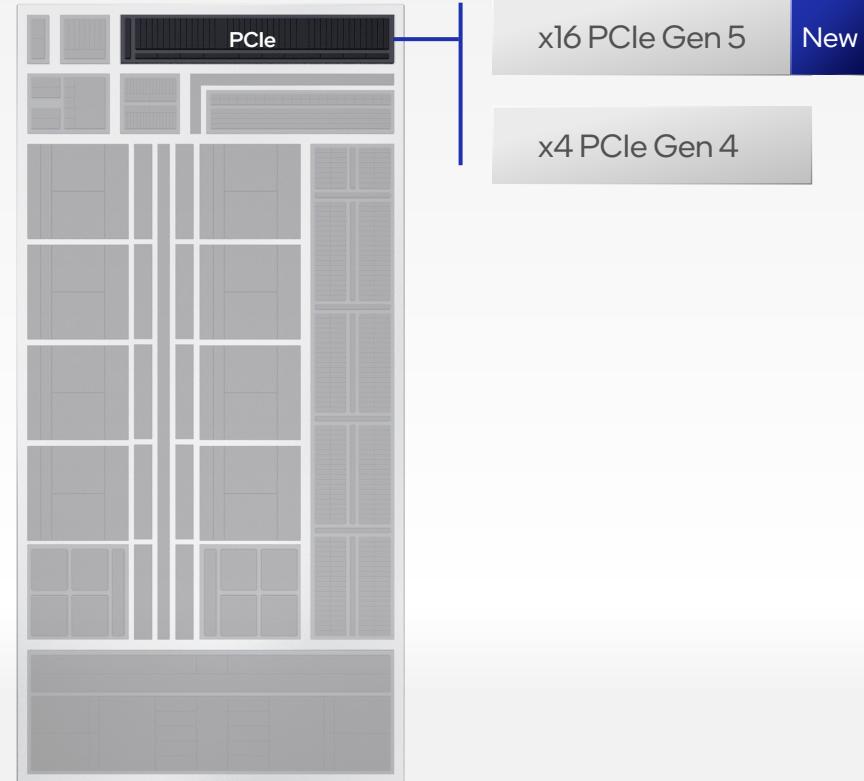
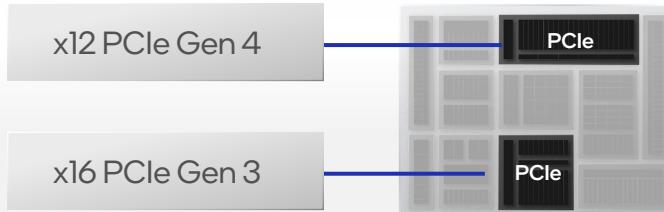


Alder Lake

PCIe

Leading the industry transition to
PCIe Gen5

Up to 2X bandwidth vs. Gen4
Up to 64GB/s with x16 lanes



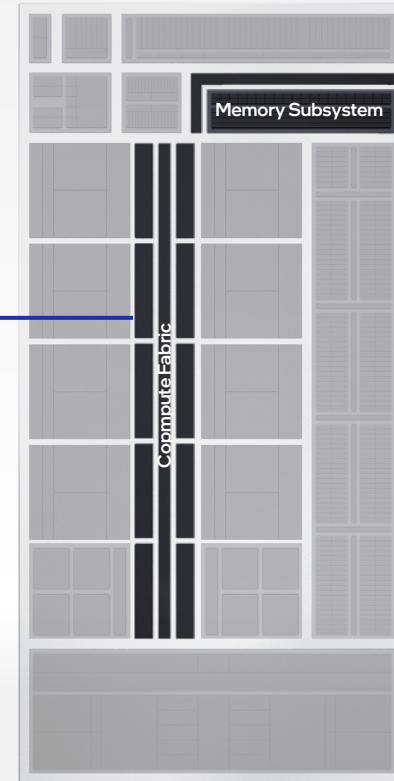
Visit www.intel.com/ArchDay21claims for details

Alder Lake Interconnect

Compute Fabric

Up to
1000 GB/s

Dynamic Latency
Optimization



I/O Fabric

Up to

64 GB/s

Real-time, demand-
based BW control

Memory Fabric

Up To

204 GB/s

Dynamic Bus Width
& Frequency

Visit www.intel.com/ArchDay21claims for details



Beginning Fall 2021

Alder Lake

Reinventing Multi Core Architecture

Single, Scalable SoC Architecture

All Client Segments – 9W to 125W – built on Intel 7 process

All-New Core Design

Performance Hybrid with Intel Thread Director

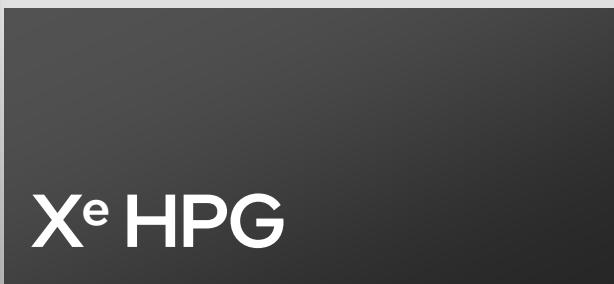
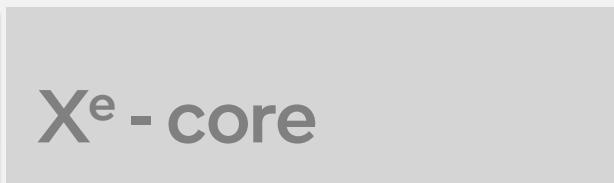
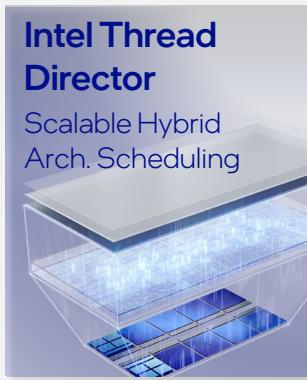
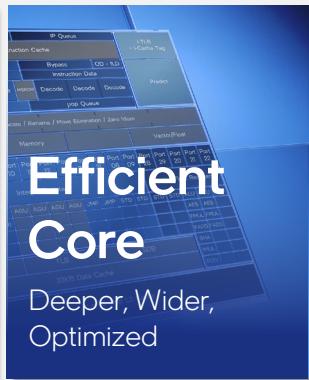
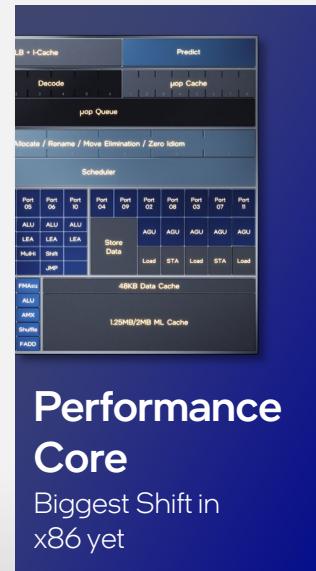
Industry-Leading Memory & I/O

DDR5, PCIe Gen5, Thunderbolt™ 4, Wi-Fi 6E

Architecture Day

2021

New Architectural Foundations

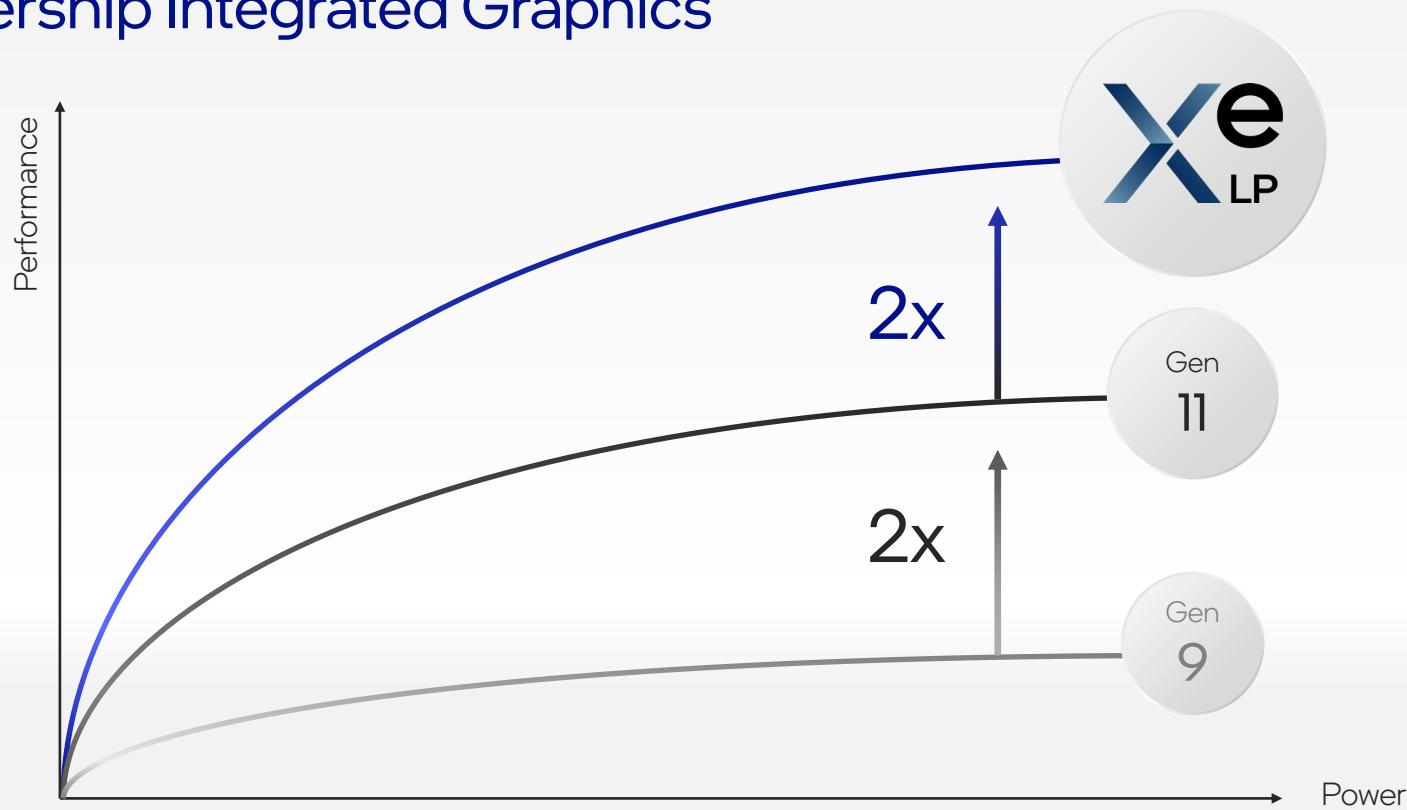


Mount Evans



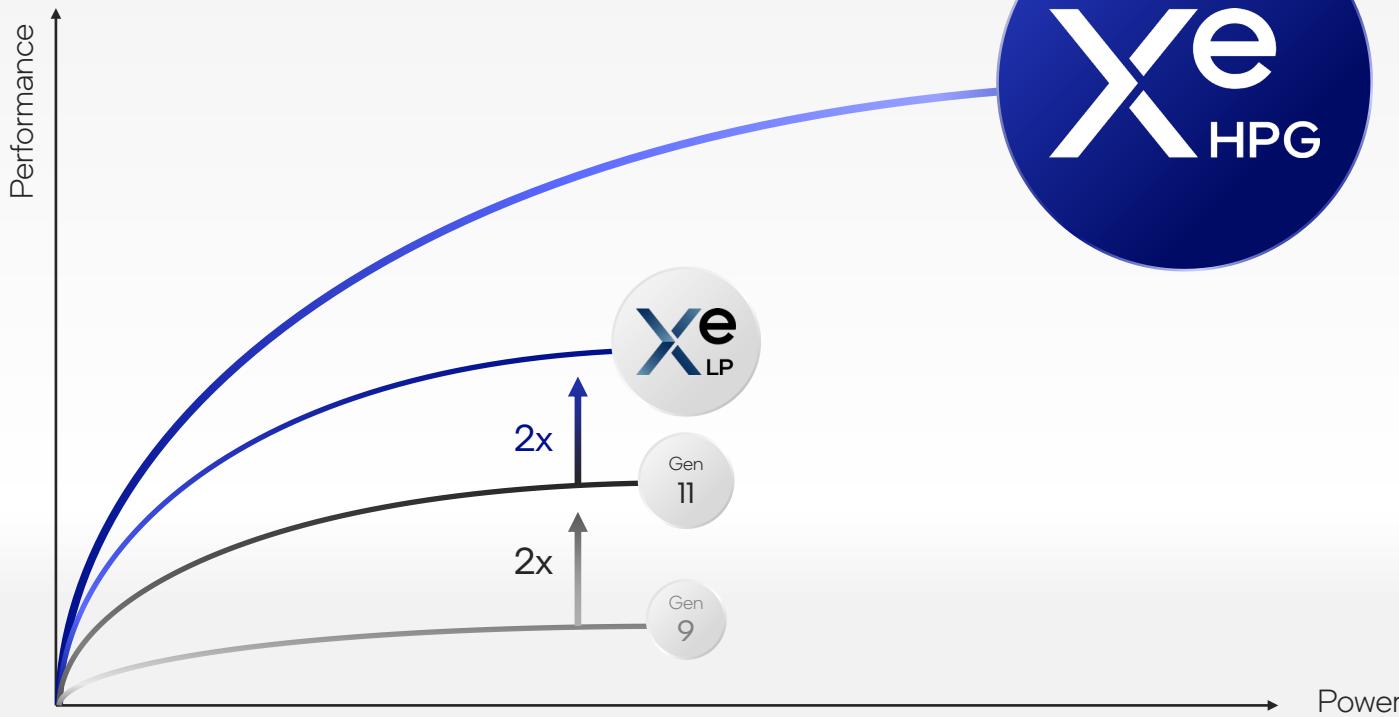
Xe HPG architecture

Leadership Integrated Graphics



For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Unconstrained Discrete Graphics



For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Vivid PC Graphics Market

1.5B
PC Gamers

Over the last 4 years, the amount of concurrent users has **doubled** on Steam.

8.8B
Hours of
Live Streams
Watched

Twitch.tv viewership has **doubled** in one year

13M+
Game
Developers

Over **10,000 games** released on Steam in 2020

1. Source: <https://www.pcgamesn.com/pc-gaming-study>

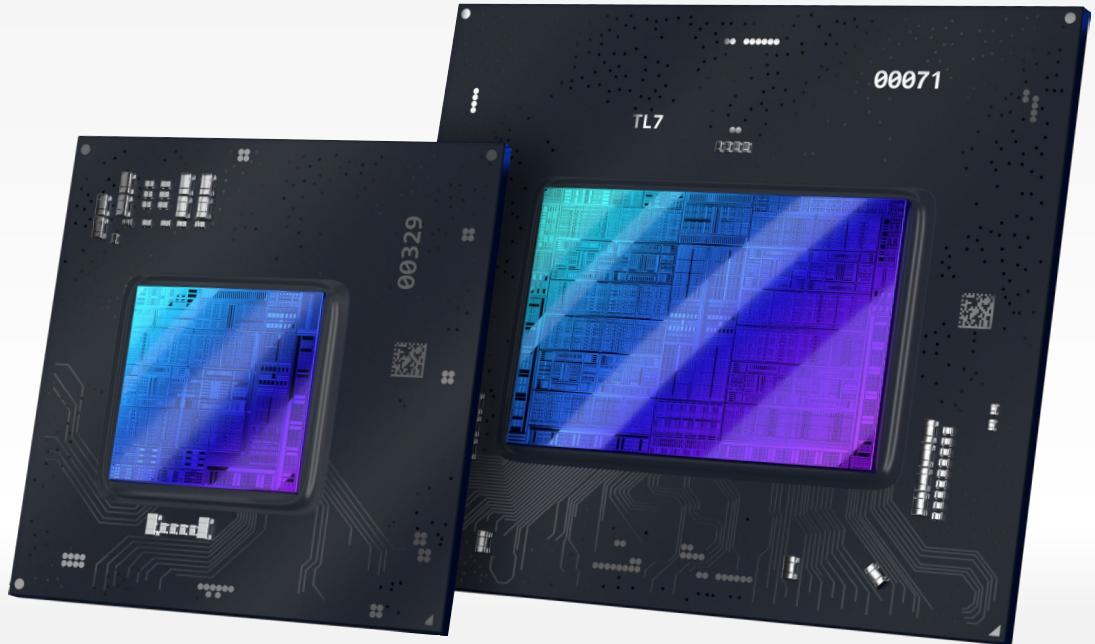
2. Source: <https://blog.streamlabs.com/streamlabs-stream-hatchet-q1-2021-live-streaming-industry-report-eaba2143f492>

3. Source: Part 1 : Game Developer Population Forecast 2020, April 2020, SlashData

intel® ARC™

Powered by

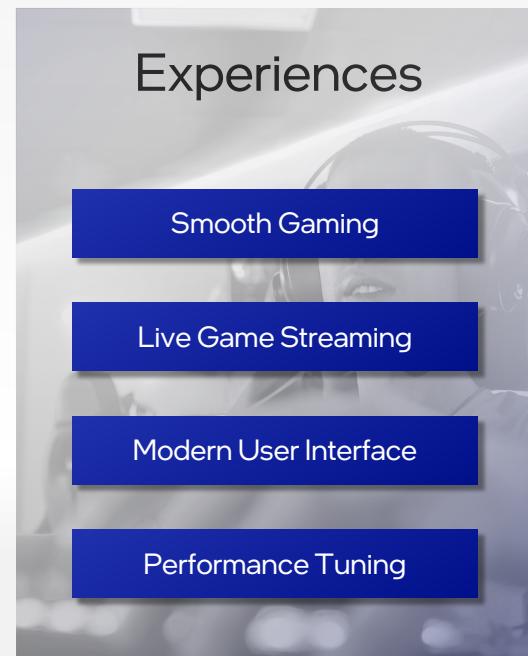
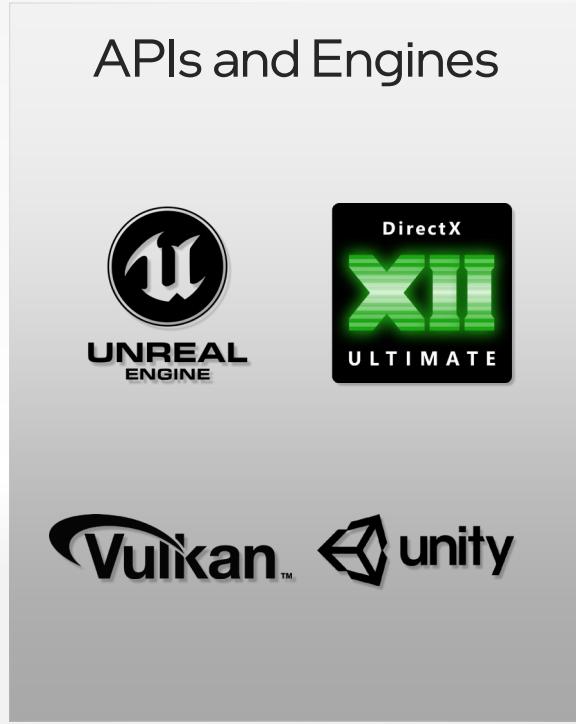
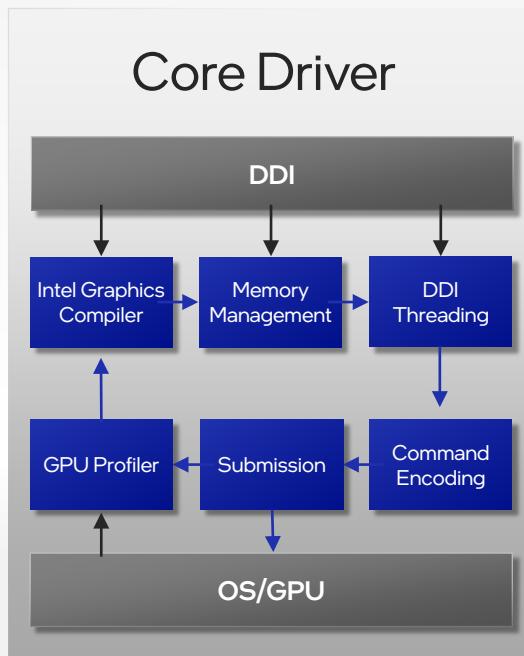
Alchemist Soc



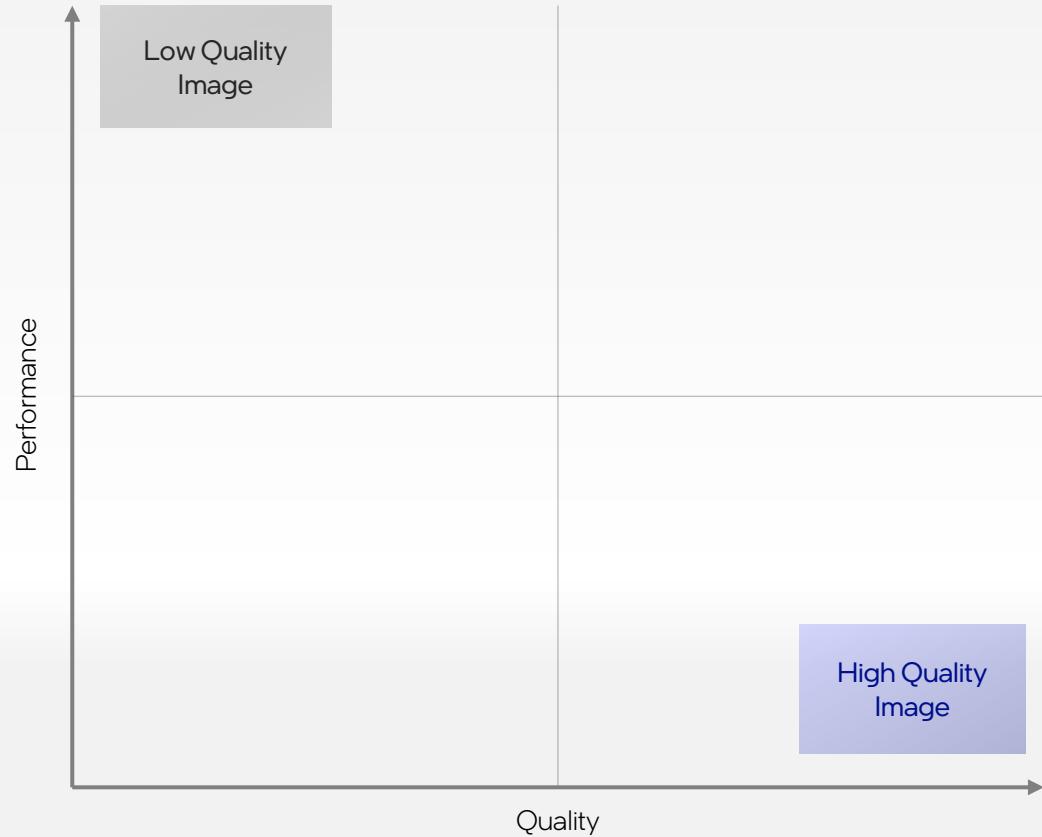
X^e HPG Sneak Peek

Lisa Pearce

Software First



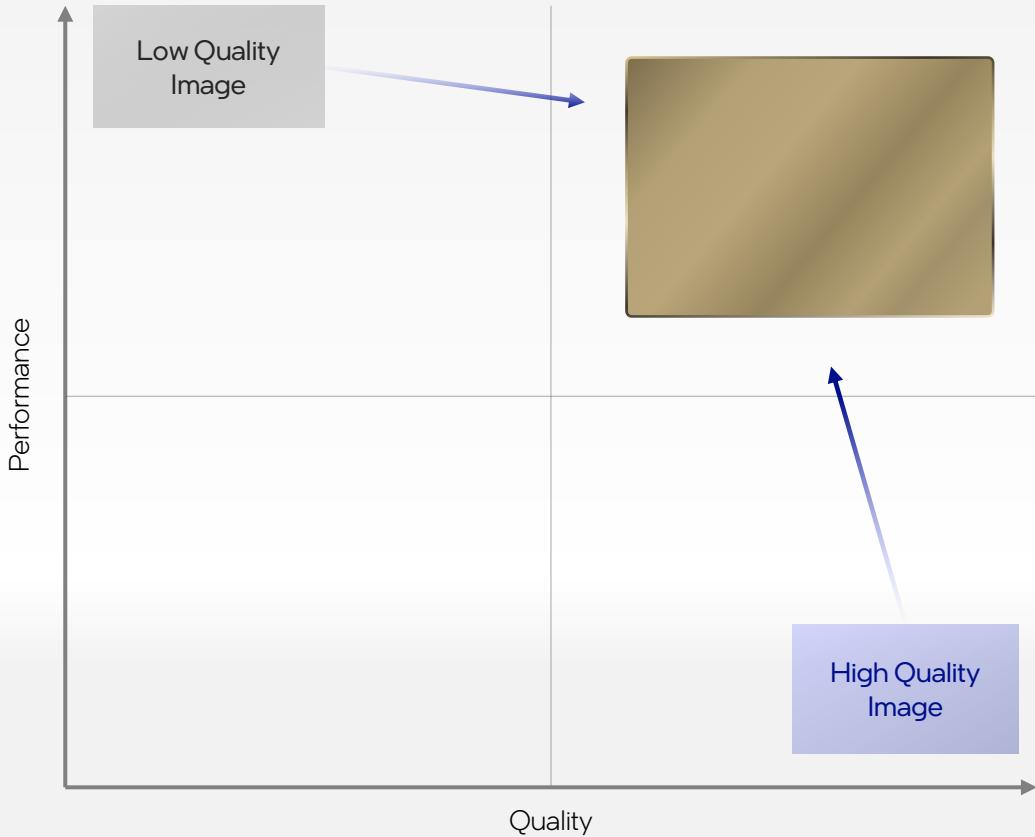
Render Quality Trade-off



Render Quality Trade-off



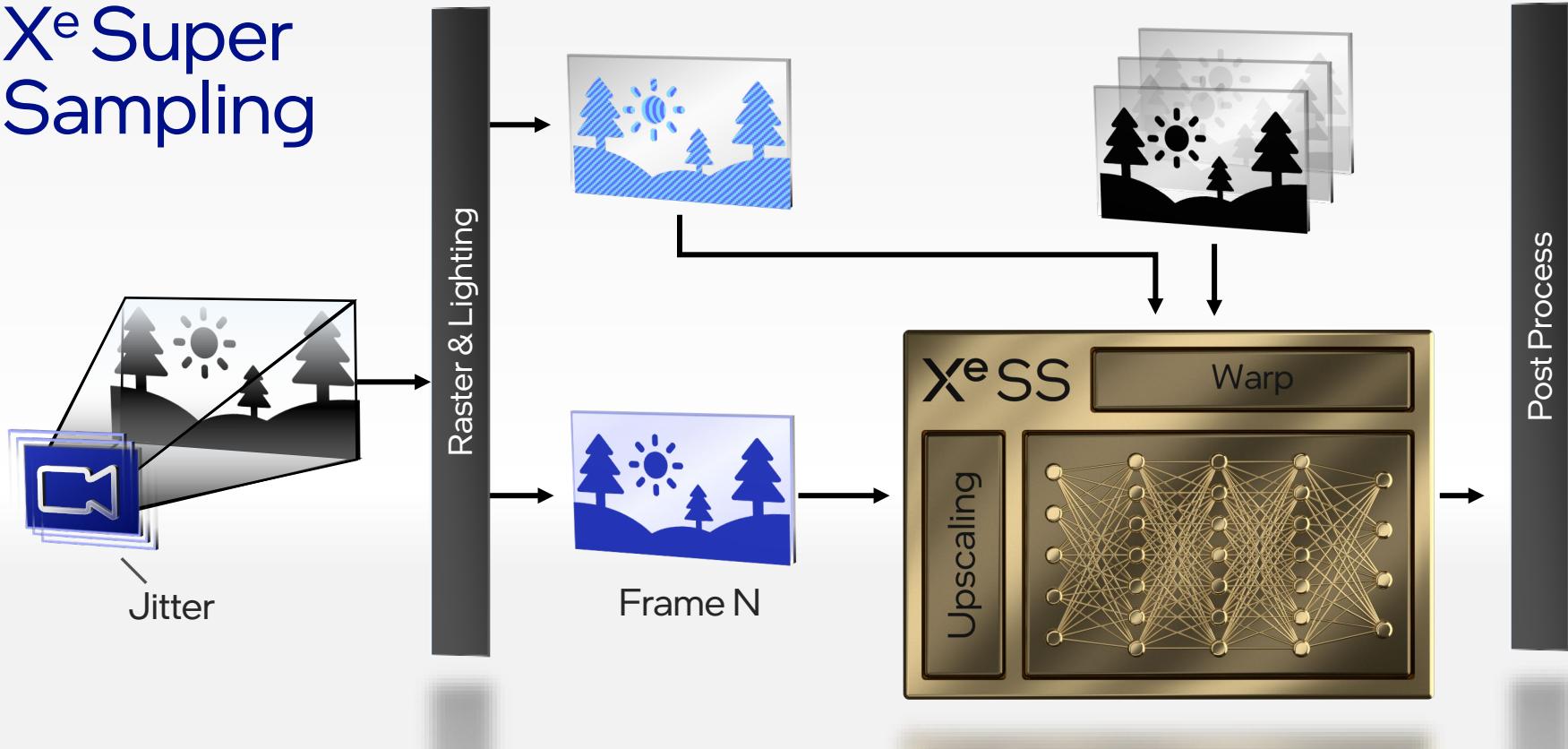
Render Quality Trade-off



Render Quality Trade-off

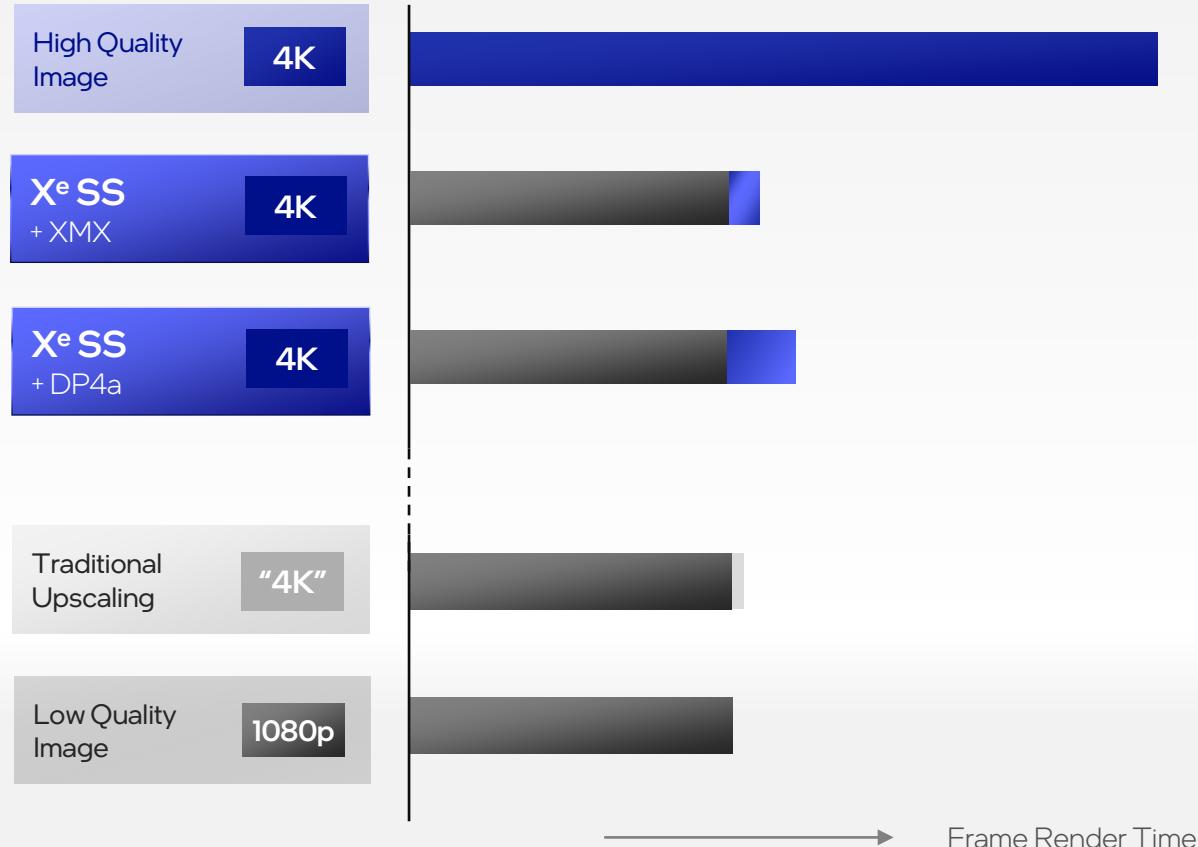


X^e Super Sampling



X^eSS

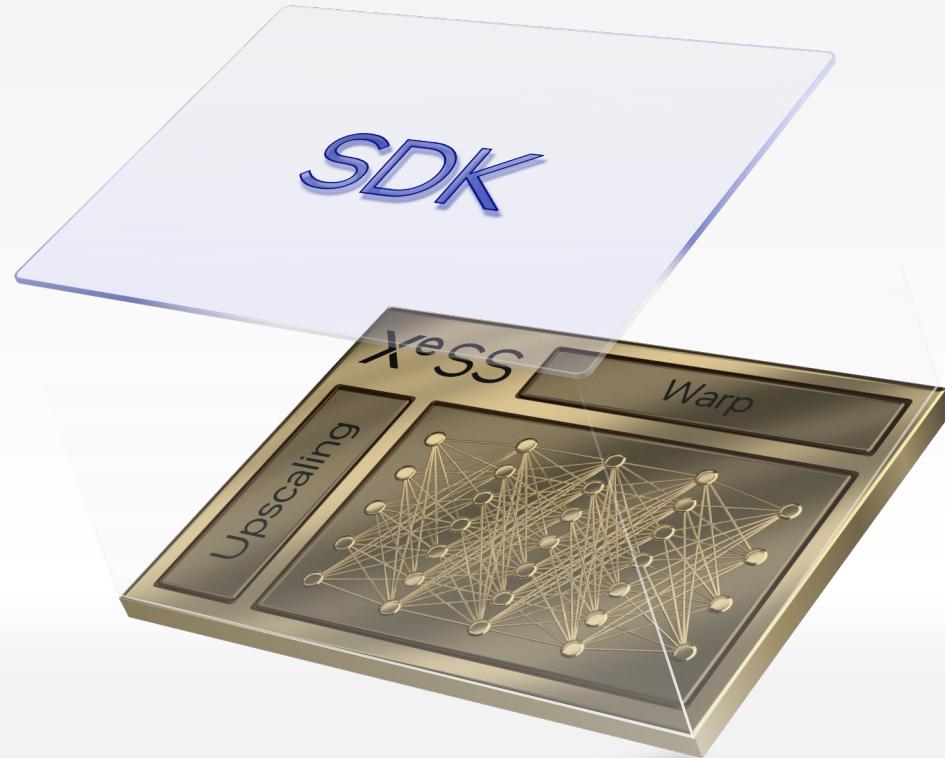
Hits the Sweet Spot



Graph is for conceptual illustration purposes only. Subject to revision with further testing.

Xe SS SDK

Available this month



X^e HPG Sneak Peek

David Blythe





Compute Efficiency

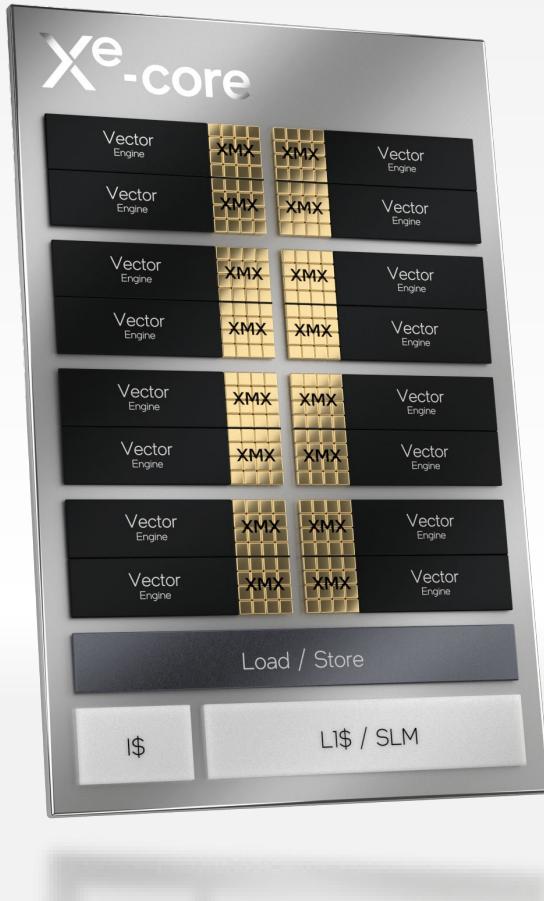


Scalability

Graphics Efficiency



High Performance
Gaming Optimized



Xe-core

Compute Building Block of Xe HPG-based GPUs

16
Vector Engines

256 bit
per engine

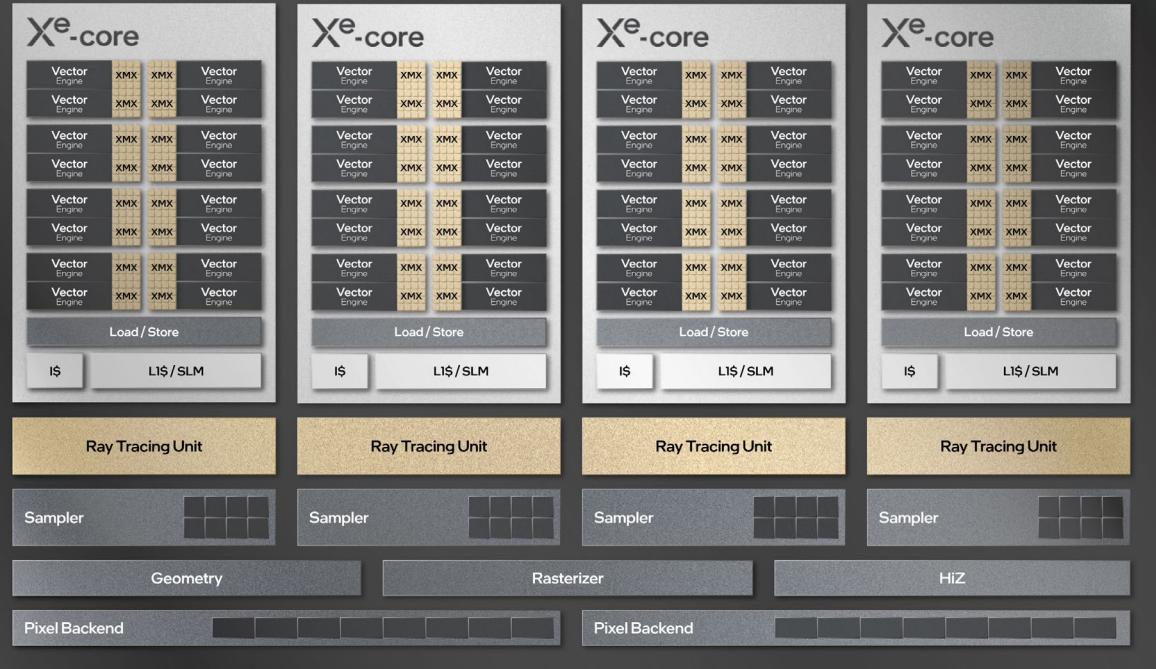
16
Matrix Engines

1024 bit
per engine



Render Slice

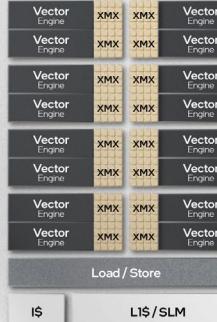
Render slice



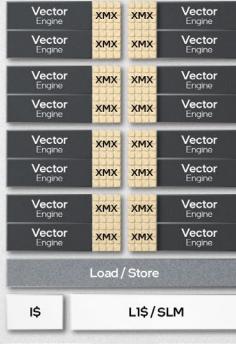
4 X^e-cores with XMX

Render slice

X^e-core



X^e-core



X^e-core



X^e-core



Ray Tracing Unit

Ray Tracing Unit

Ray Tracing Unit

Ray Tracing Unit

Sampler



Sampler



Sampler



Sampler



Geometry

Rasterizer

HIZ

Pixel Backend

Pixel Backend

Fixed Function optimized for DX12 Ultimate Gaming

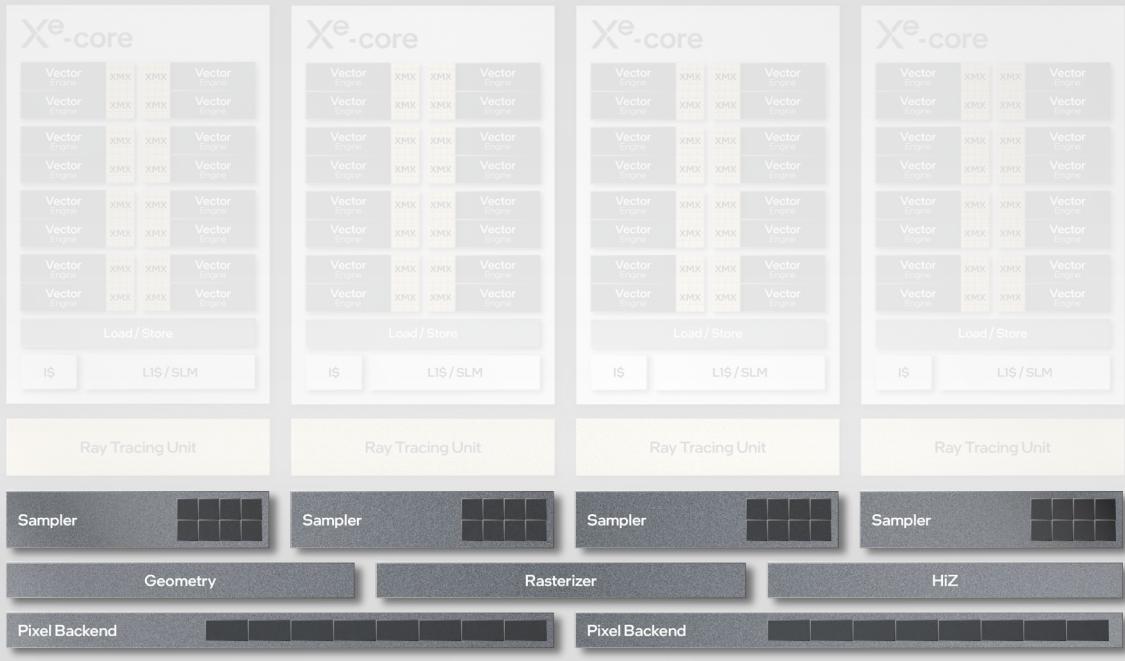
Geometry Pipeline

Rasterization Pipeline

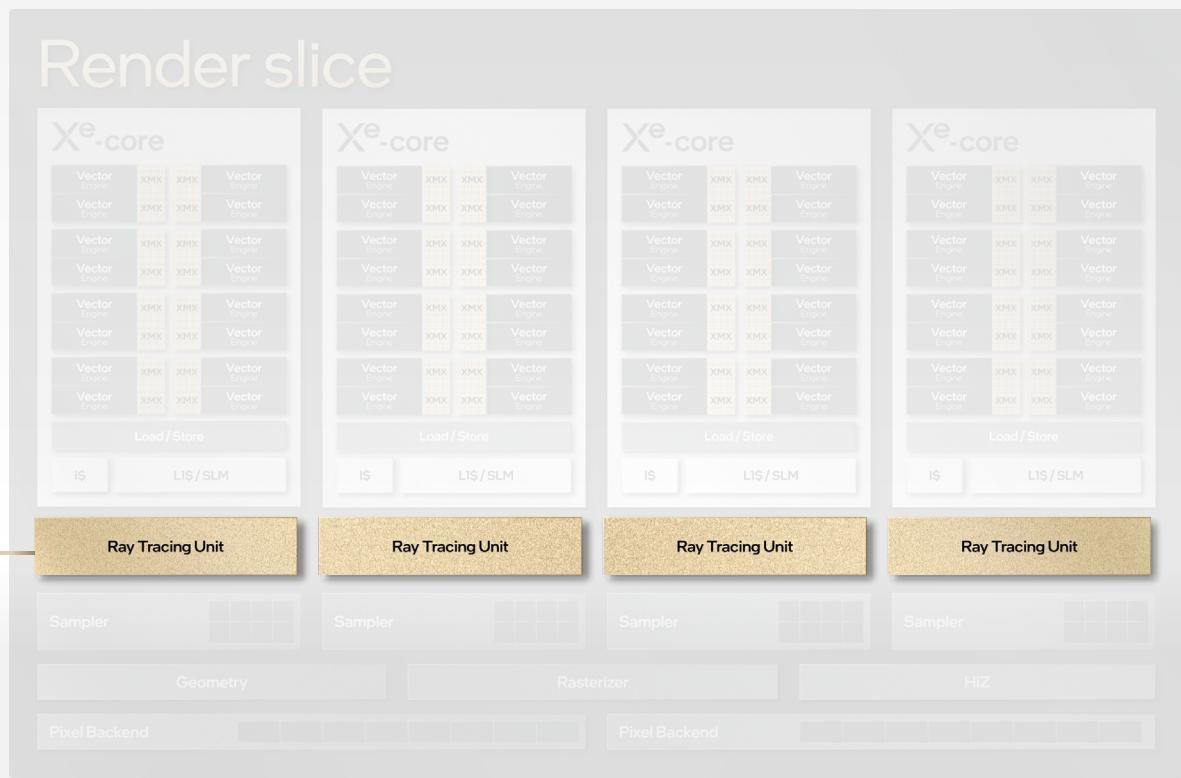
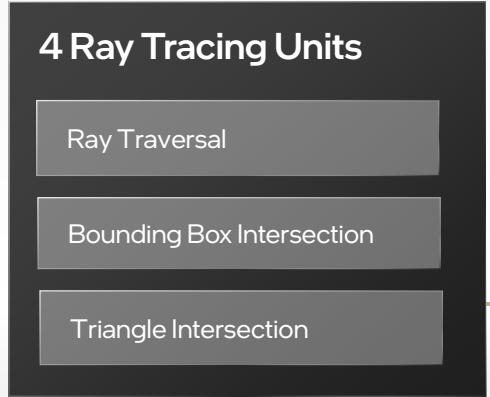
Samplers

Pixel Backends

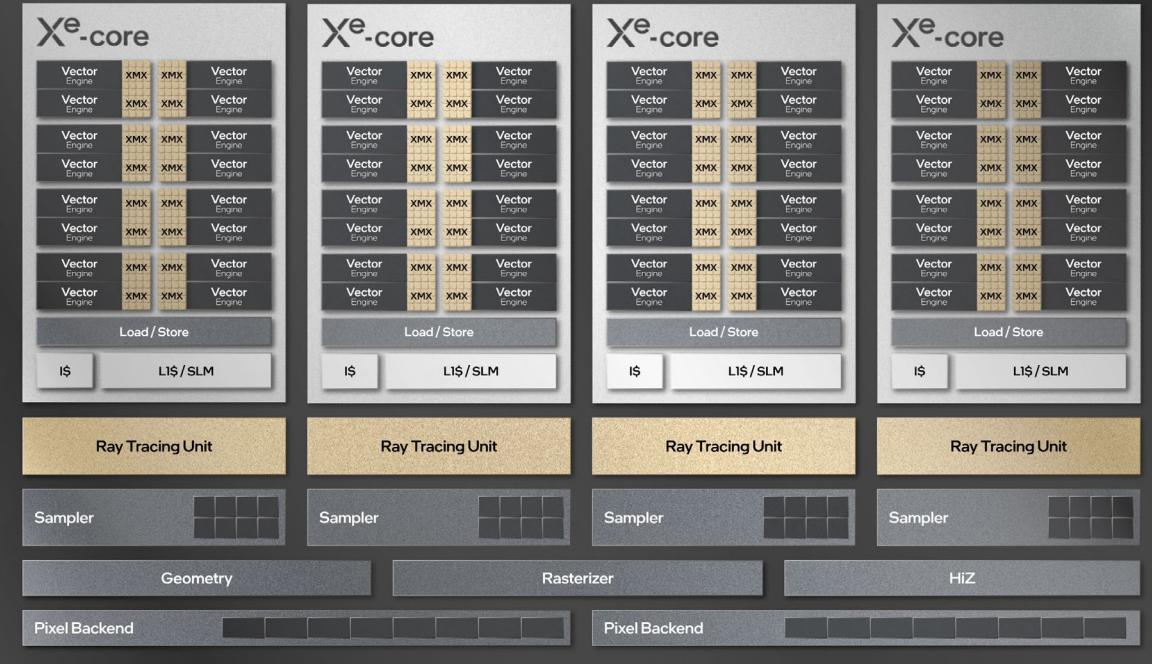
Render slice



Render slice

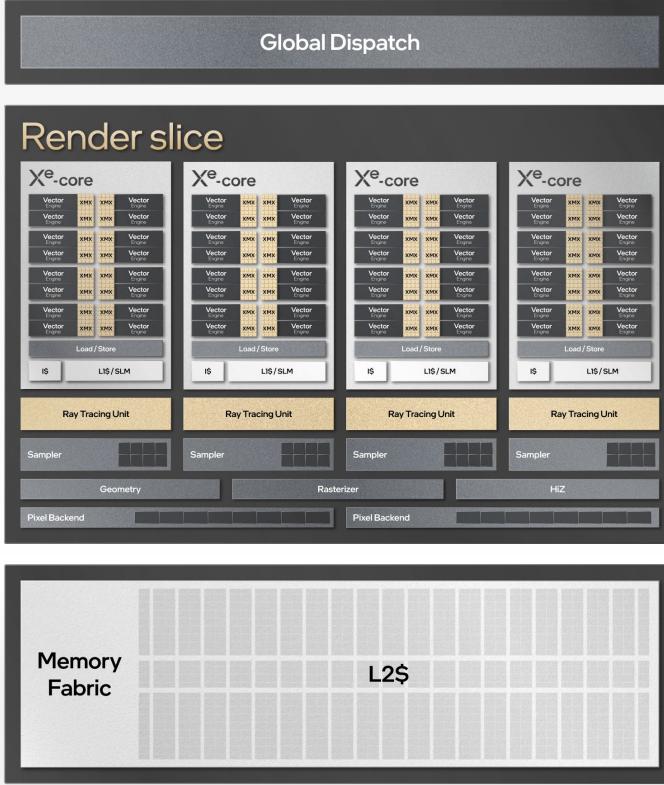


Render slice



Xe HPG

Scaling the Graphics Engine



Xe HPG

Scaling the Graphics Engine





Leadership IP Performance/Watt

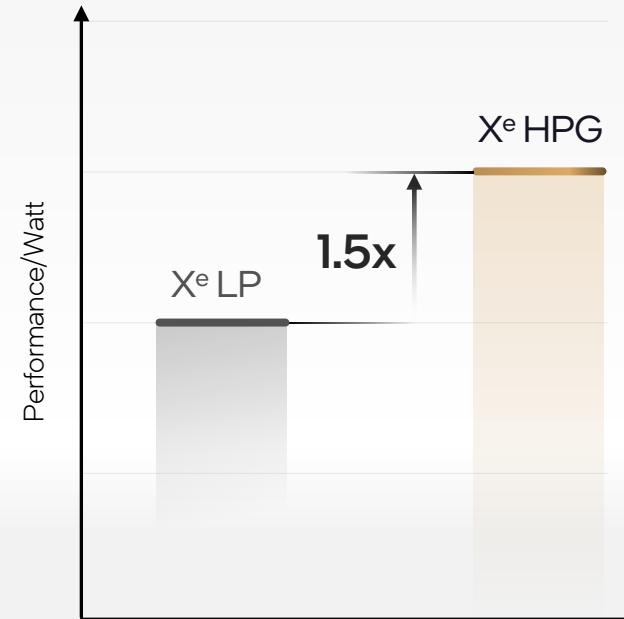
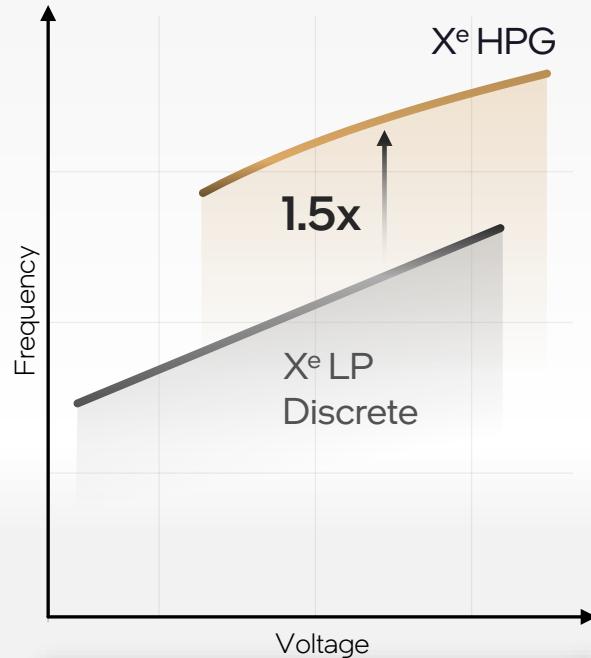
Architecture

Logic Design

Circuit Design

Process Technology

Software



For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

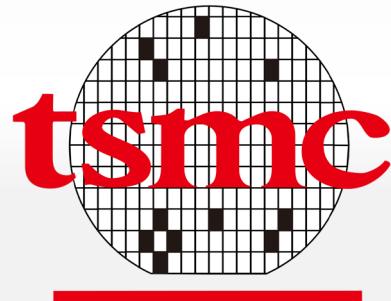


“In the world of graphics, there is an insatiable demand for better performance and more realism. TSMC is excited that Intel has chosen our N6 technology for their Alchemist family of discrete graphics solutions”.

“There are many ingredients to a successful graphics product including the semiconductor technology. With N6, TSMC provides an optimal balance of performance, density and power efficiency that are ideal for modern GPUs. We are pleased with the collaboration with Intel on the Alchemist family of discrete GPUs”.

Dr. Kevin Zhang,

Senior Vice President of Business Development at TSMC



Multi-Year **Roadmap**

Performance ↑

Alchemist

X^e HPG



Q1
2022

Battlemage

X^e2 HPG



Celestial

X^e3 HPG



Druid

X^e Next Architecture

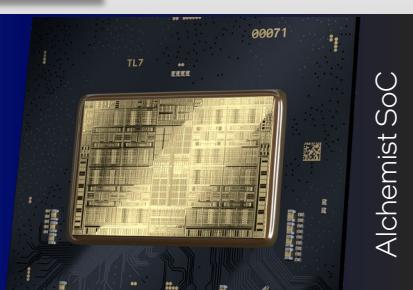
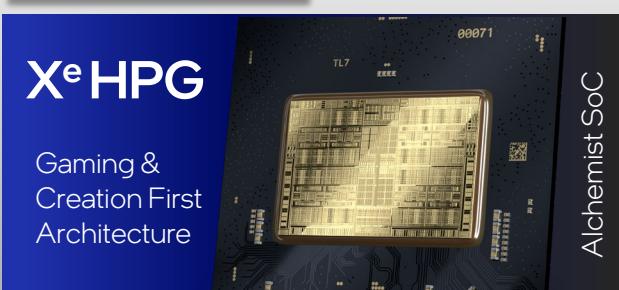
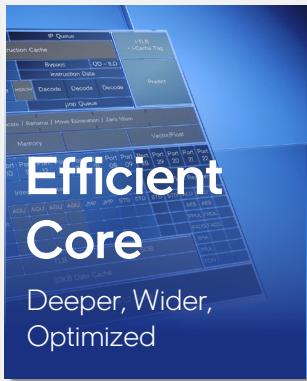
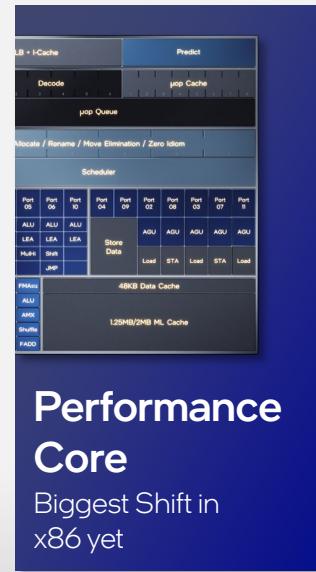


intel®
ARC™

Architecture Day

2021

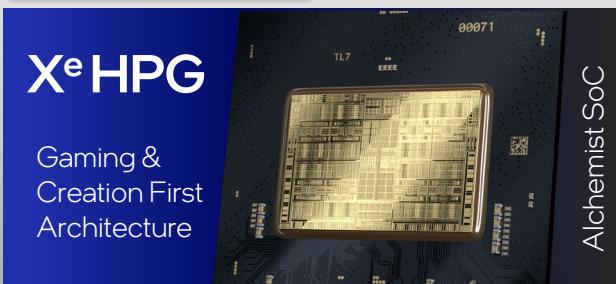
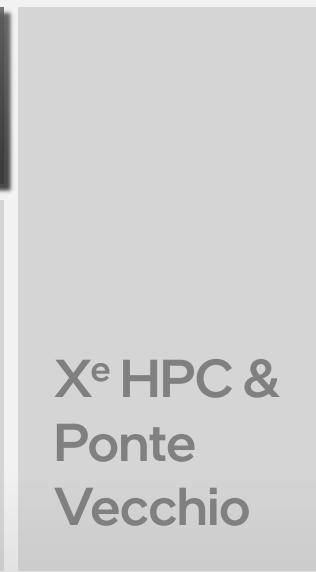
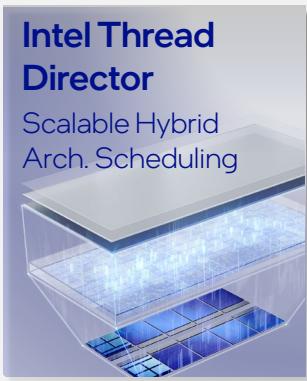
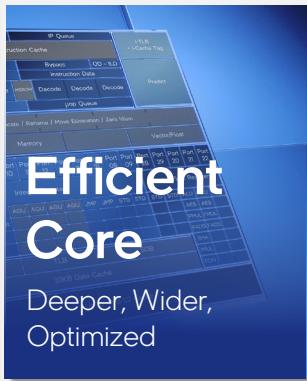
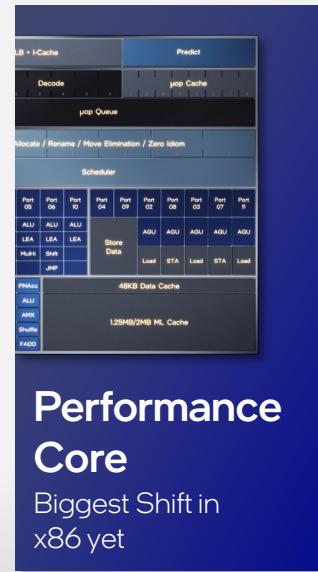
New Architectural Foundations



Architecture Day

2021

Part 1 Recap



Sapphire Rapids

Sailesh Kottapalli

Introducing

Sapphire Rapids

Next-Gen Intel Xeon Scalable Processor

New Standard for
Data Center Architecture

Designed for Microservices
& AI Workloads

Pioneering Advanced Memory
& IO Transitions



Node Performance



Data Center Performance

Node Performance



Scalar Performance

New Performance Core
Microarchitecture

Data Parallel Performance

Multiple Integrated
Acceleration Engines

Cache & Memory Sub- System Arch

Larger Private &
Shared Caches

DDR 5

Next Gen Optane
Support

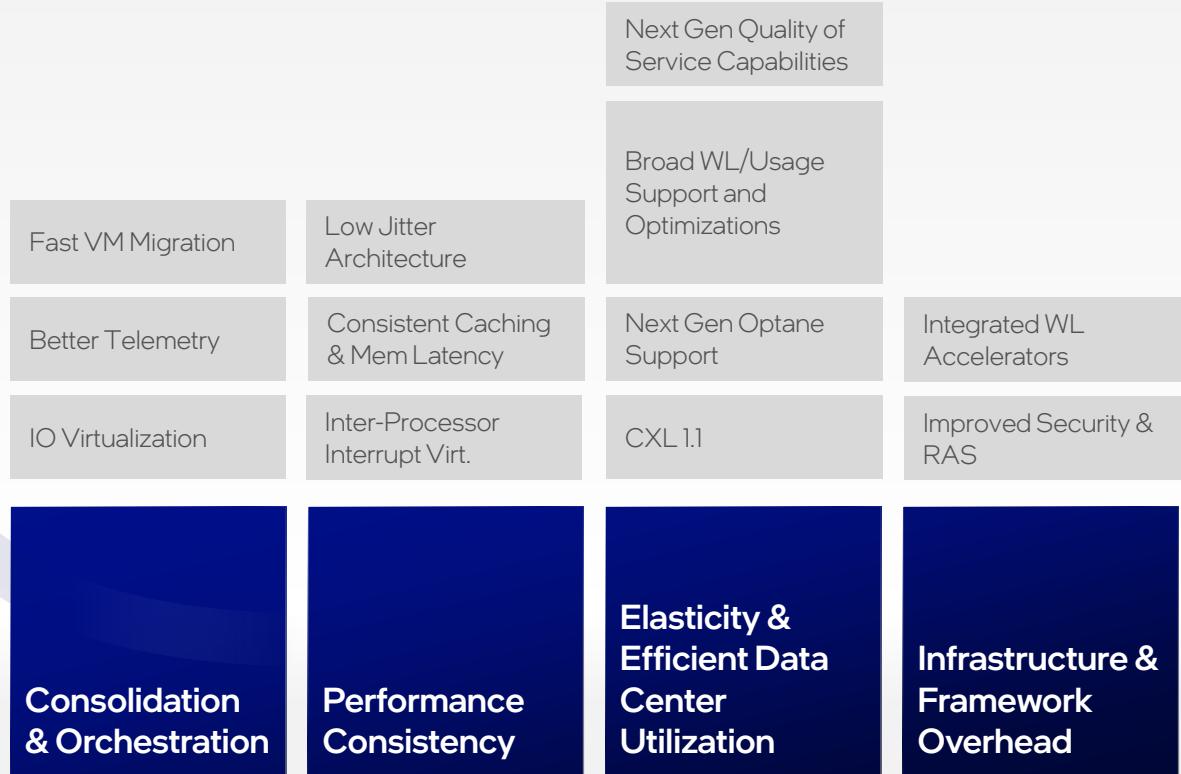
PCIe 5.0

Intra/Inter Socket Scaling

Modular SoC /w
Modular Die Fabric

Wider & Faster UPI

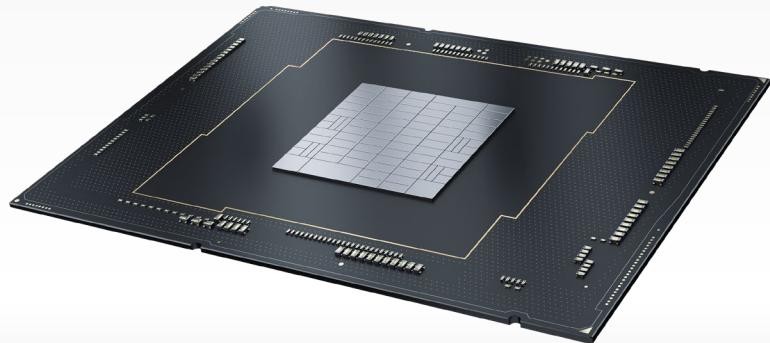
Embedded Silicon
Bridge (EMIB)



Data Center Performance

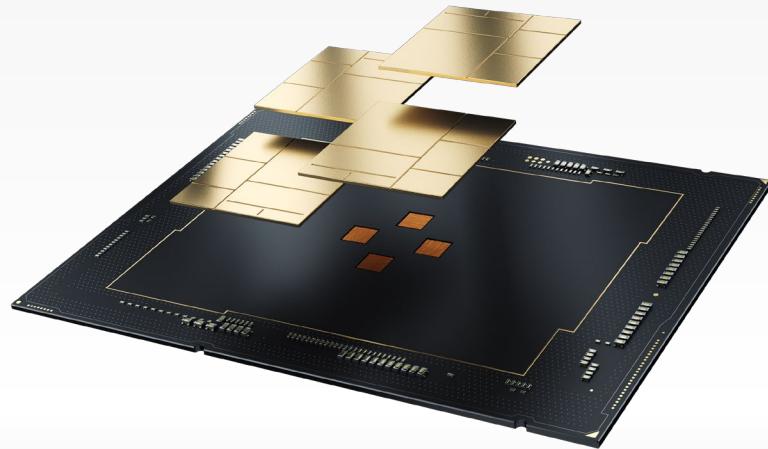
Ice Lake

Single Monolithic Die



Sapphire Rapids

Multi-Tile Design for Increased Scalability



Delivers a scalable, balanced architecture leveraging existing software paradigms
for monolithic CPUs via a modular architecture

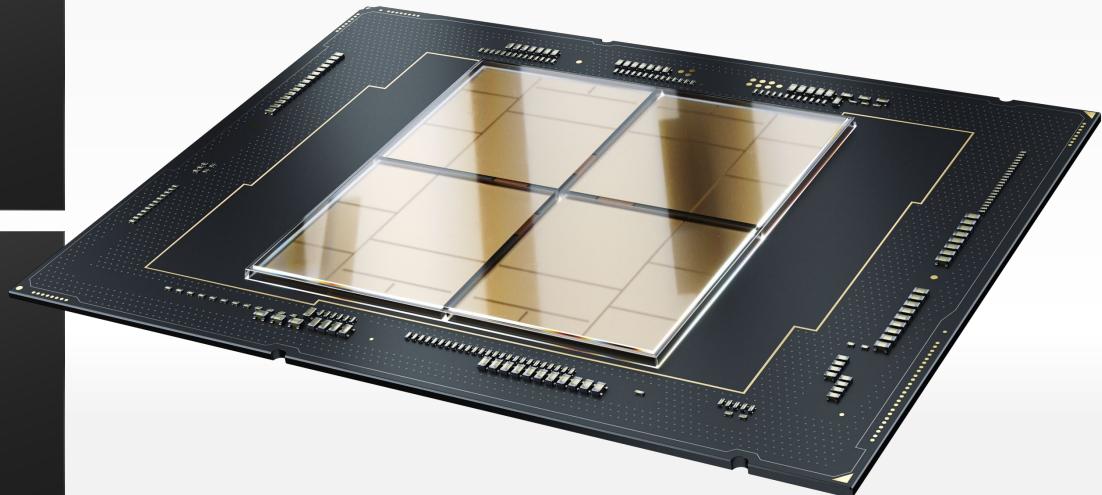
Sapphire Rapids

Multiple Tiles, Single CPU

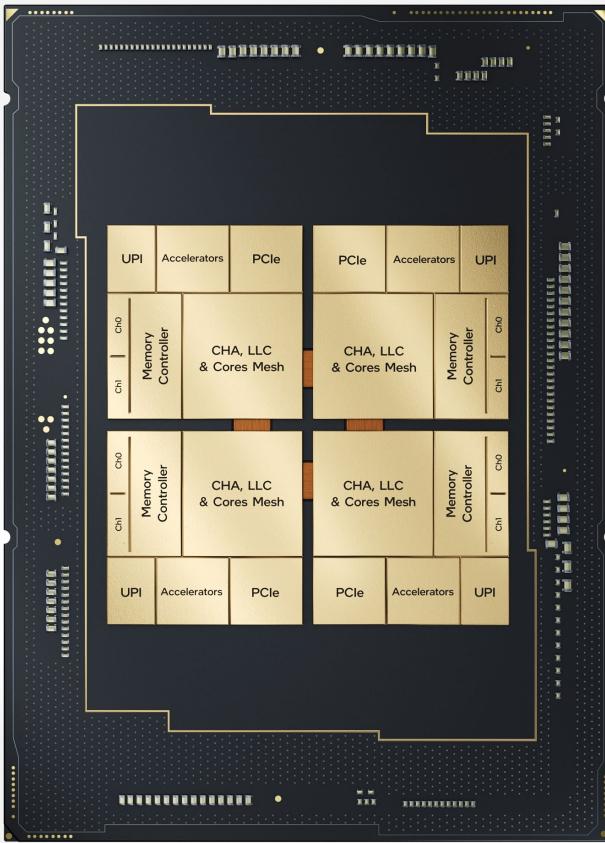
Every thread has full access to all resources on all tiles

Cache, Memory, IO...

Provides consistent low latency & high cross-section BW across the entire SoC

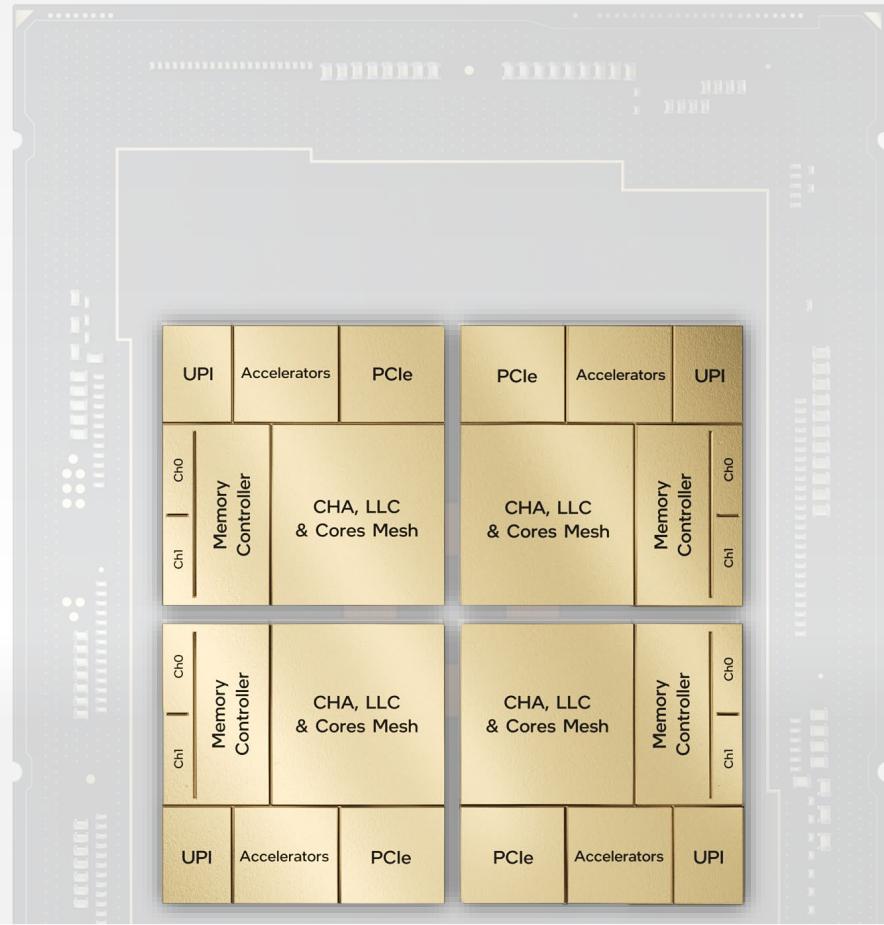
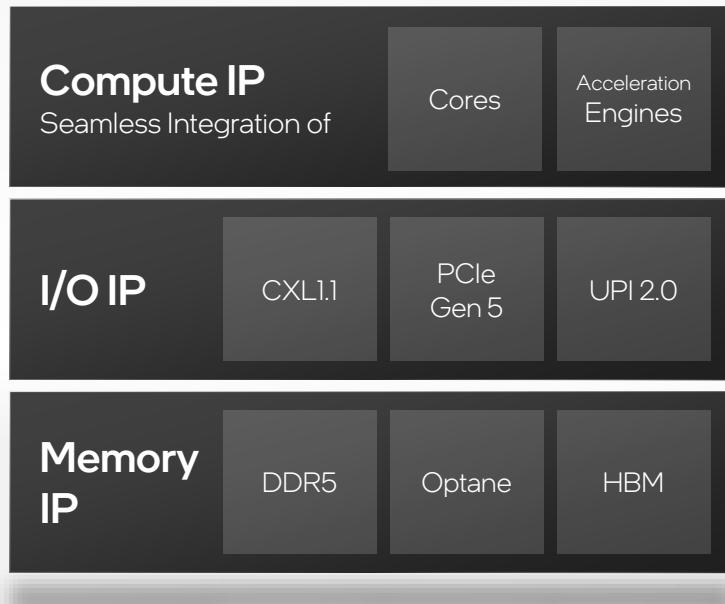


Sapphire Rapids SoC



Sapphire Rapids

Key Building Blocks



Performance Core

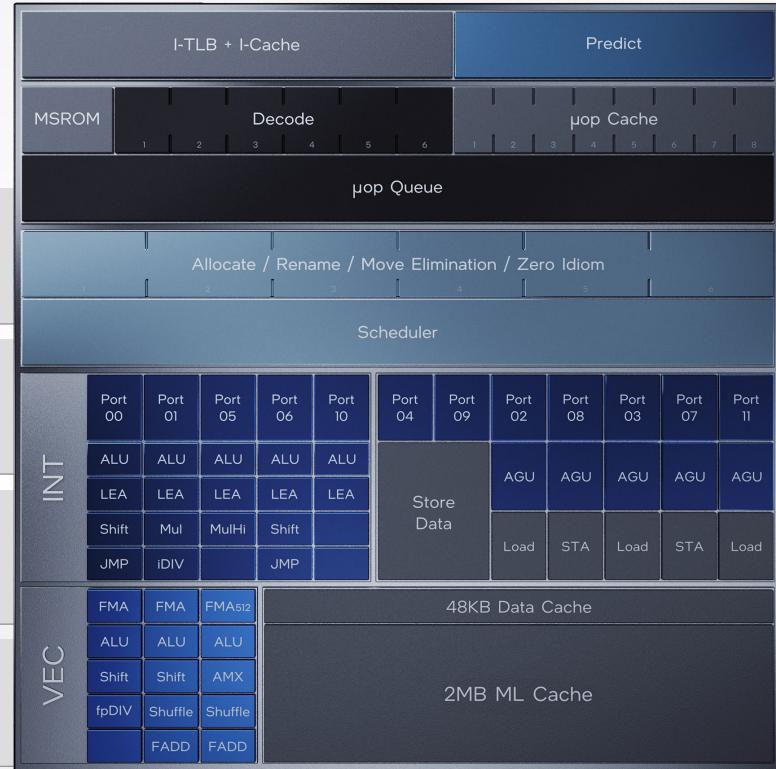
Built for Data Center

Major microarchitecture and IPC improvement

Improved support for large code/data footprint

Consistent performance for multi-tenant usages

Autonomous/Fast PM for high freq @ low jitter



Performance Core

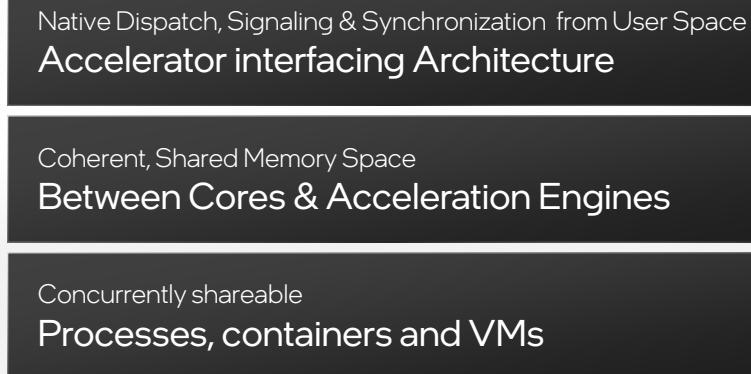
Architecture
Improvements for DC
Workloads & Usages

AI	Intel® Advanced Matrix Extensions - AMX Tiled matrix operations for inference & training acceleration
Attached Device	Accelerator interfacing Architecture - AiA Efficient dispatch, signaling & synchronization from user level
FP16	Half- Precision Support for higher throughput lower precision
Cache Management	CLDEMOTE Proactive placement of cache contents

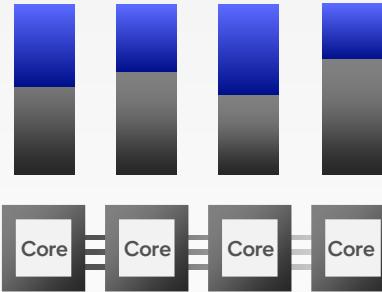
Sapphire Rapids

Acceleration Engines

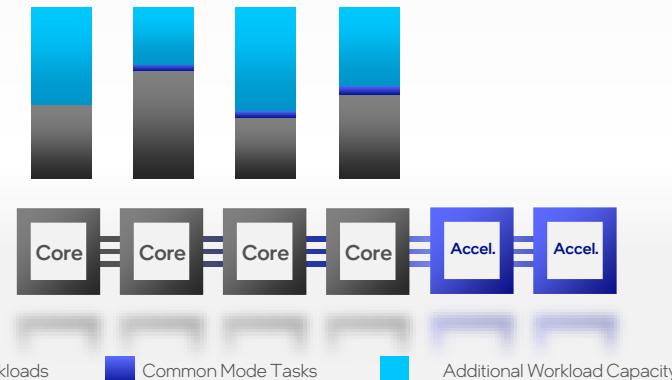
Increasing effectiveness of cores,
by enabling offload of common mode tasks via
seamlessly integrated acceleration engines



Utilization Without Acceleration



Utilization With Acceleration



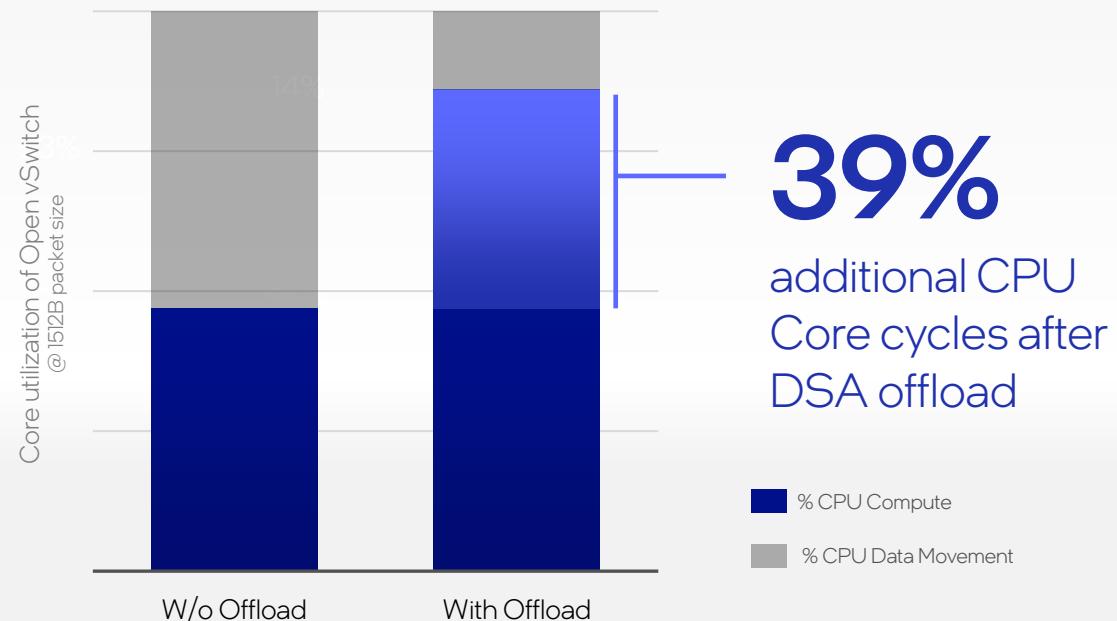
Acceleration Engine

Optimizing streaming data movement and transformation operations

up to
4 Instances per Socket

Low Latency Invocation

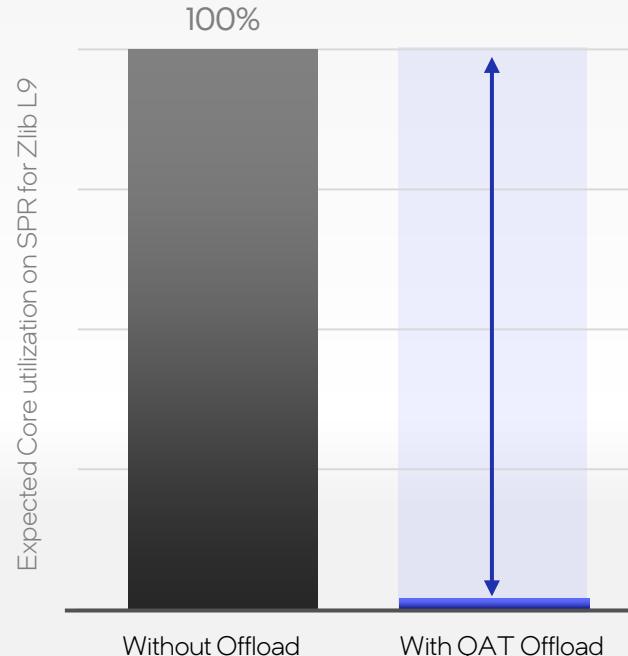
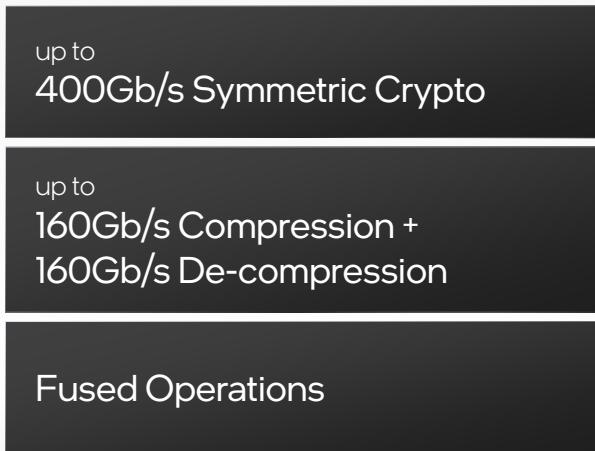
No Memory Pinning Overhead



Results have been estimated or simulated and based on tests with Ice Lake with Intel QAT For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Acceleration Engine

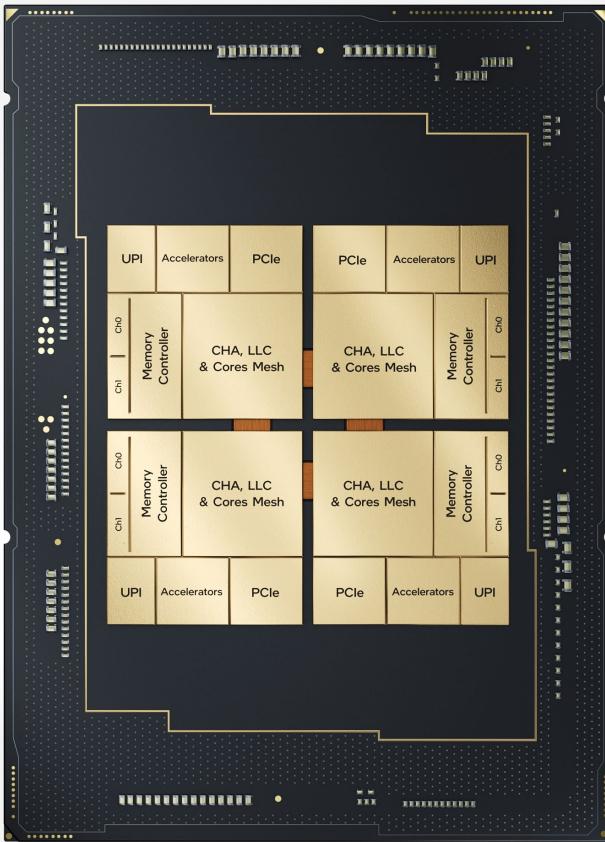
Accelerating Cryptography and Data De/Compression



98%
additional
workload capacity
after QAT offload

Results have been estimated or simulated. Sapphire Rapids estimation based on architecture models and baseline testing with Ice Lake and Intel QAT. For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Sapphire Rapids SoC



Sapphire Rapids

I/O Advancements

Introducing Compute eXpress Link (CXL) 1.1

Accelerator and memory expansion in datacenter

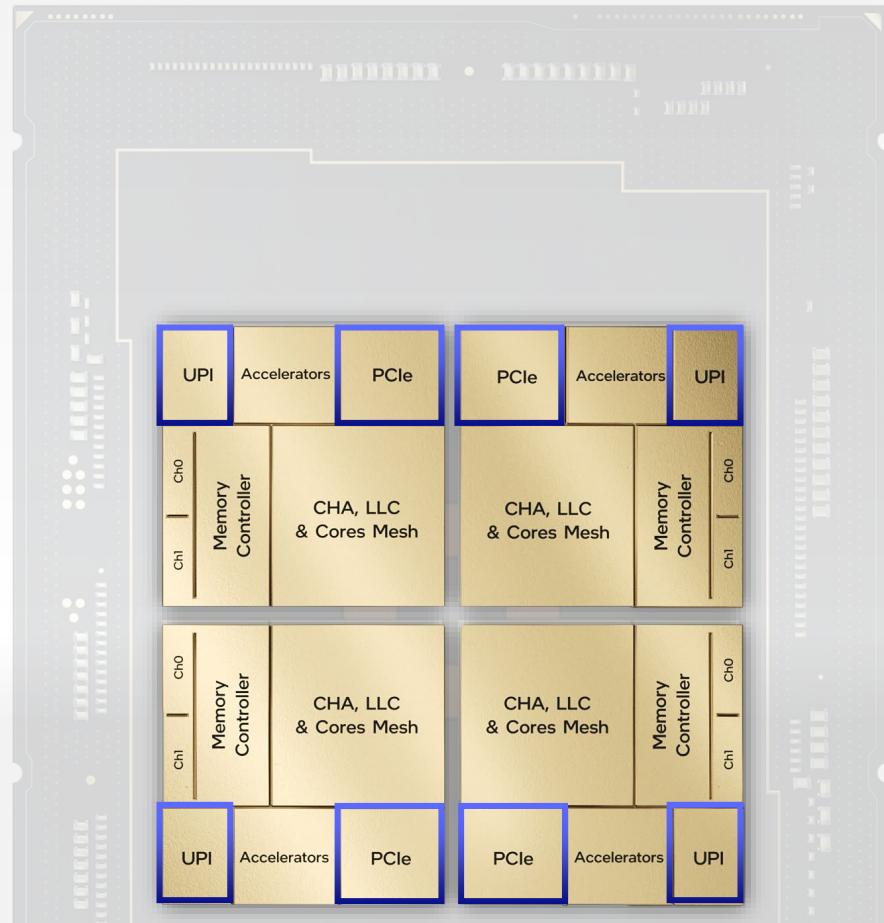
Expanded device performance via PCIe 5.0 & connectivity

Improved DDIO & QoS capabilities

Improved Multi-Socket scaling via Intel® Ultra Path Interconnect (UPI) 2.0

Up to 4 x24 UPI links operating @ 16 GT/s

New 8S-4UPI performance optimized topology



Sapphire Rapids

Memory and Last Level Cache

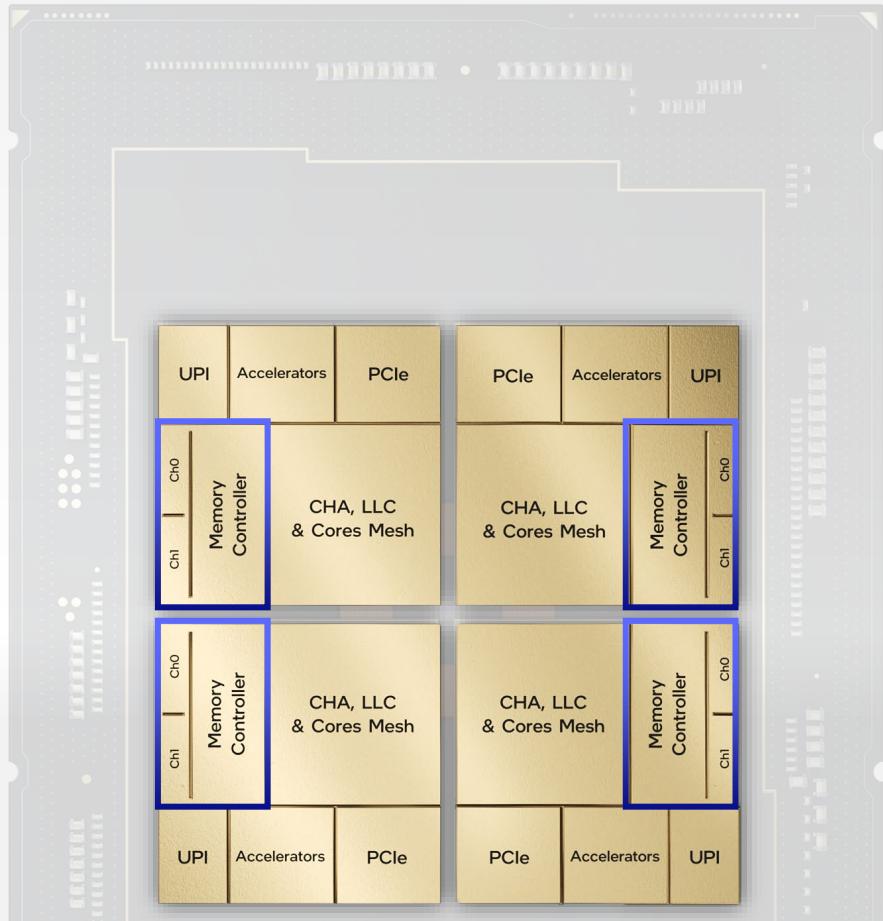
Increased Shared Last Level Cache (LLC)

Up to >100 MB LLC shared across ALL cores

Increased bandwidth, security & reliability via DDR 5 Memory

4 memory controllers supporting 8 channels

Intel® Optane™ Persistent Memory 300 Series



Sapphire Rapids

High Bandwidth Memory

Significantly Higher Memory Bandwidth

vs. baseline Xeon-SP with 8 channels of DDR 5

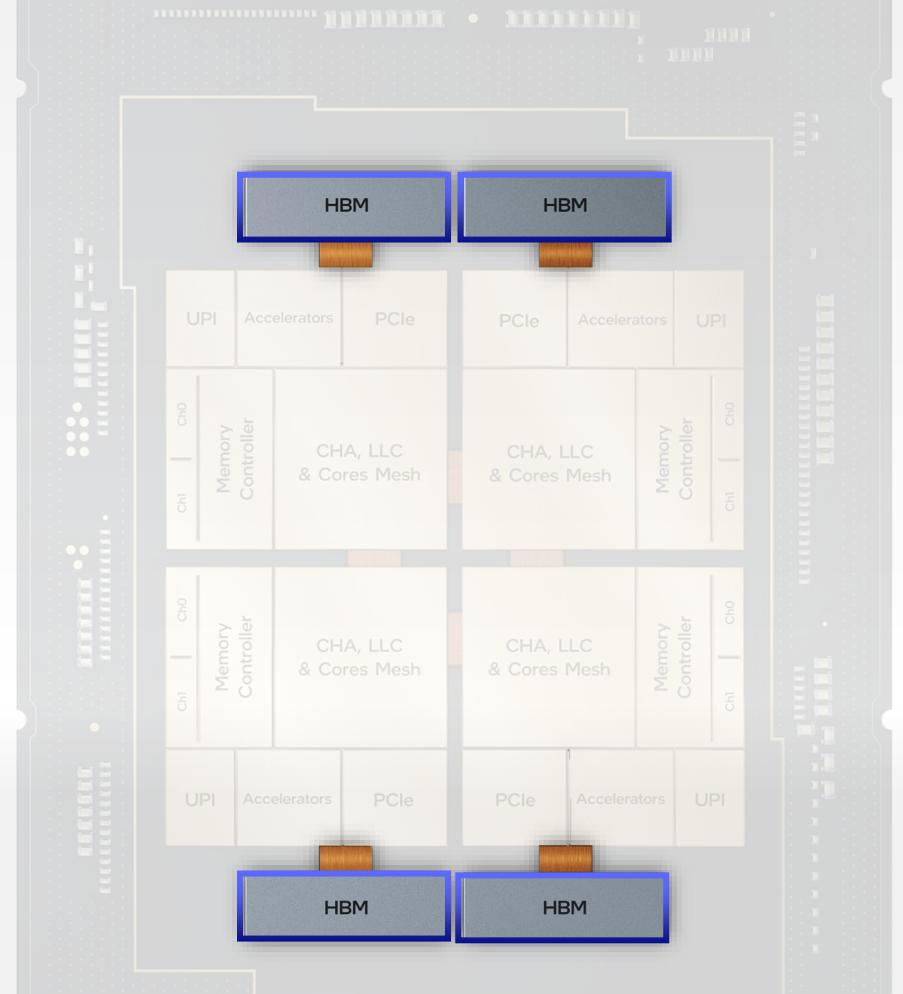
Increased capacity and Bandwidth

some usages can eliminate need for DDR entirely

2 Modes

HBM Flat Mode
Flat Mem Regions w/ HBM & DRAM

HBM Caching Mode
DRAM backed cache



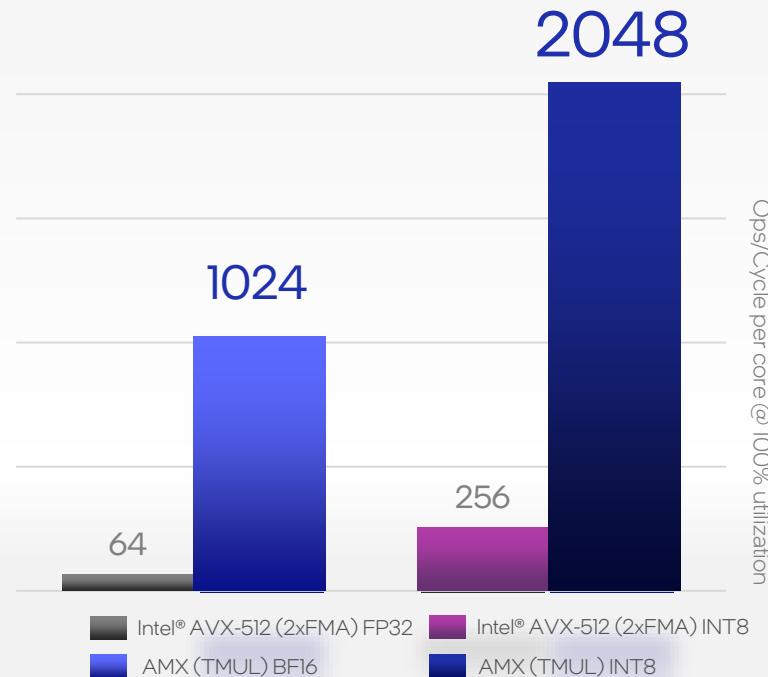
Sapphire Rapids - Architected for AI

AI has become ubiquitous across usages – AI performance required in all tiers of computing

Goal

Enable efficient usage of AI across all services deployed on elastic general-purpose tier by delivering many times more AI performance and lower CPU utilization

For Deep Learning Datatypes	<ul style="list-style-type: none">▪ int8 with int32 accumulation▪ Bfloat16 with IEEE SP accumulation
Acceleration at the ISA Level	<ul style="list-style-type: none">▪ Full Intel Arch. programmability▪ Low Latency
Available and integrated with industry-relevant frameworks & libraries	



Results have been simulated. For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Sapphire Rapids - Built for elastic computing models - microservices

>80% of new cloud-native and SaaS applications are expected to be built as microservices

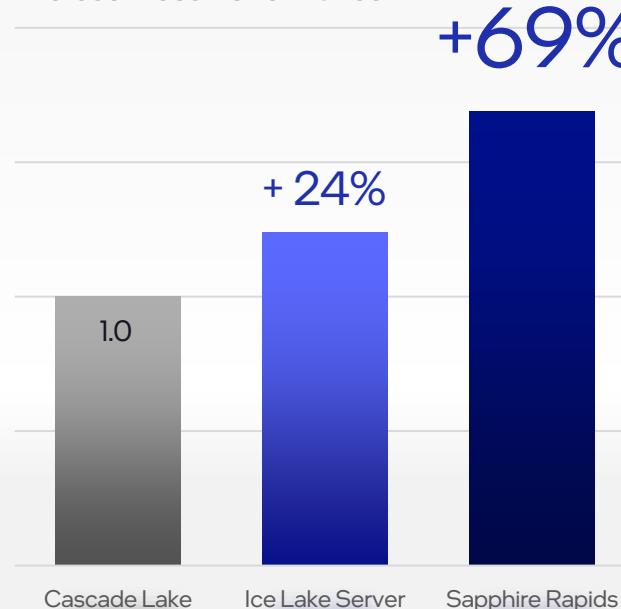
Goal

Enable higher throughput while meeting latency requirements and reducing infrastructure overhead for execution, monitoring and orchestration thousands of microservices

Improved Performance and Quality of Service	Runtime Languages - lower latency for Runtime Languages AiA ISA's - efficient worker threads, signaling and synch.
Reduced Infrastructure Overhead	Kubernetes – enhanced for scaling, placement and policies Advanced Telemetry - easier analysis & optimization
Better Distributed Communication	Improved latency of Remote procedure calls and service-mesh QAT, DSA etc.- optimized networking and data movement

Results have been simulated. For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Microservices Performance



New Standard in Data Center Architecture

Multi Tile SoC for Scalability

Physically Tiled,
Logically Monolithic

General Purpose
& Dedicated
Acceleration Engines

Designed for Microservices and AI Workloads

Performance Core
Architecture

Workload Specialized
Acceleration

Pioneering Advanced Memory & IO Transitions

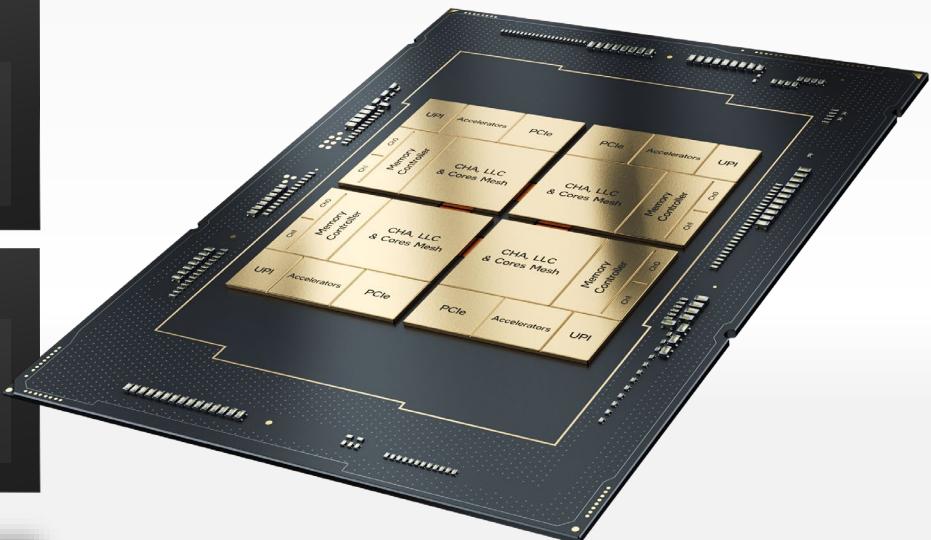
DDR 5 &
HBM

PCIe 5.0

Enhanced
Virtualization
Capabilities

Sapphire Rapids

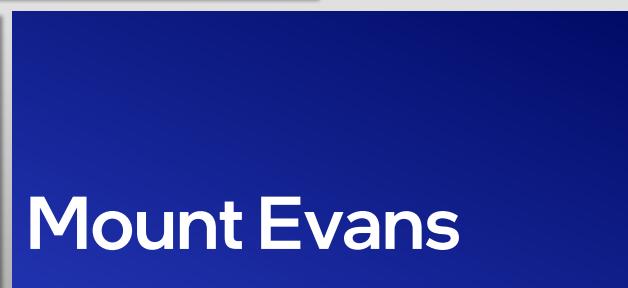
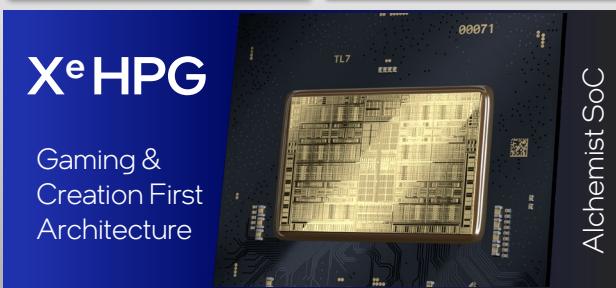
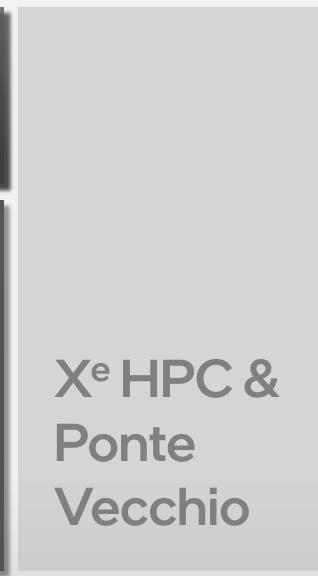
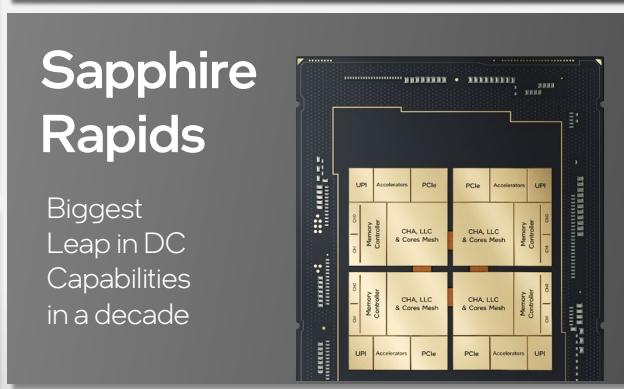
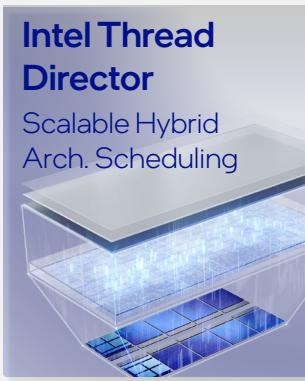
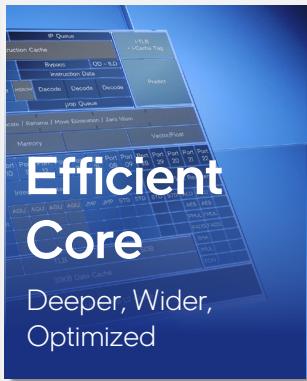
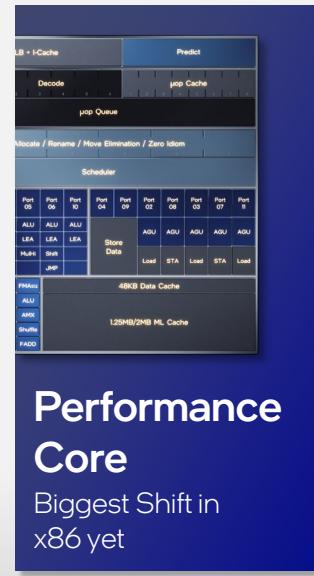
Biggest Leap in Data Center Capabilities
in over a Decade



Architecture Day

2021

New Architectural Foundations

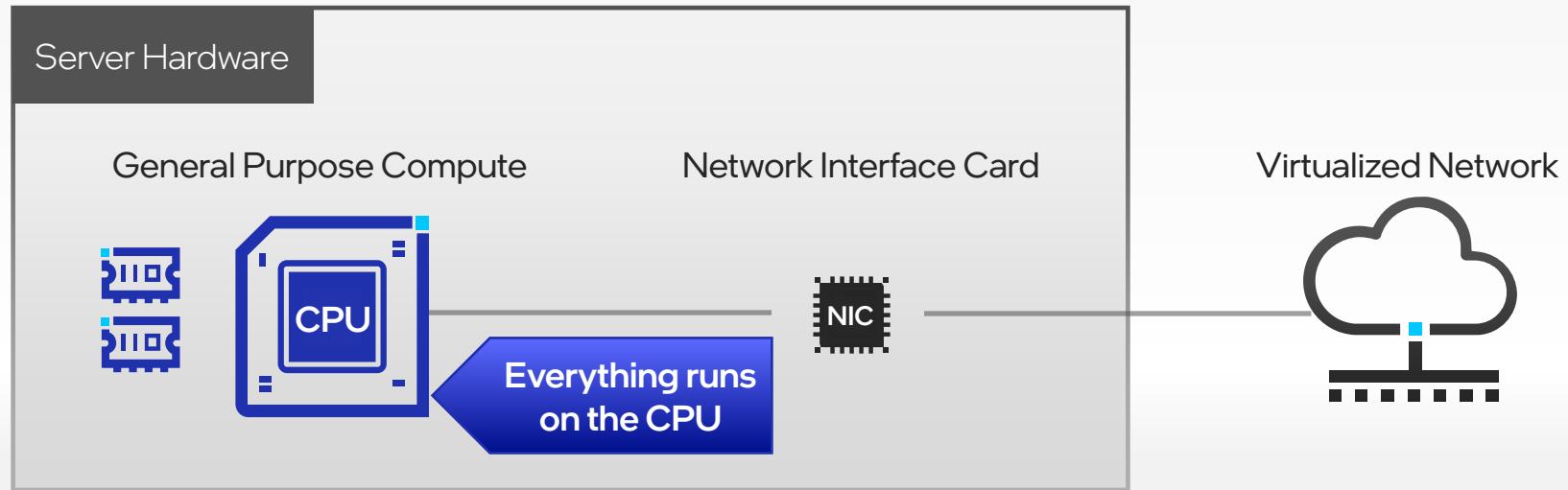


Infrastructure Processing Unit

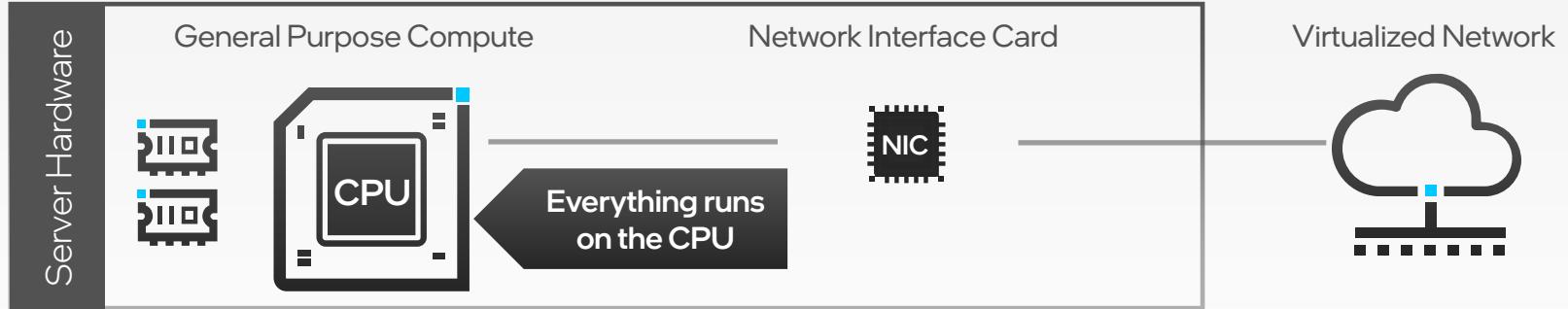
Guido Appenzeller

Server Architecture in a classic Data Center

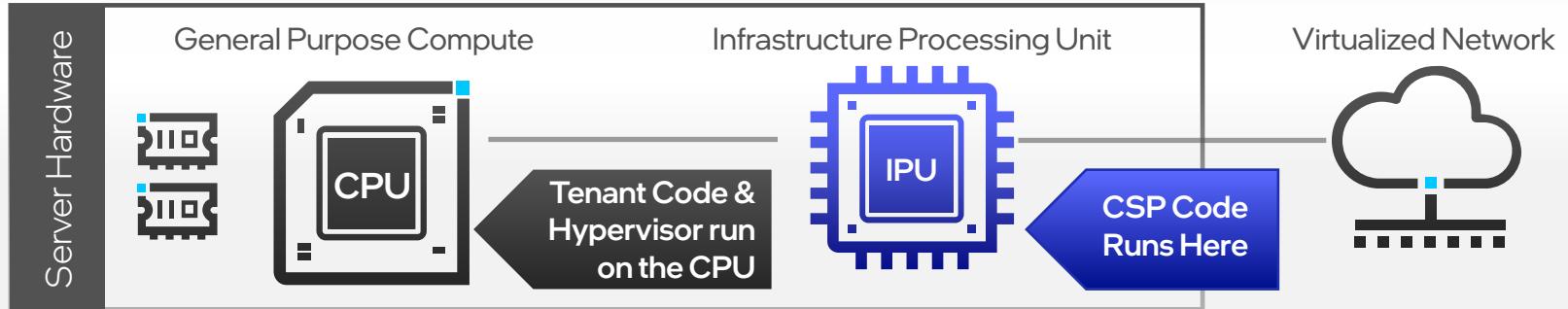
Software and Infrastructure are all controlled by One Entity

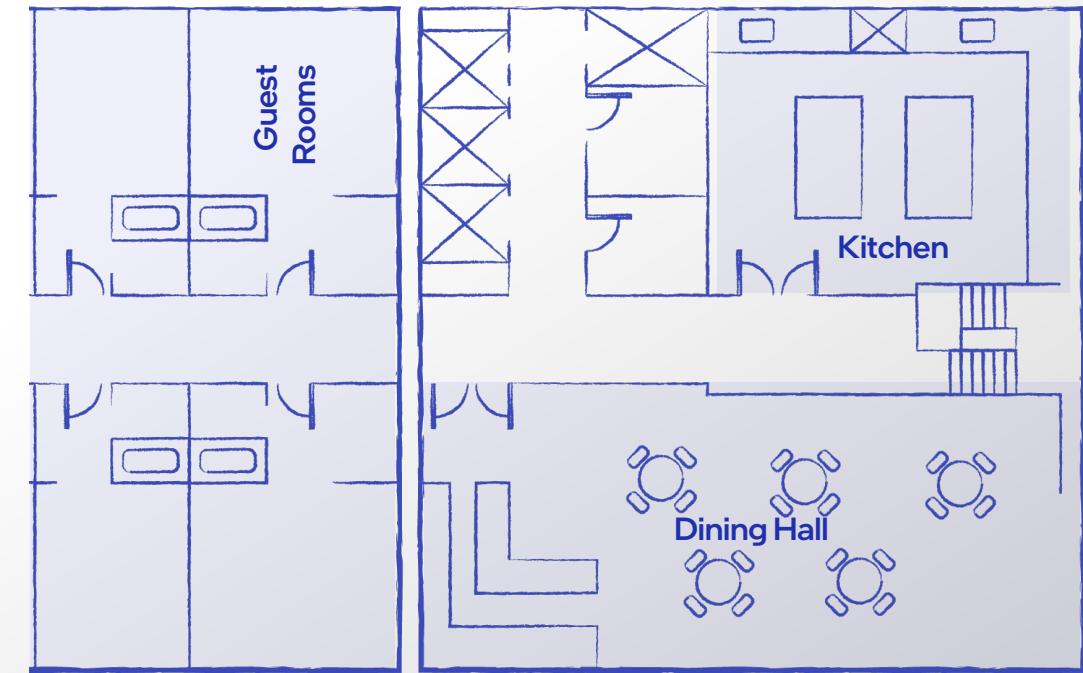
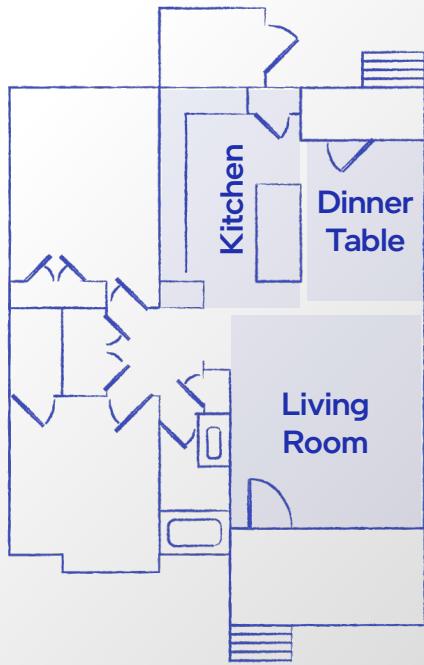


Classic Server Architecture



Cloud Server Architecture





Major Advantages of IPUs

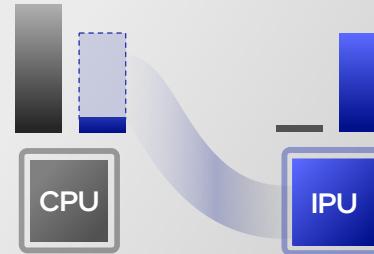
1



Separation of Infrastructure & Tenant

Guest can fully control the CPU with their SW, while CSP maintains control of the infrastructure and Root of Trust

2



Infrastructure Offload

Accelerators help process these task efficiently. Minimize latency and jitter and maximize revenue from CPU

3

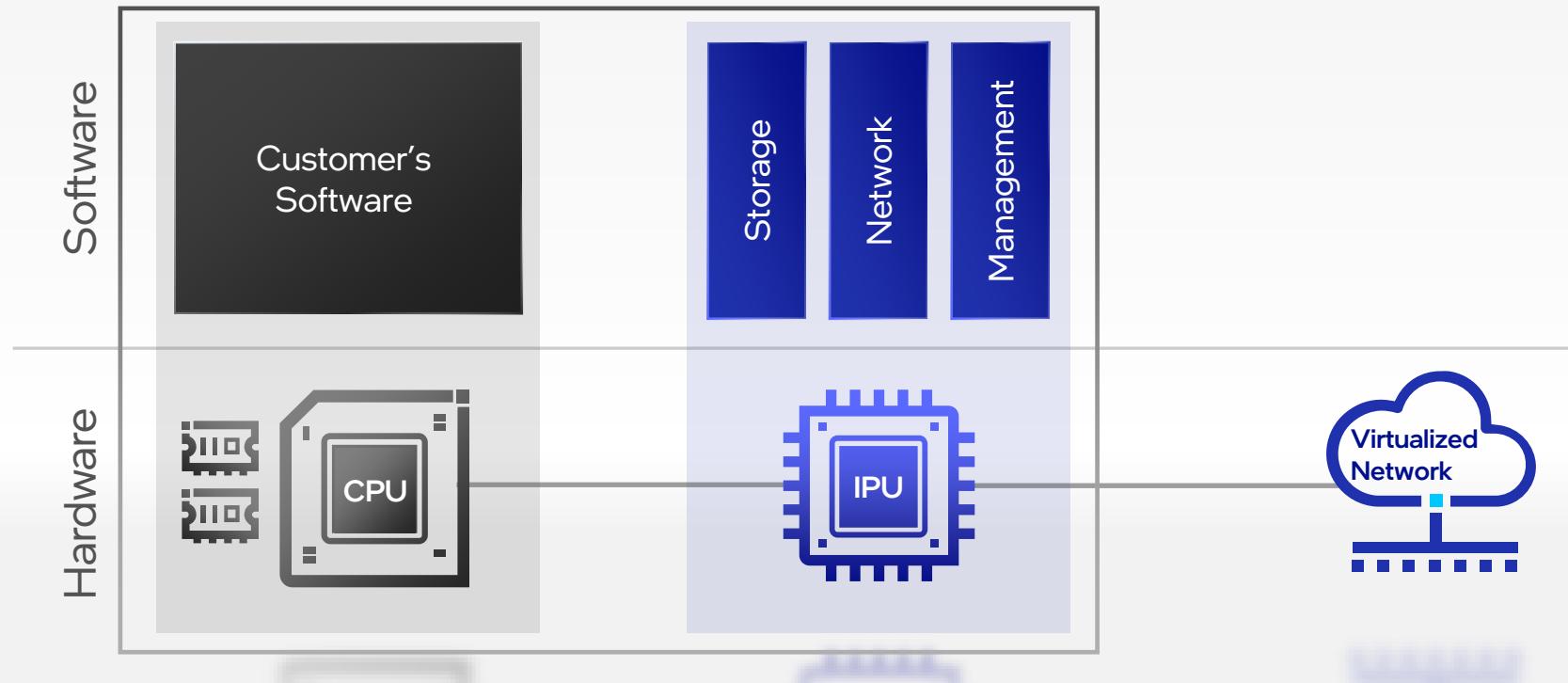


Diskless Server Architecture

Simplifies data center architecture while adding flexibility for the CSP

Advantage 1 - Separation of Infrastructure and Tenant

Maximum Control and Isolation for the Tenant

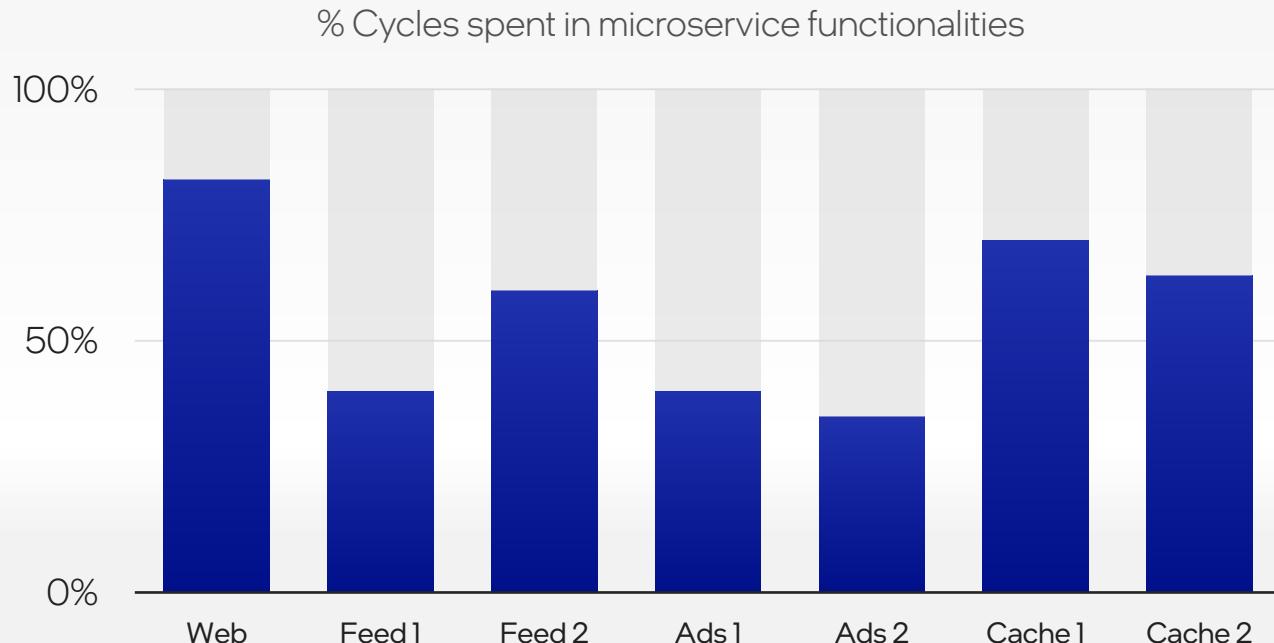


Advantage 2 - Infrastructure Offload

In some cases, the majority of CPU cycles are spent on overhead

31%
to 83%

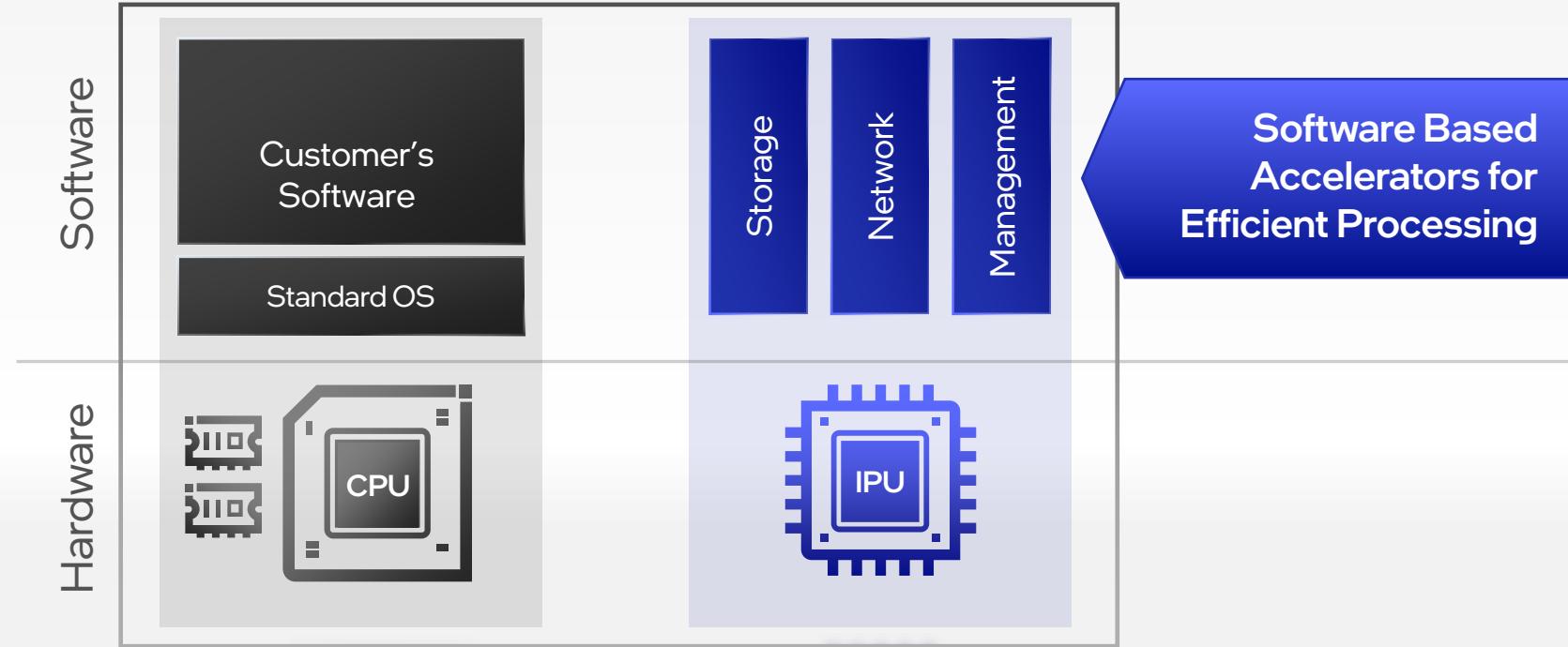
Microservice
Overhead at
Facebook



Source: From Accelerometer: Understanding Acceleration Opportunities for Data Center Overheads at Hyperscale. Akshitha Srirama, Abhishek Dhanotia. Facebook.

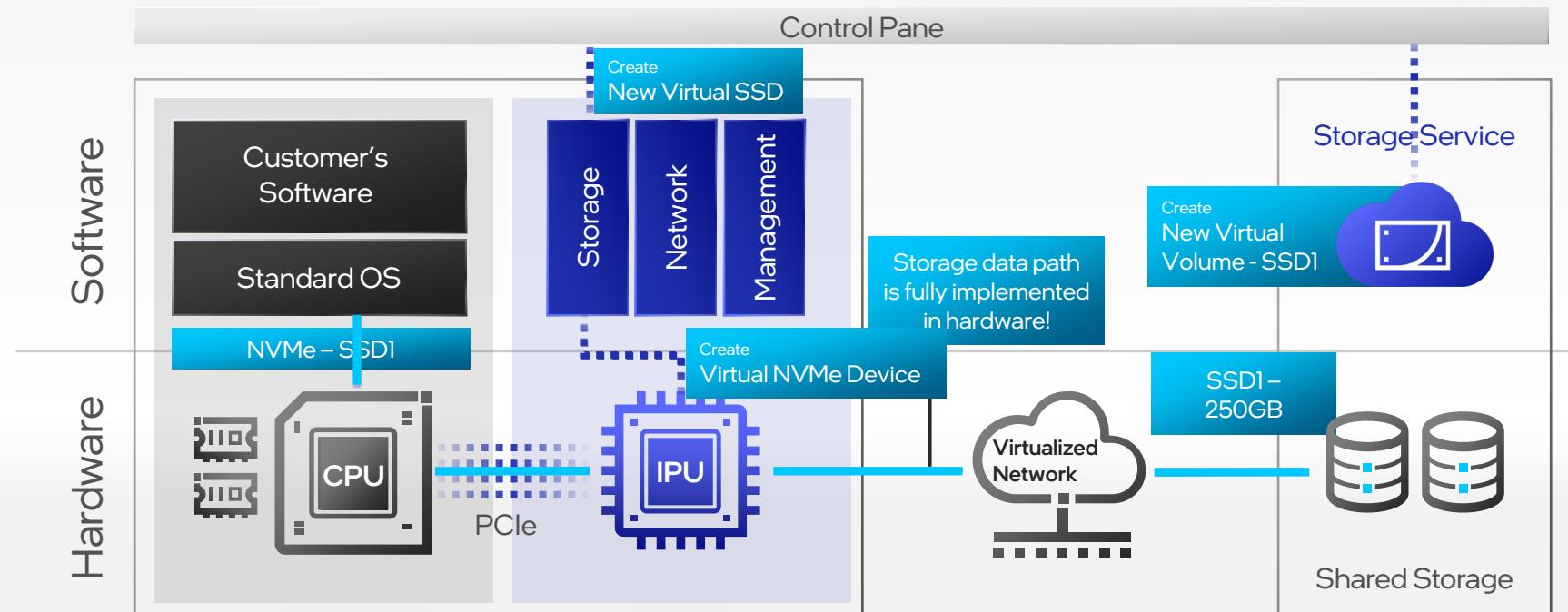
Advantage 2 - Infrastructure Offload

Dedicated Accelerators Free up CPU Capacity



Advantage 3 - Diskless Server Architecture

Scale with Virtual Storage via Network



Broad Infrastructure Acceleration Portfolio

Dedicated ASIC IPU

Performance and power optimized

Optimized secure networking and storage pipeline



FPGA-based Acceleration

IPU Platforms & Adapters

Faster time to market for evolving standards

Re-programmable Secure Datapath enables flexible/customizable workload offload (future proof)

Onboard Intel® Xeon® processor



SmartNICs

Programmable accelerated infrastructure workloads with customizable packet processing

Intel Ethernet NIC with DPDK support



Note: Future Intel IPUs may integrate both ASIC and FPGA

Introducing

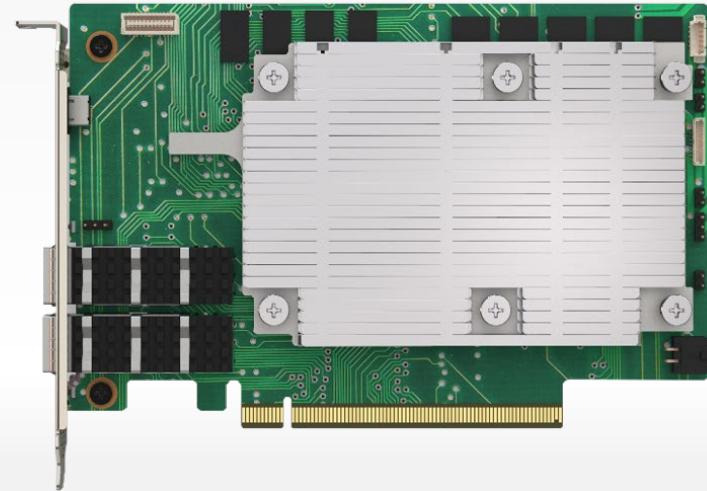
Oak Springs Canyon

High perf networking and storage acceleration for
Cloud Service Providers

OVS, NVMe over Fabric, and RoCE solutions

Programmable through Intel OFS, DPDK, and SPDK

Customizable solutions with FPGA



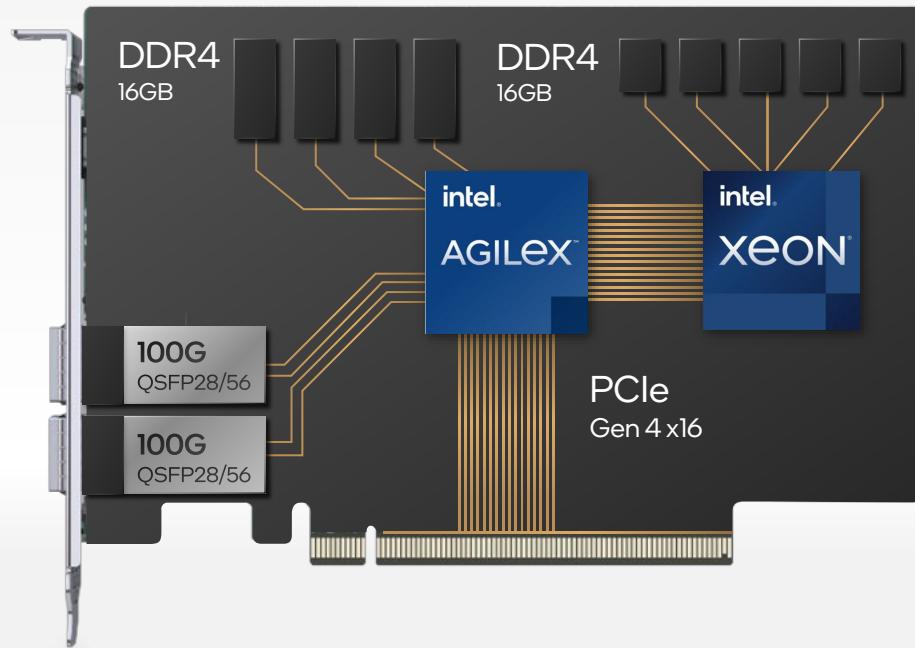
Oak Springs Canyon

Built with Intel® Agilex FPGA and Xeon-D SoC

High speed Ethernet support - 2x100G

PCIe Gen 4 x16

Hardware crypto block enables security at line rate



Introducing

Arrow Creek

Acceleration Development Platform (ADP) for High Performance 100G networking acceleration

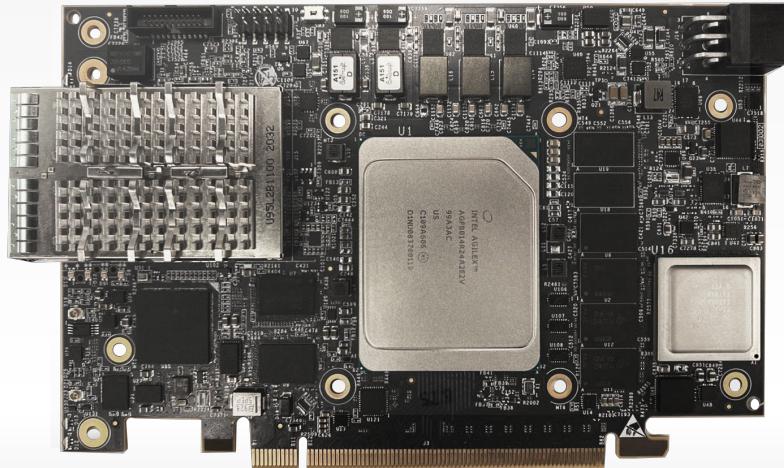
Customizable packet processing
including bridging and networking services

Programmable through Intel OFS and DPDK

Accelerated infrastructure workloads
Juniper Contrail, OVS, SRv6, vFW

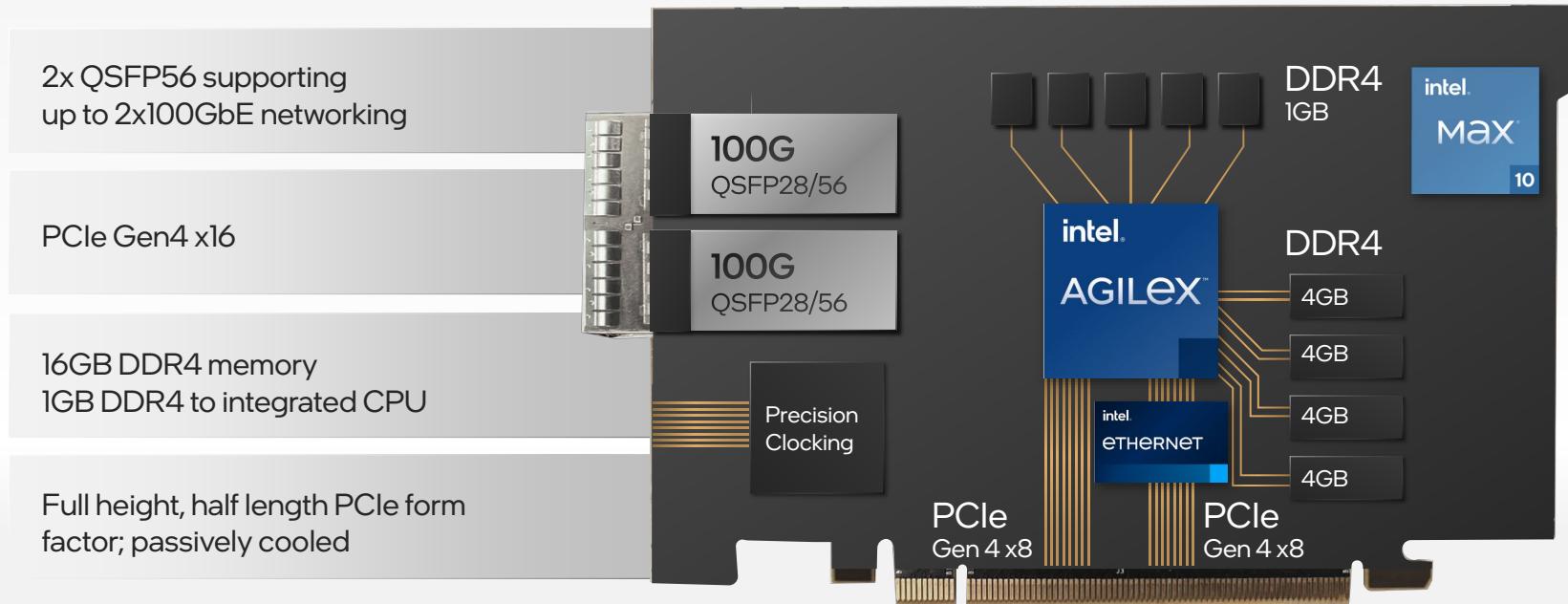
Secure Remote Update
of FPGA and Firmware over PCIe

On-board root of trust



Arrow Creek

Built with Intel® Agilex FPGA and Ethernet E810 Controller



Mount Evans

Naru Sundar

Introducing

Mount Evans

Intel's 200G IPU



Hyperscale Ready

Co-designed with a top cloud provider

Integrated learnings from multiple gen. of FPGA sNICs

High performance under real world load

Security and isolation from the ground up

Technology Innovation

Best-in-Class Programmable Packet Processing Engine

NVMe storage interface scaled up from Intel Optane Tech

Next Generation Reliable Transport

Advanced crypto and compression accel.

Software

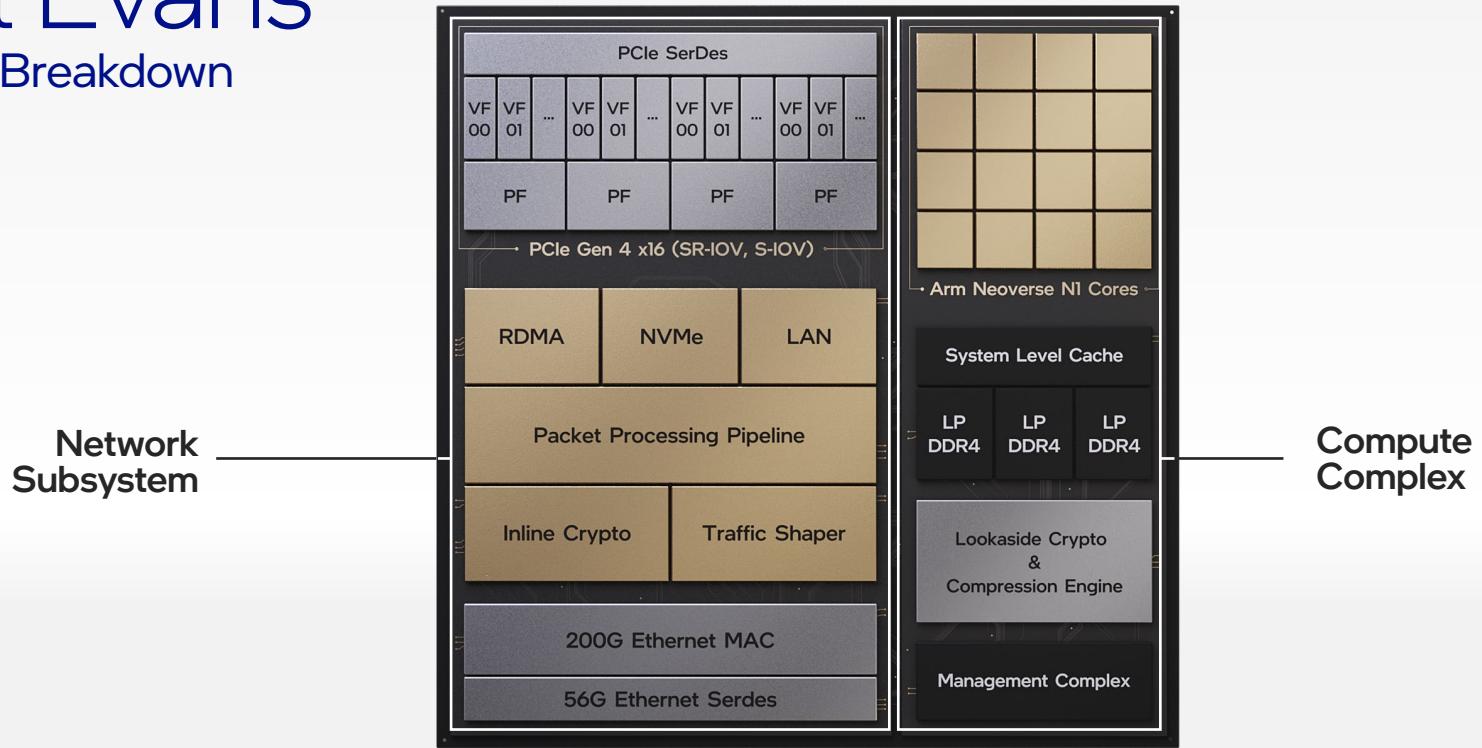
SW/HW/Accel co-design

P4 Studio based on Barefoot

Leverage and extend DPDK and SPDK

Mount Evans

Architectural Breakdown



Mount Evans

Architectural Breakdown

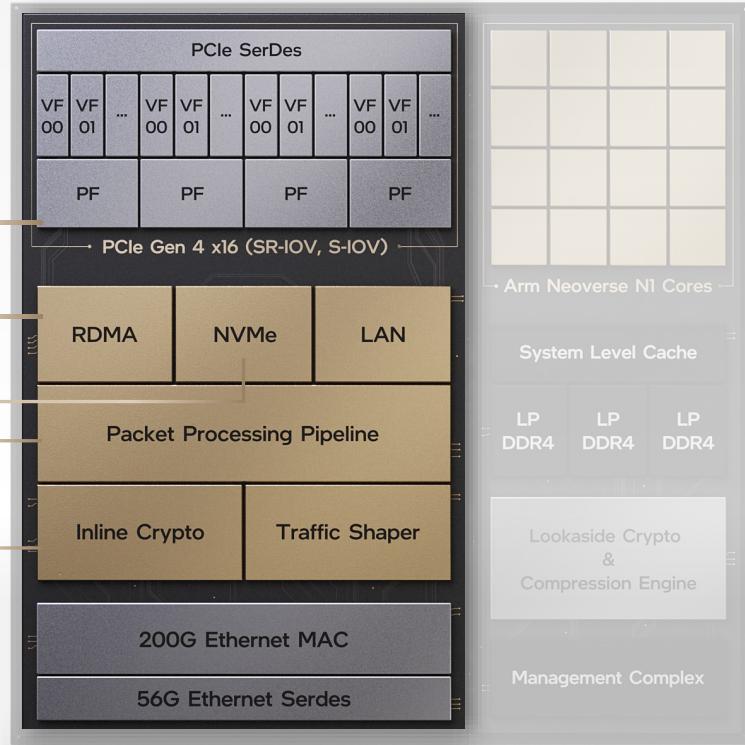
Support for up to 4 host Xeons with
200Gb/s full duplex

High-performance ROCEv2

NVMe offload engine

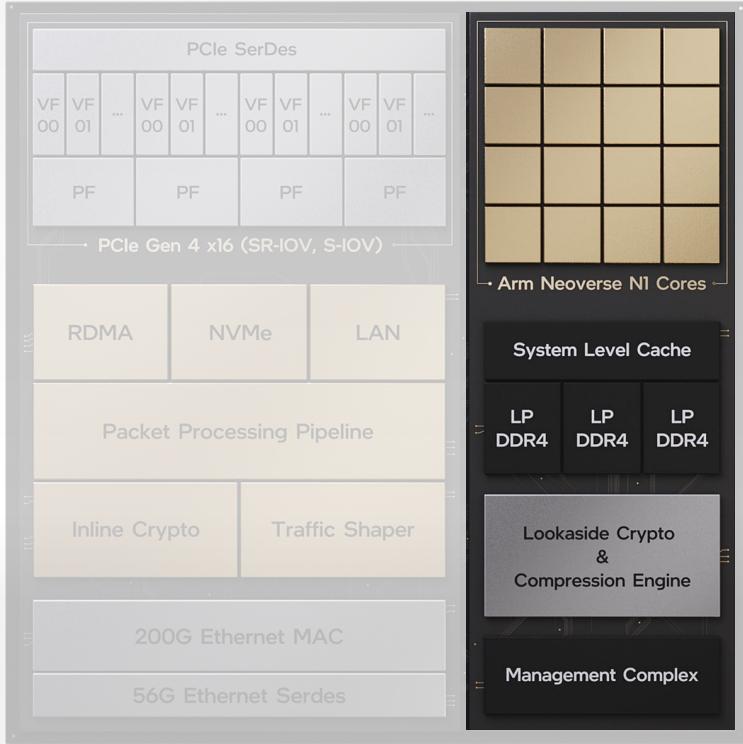
Programmable packet pipeline with QoS
and telemetry capabilities

Inline IPSec



Mount Evans

Compute Complex



Up to 16 Arm Neoverse® N1 Cores

Dedicated compute and cache with up to 3 memory channels

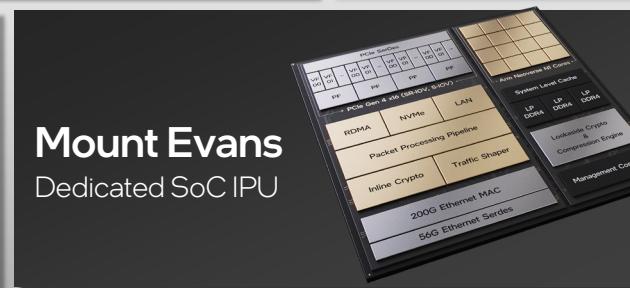
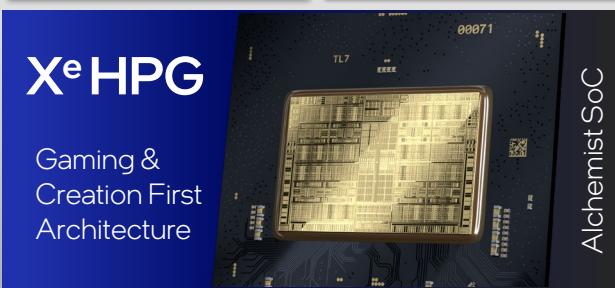
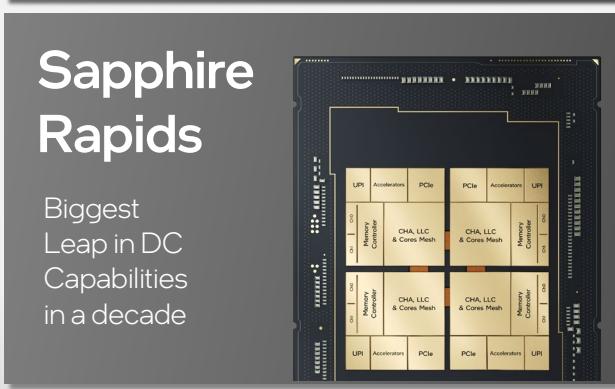
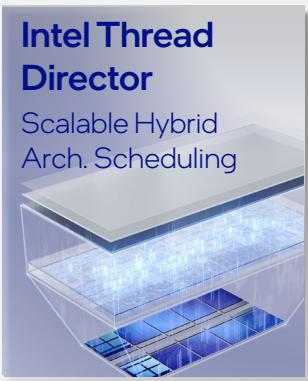
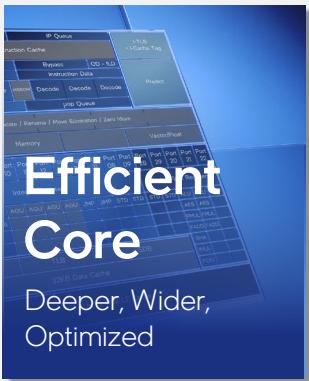
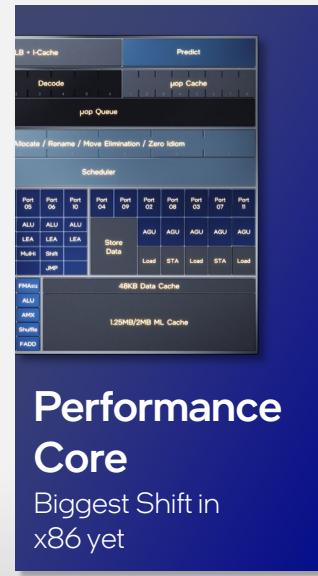
Lookaside crypto and compression

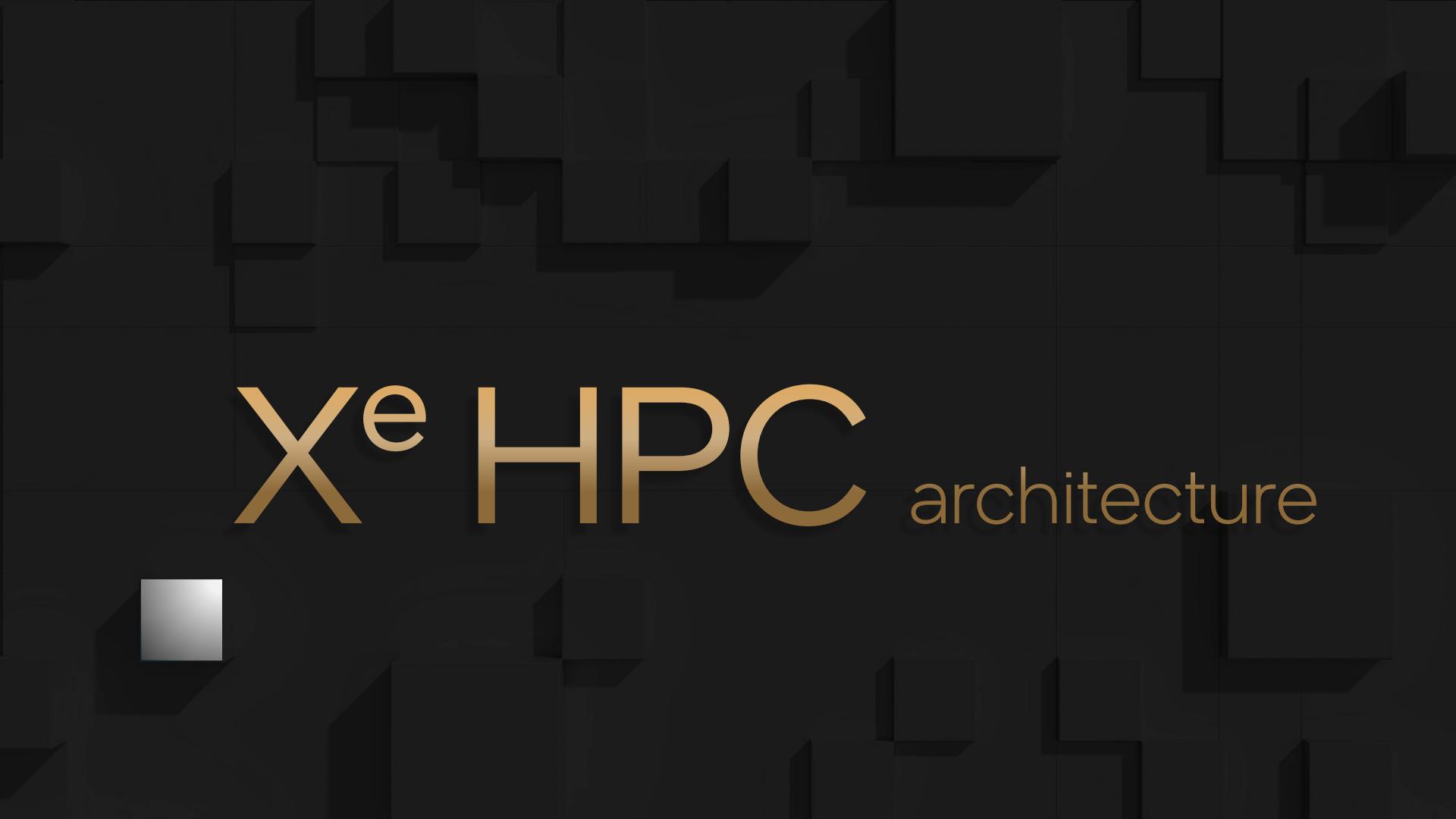
Dedicated management processor

Architecture Day

2021

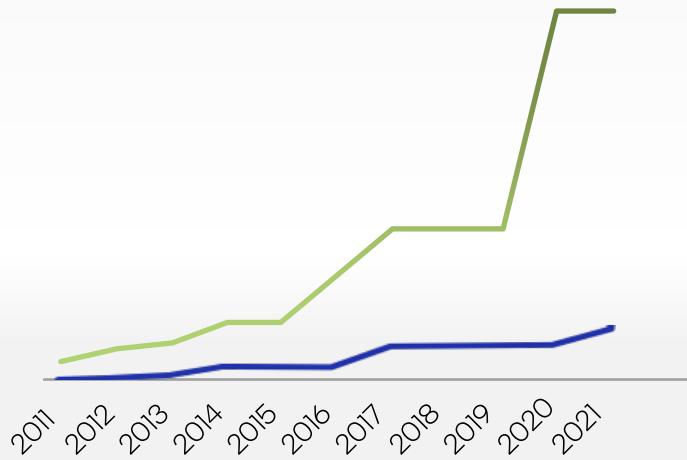
New Architectural Foundations





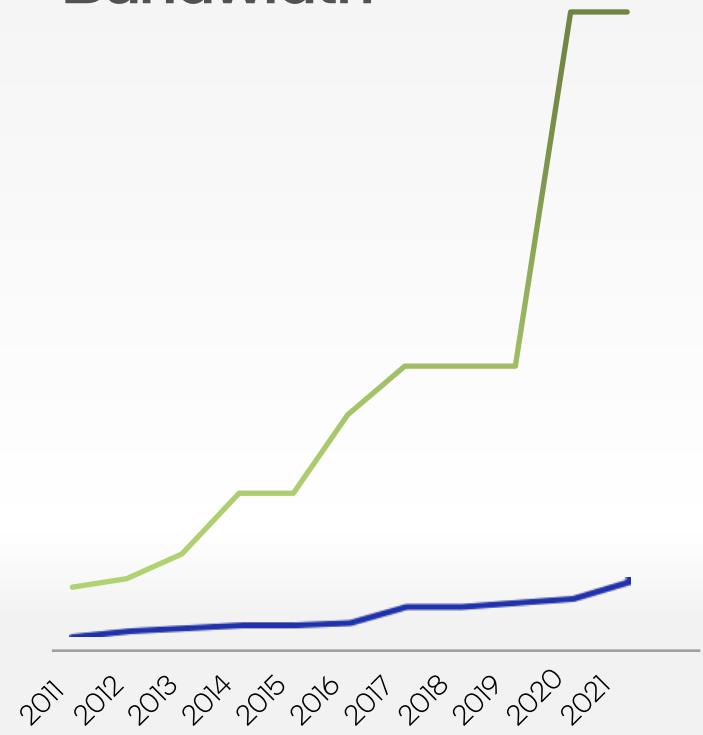
Xe HPC architecture

HPC FP64

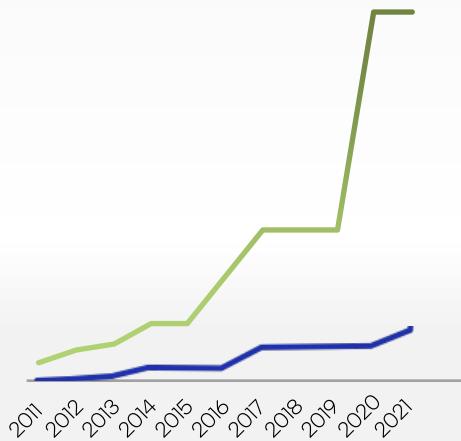


For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

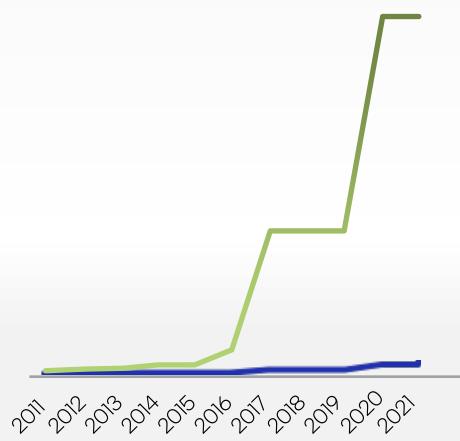
Bandwidth GB/s



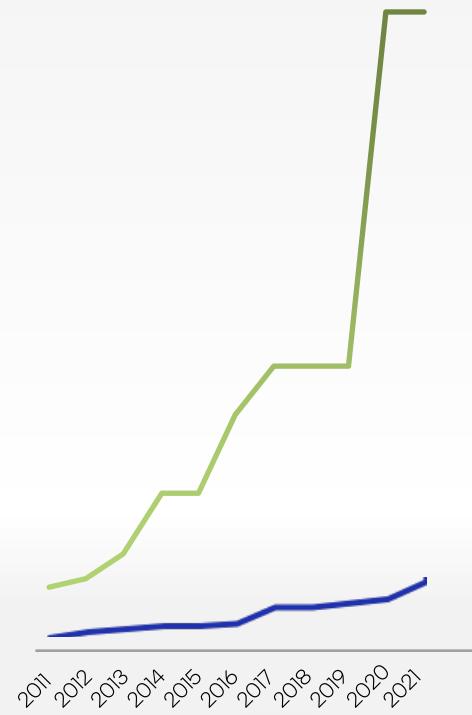
HPC FP64



AI FP16/BF16

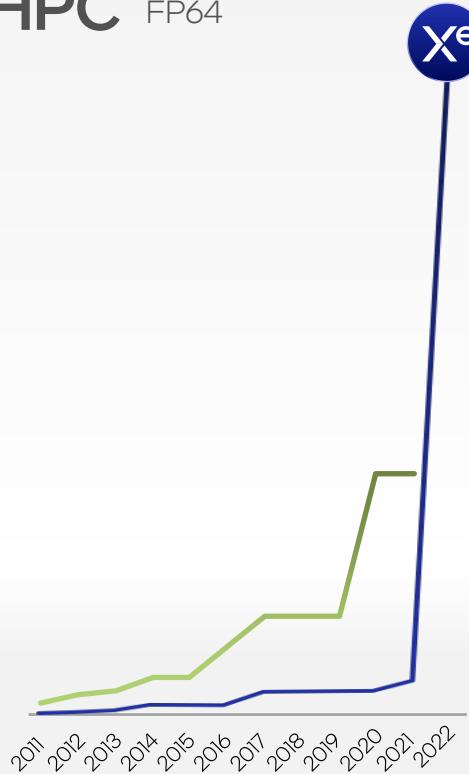


Bandwidth GB/s

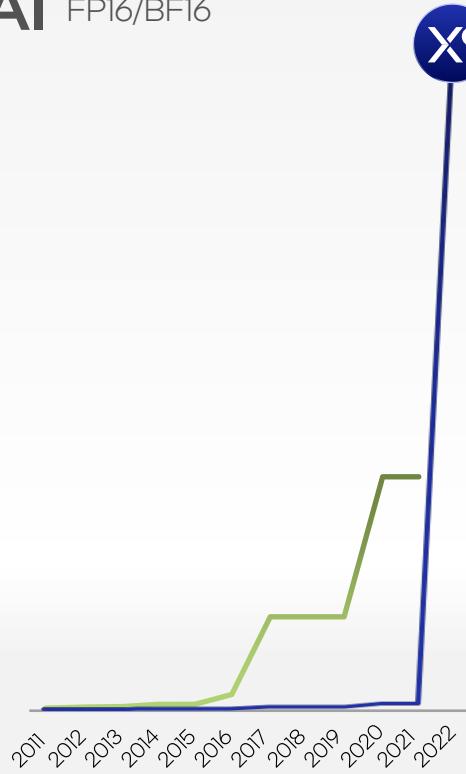


For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

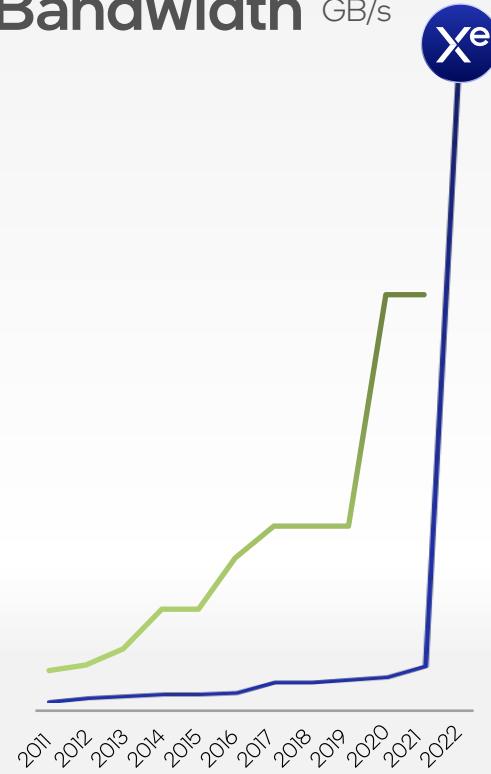
HPC FP64



AI FP16/BF16



Bandwidth GB/s

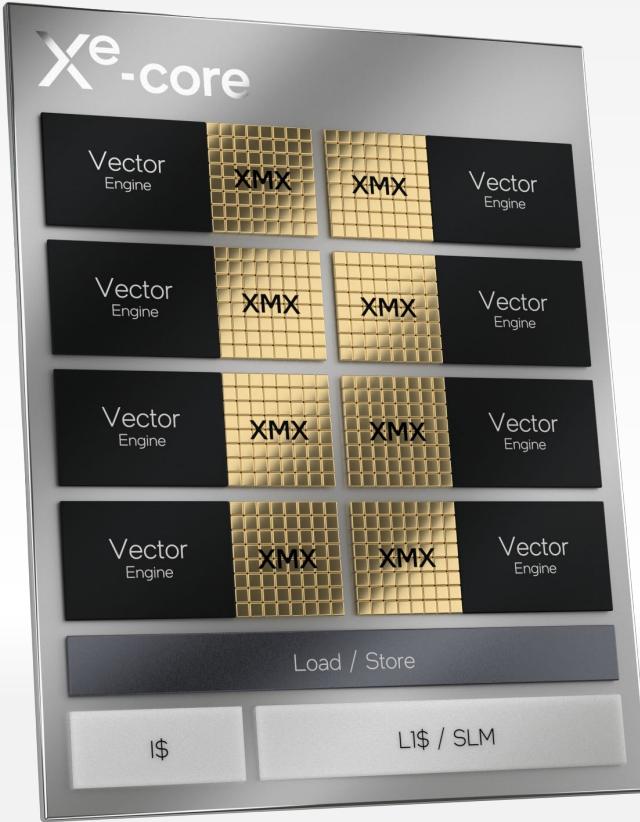


For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.



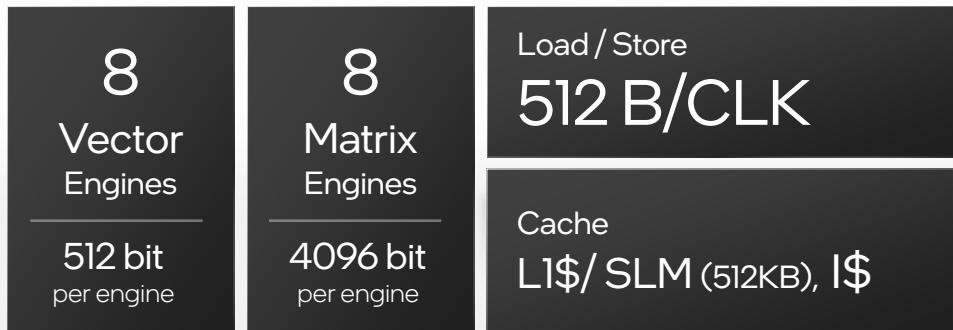
Architecture

Hong Jiang



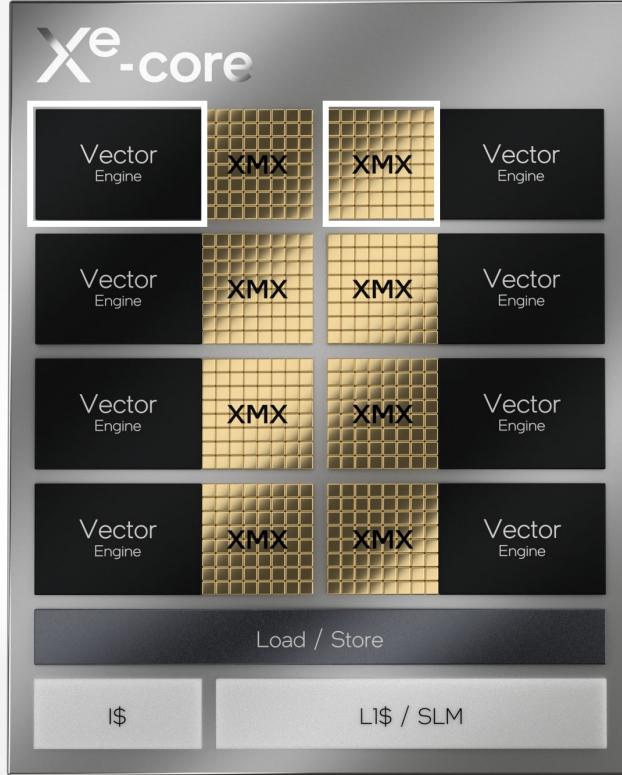
Xe -core

Compute Building Block of X^e HPC-based GPUs

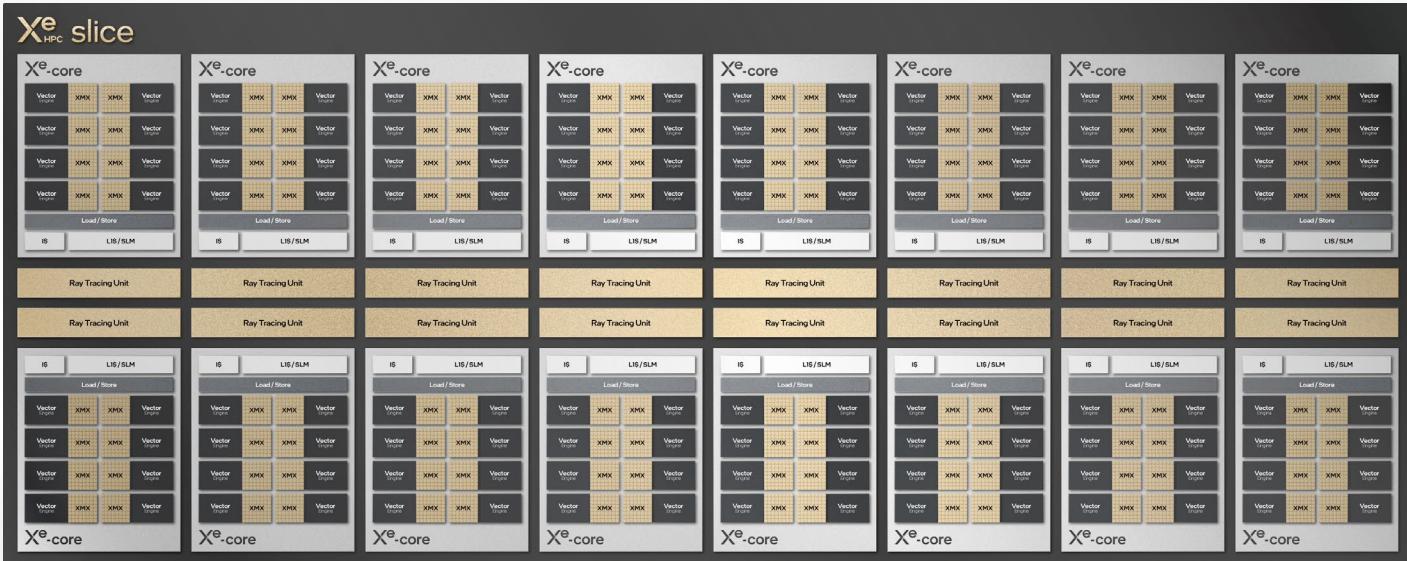




Vector Engine (ops/clk)
256 FP32
256 FP64
512 FP16

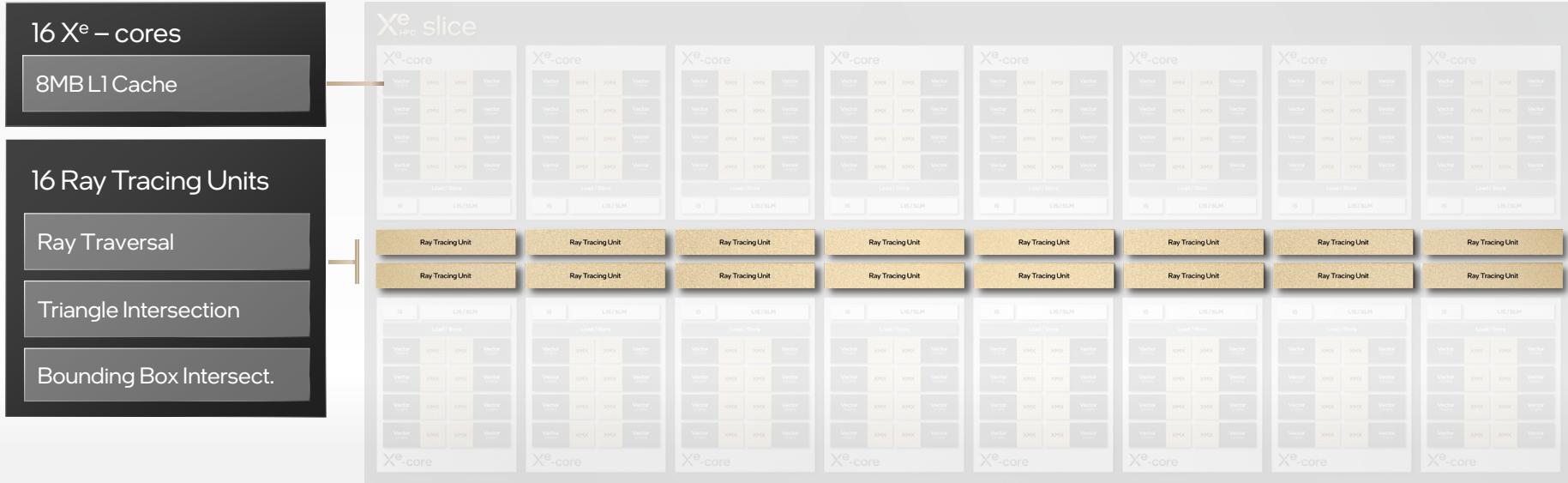


Matrix Engine (ops/clk)
2048 TF32
4096 FP16
4096 BF16
8192 INT8





Xe HPC Slice





16 X^e – cores

8MB L1 Cache

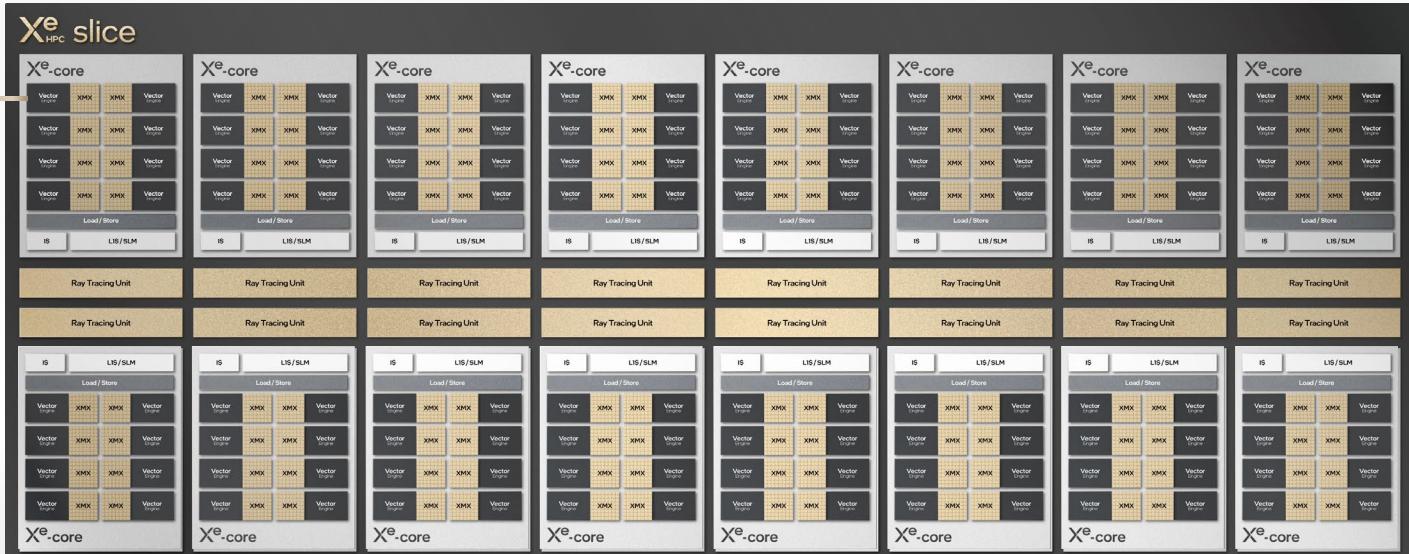
16 Ray Tracing Units

Ray Traversal

Triangle Intersection

Bounding Box Intersect.

1 Hardware Context



Up to

4 Slices

64 X^e - cores

64 Ray Tracing Units

4 Hardware Contexts

L2 Cache

4 HBM2e controllers

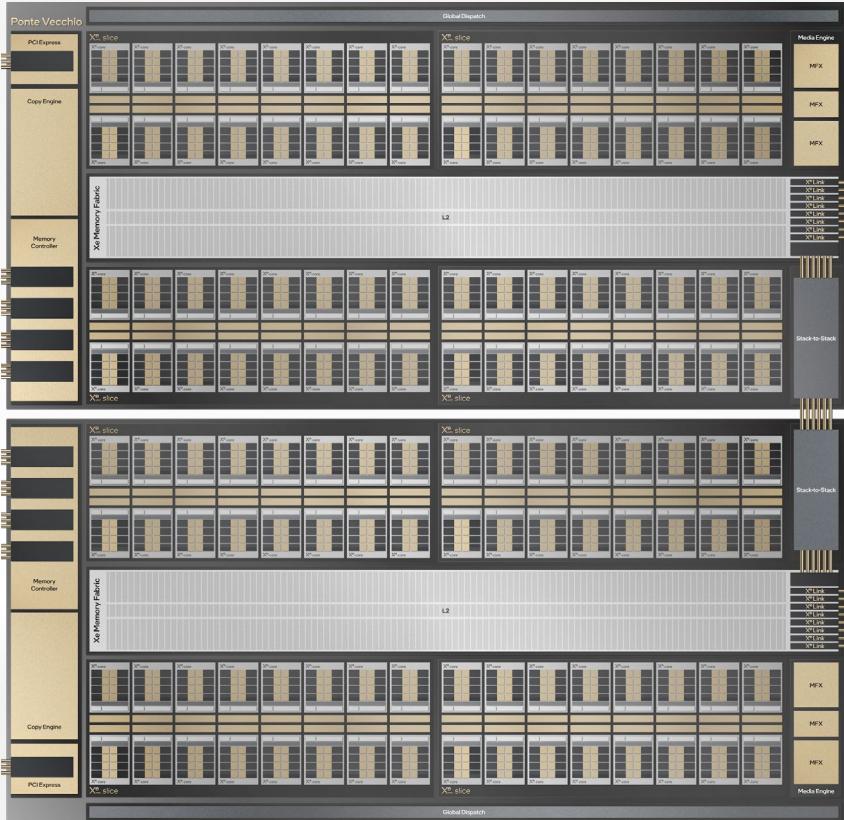
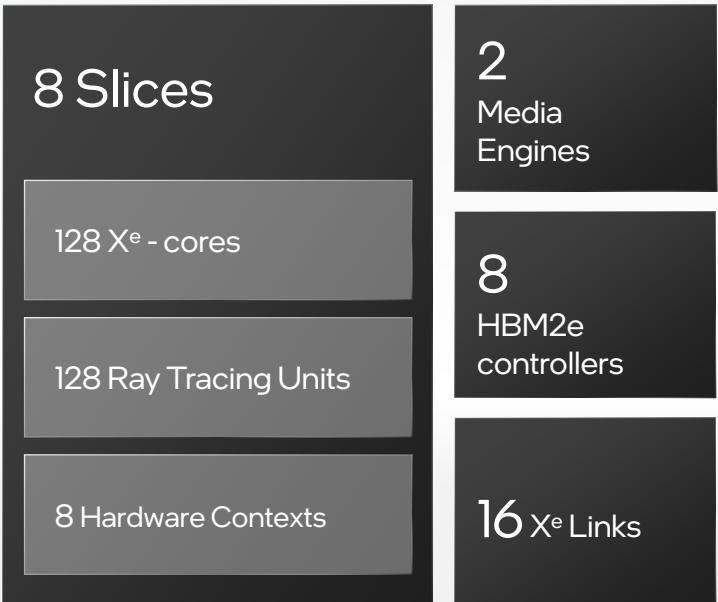
1 Media Engine

8 X^e Links



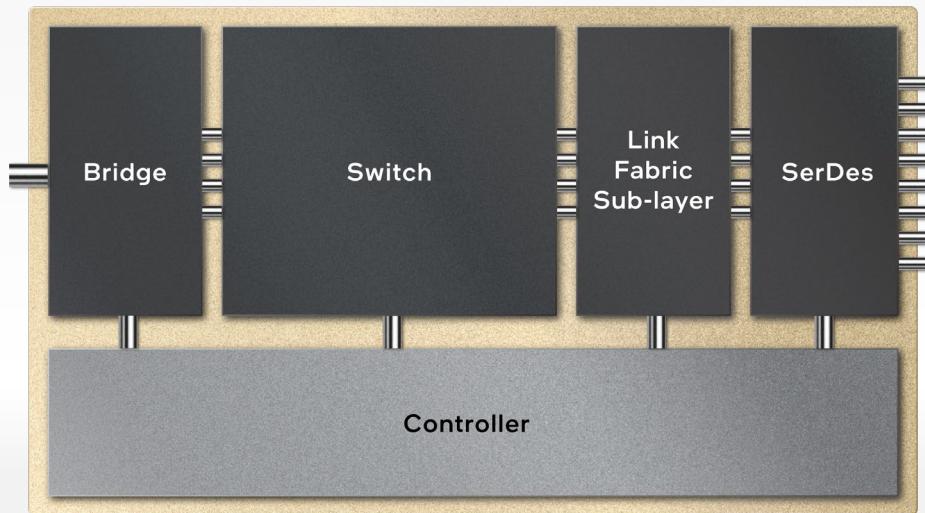
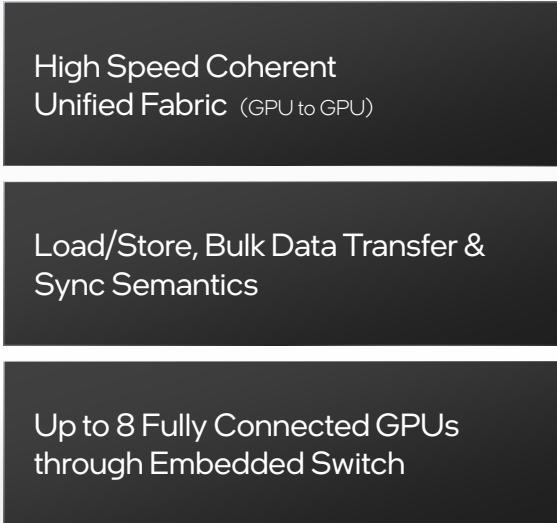


2 - Stack



For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Xe Link

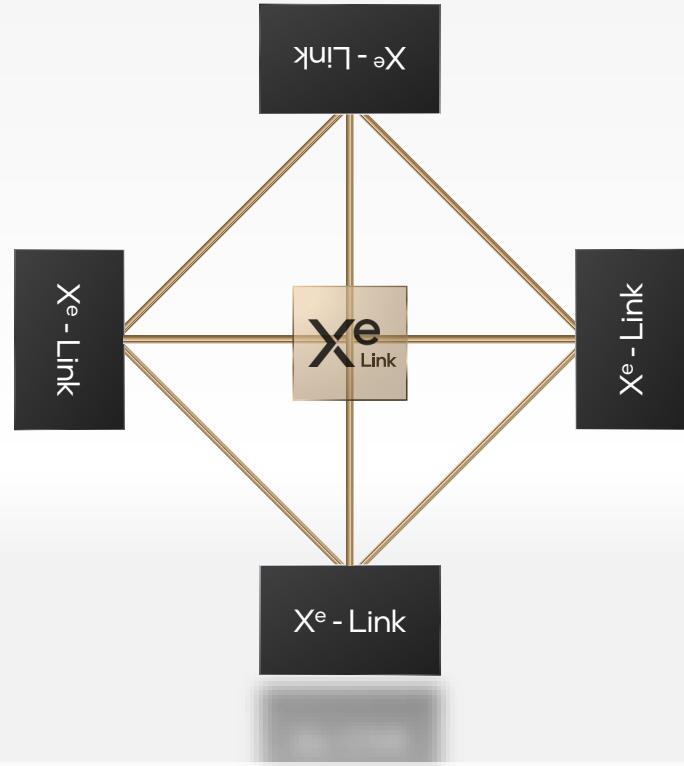


Xe Link for Scalability



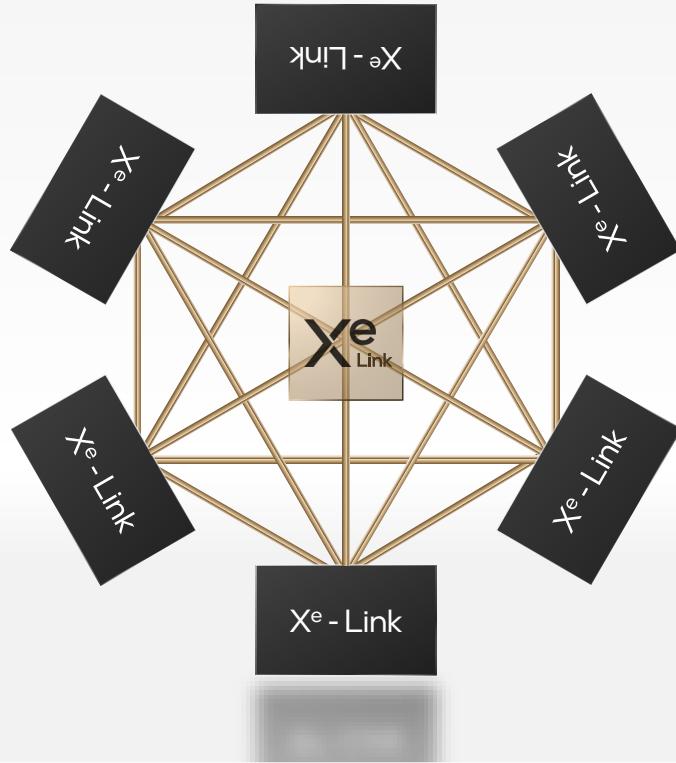


Xe Link for Scalability



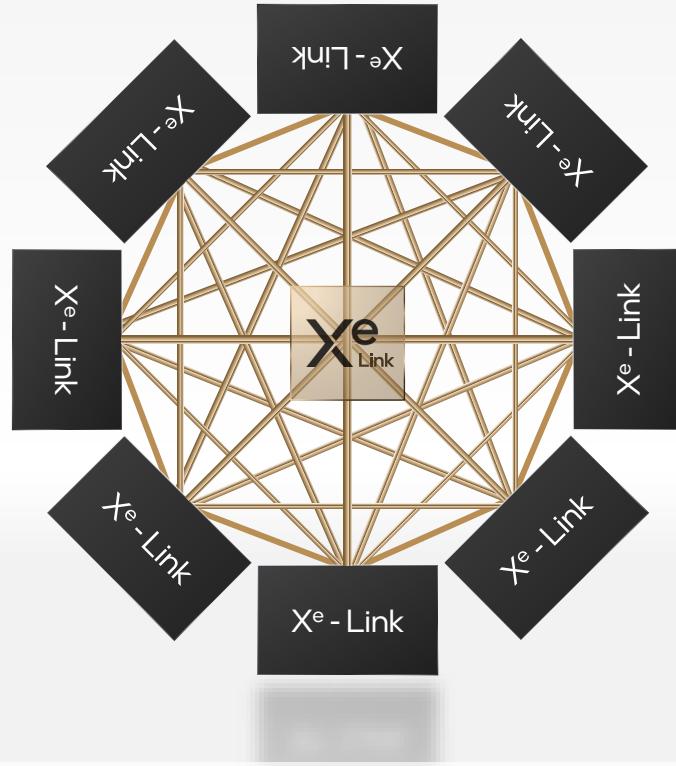


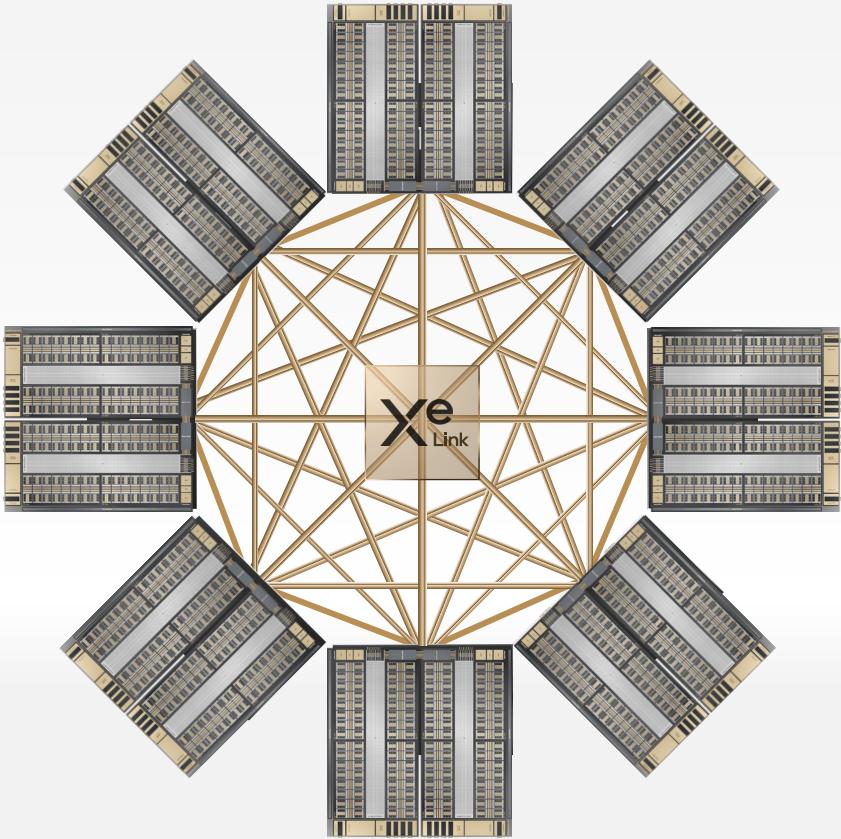
Xe Link for Scalability





Link for Scalability





8x System Compute Rates

Vector

8x Up to **32,768**
FP64 Ops/CLK

8x Up to **262,144**
TF32 Ops/CLK

8x Up to **524,288**
BF16 Ops/CLK

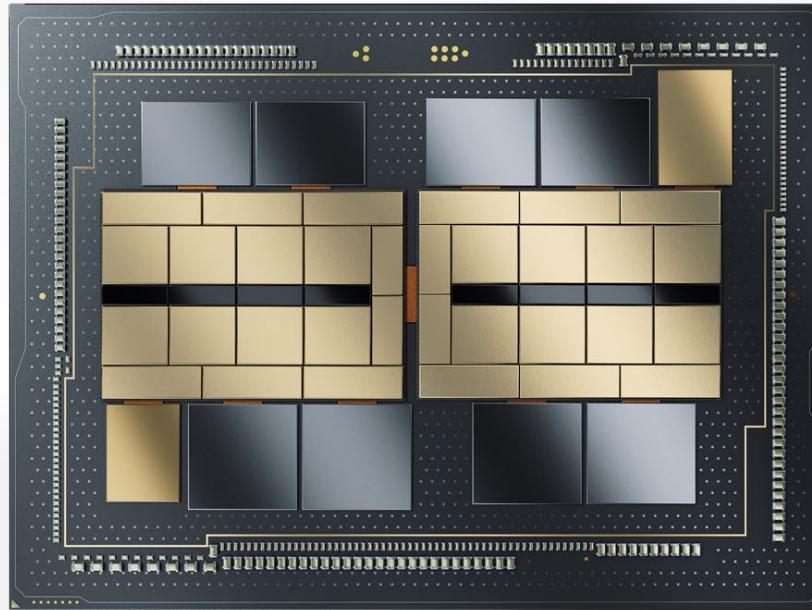
Matrix

8x Up to **1,048,576**
INT8 Ops/CLK

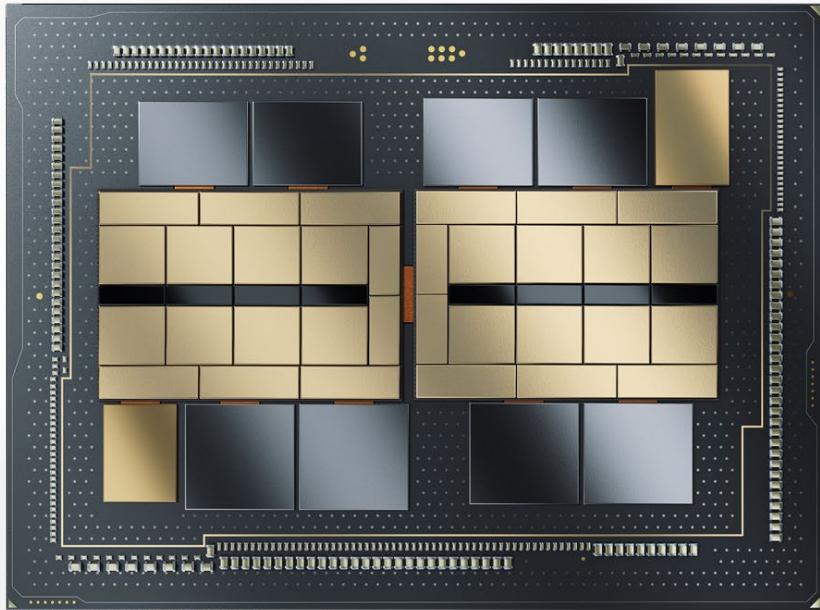
Ponte Vecchio

Masooma Bhaiwala

Ponte Vecchio



Ponte Vecchio



New **Verification Methodology**

New **Software**

New **Reliability Methodology**

New **Signal Integrity Techniques**

New **Interconnects**

New **Power Delivery Technology**

New **Packaging Technology**

New **I/O Architecture**

New **Memory Architecture**

New **IP Architecture**

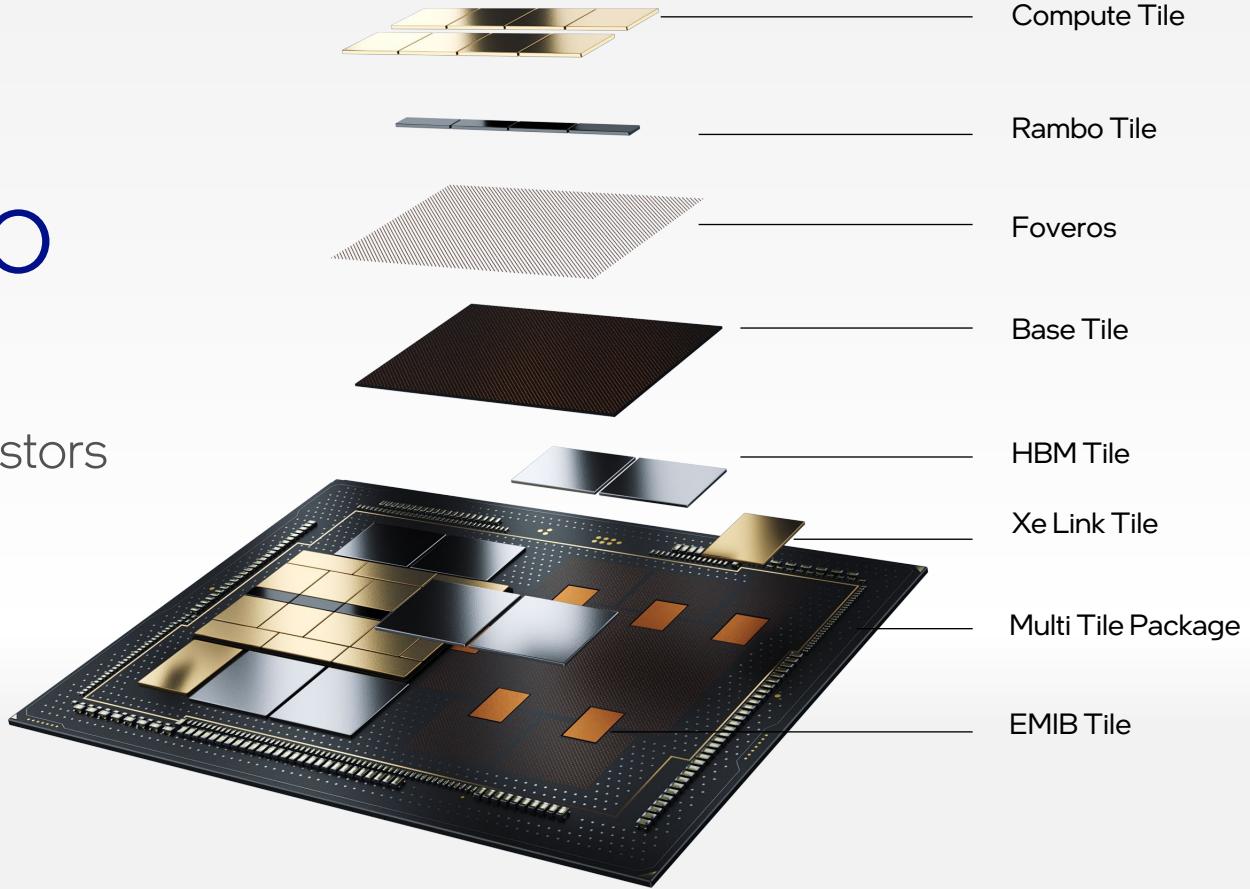
New **SOC Architecture**

Ponte Vecchio soc

>100 Billion Transistors

47 Active Tiles

5 Process Nodes



Ponte Vecchio

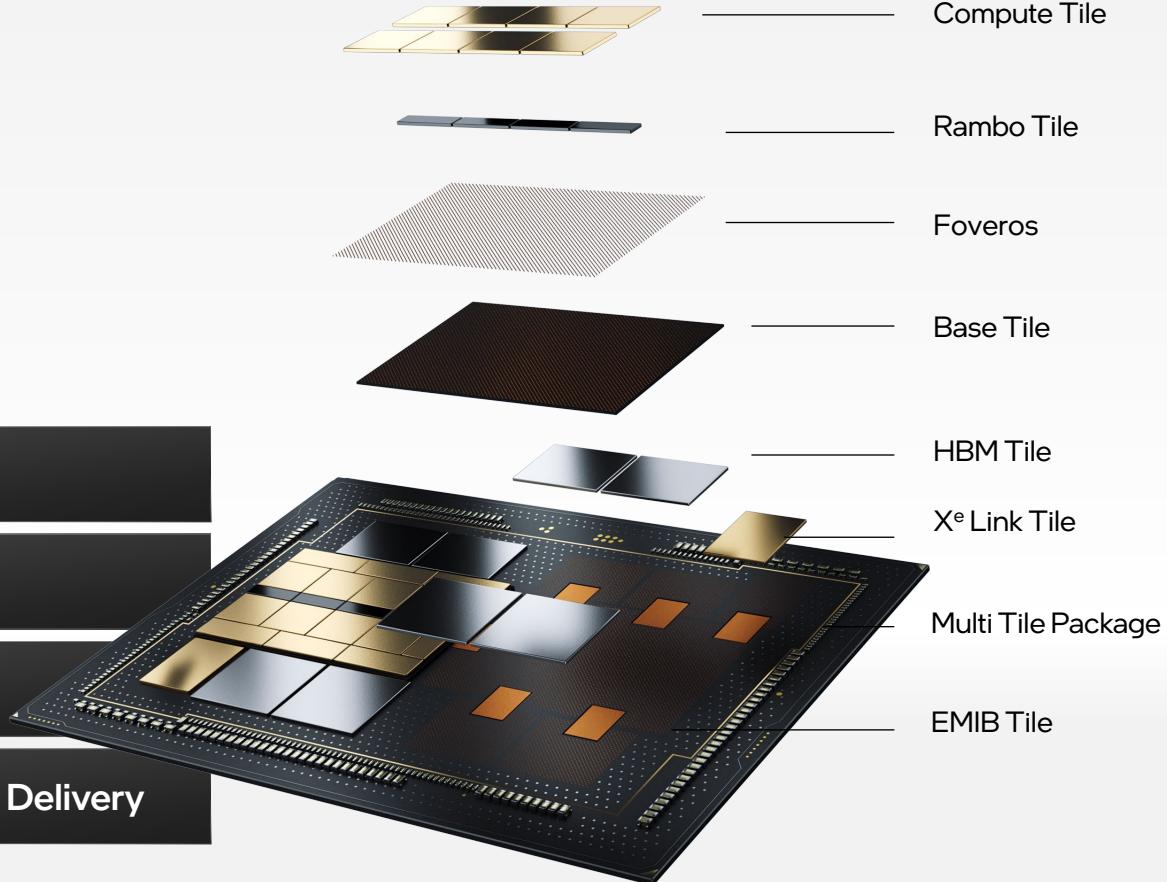
Key Challenges

Scale of Integration

Foveros Implementation

Verification Tools & Methods

Signal Integrity, Reliability & Power Delivery



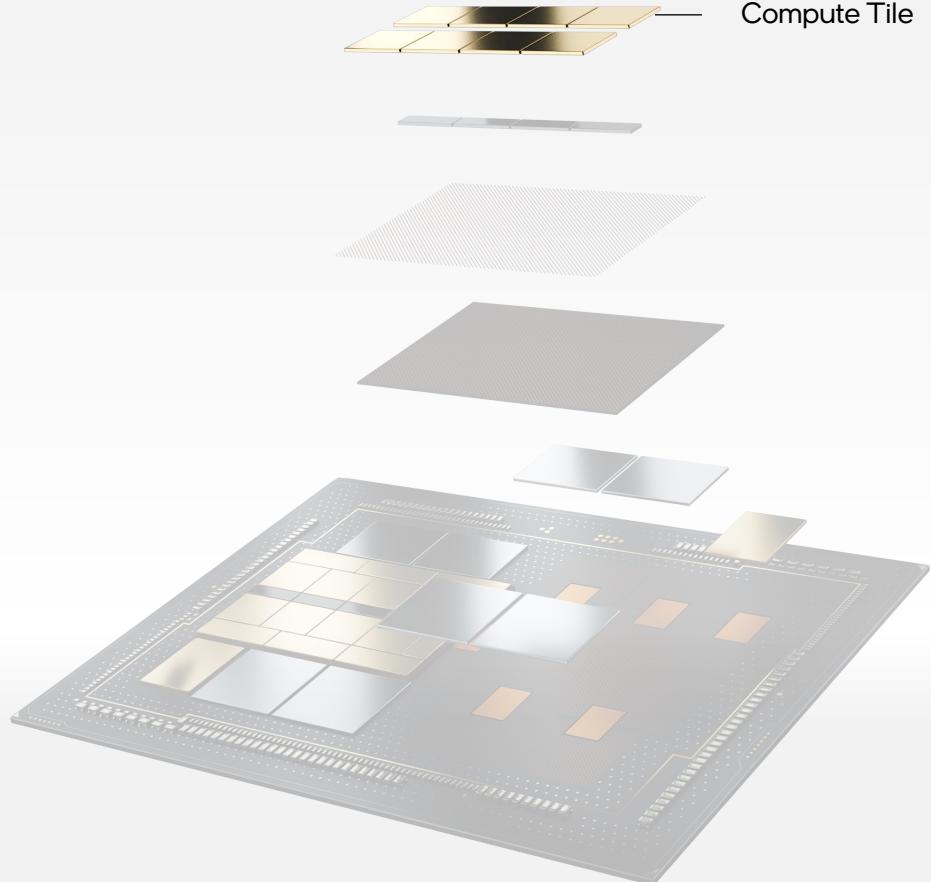
Ponte Vecchio

Compute Tiles

Per Tile
8
X^e-cores

L1 Cache
4MB
Per Tile

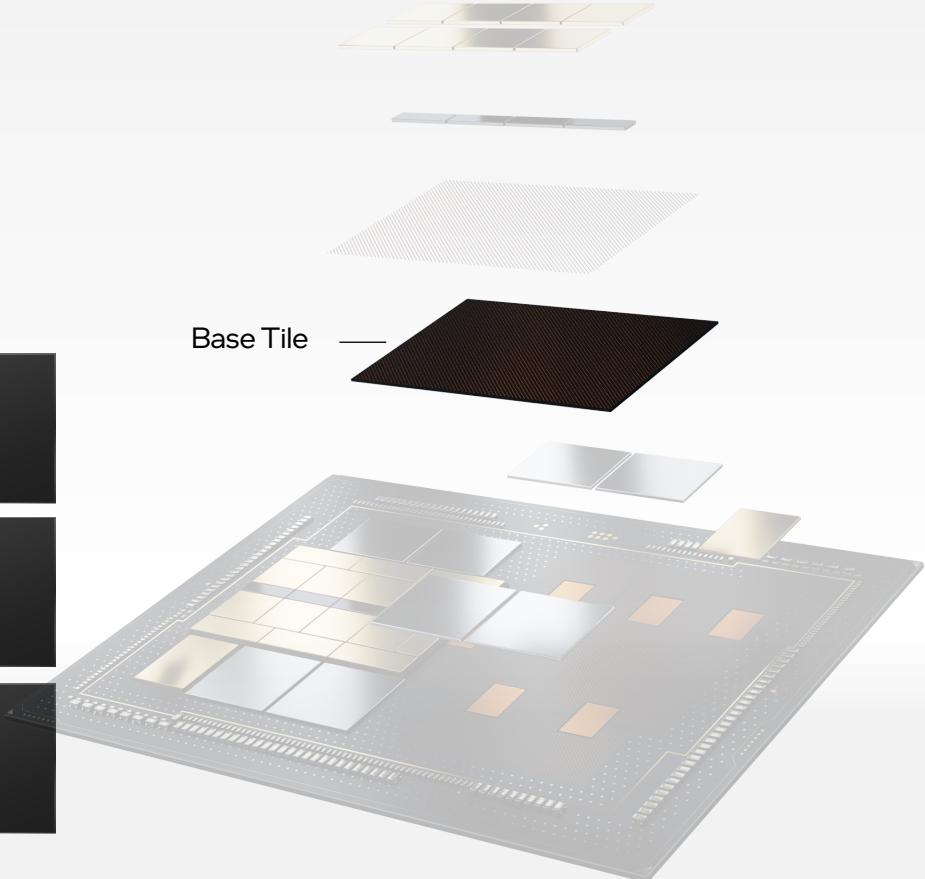
Built on
TSMC
N5



Ponte Vecchio

Base Tile

Built on Intel 7 FOVEROS	Area 640mm²	HBM2e
L2 Cache 144MB	Host Interface PCIe Gen5	MDFI



Ponte Vecchio

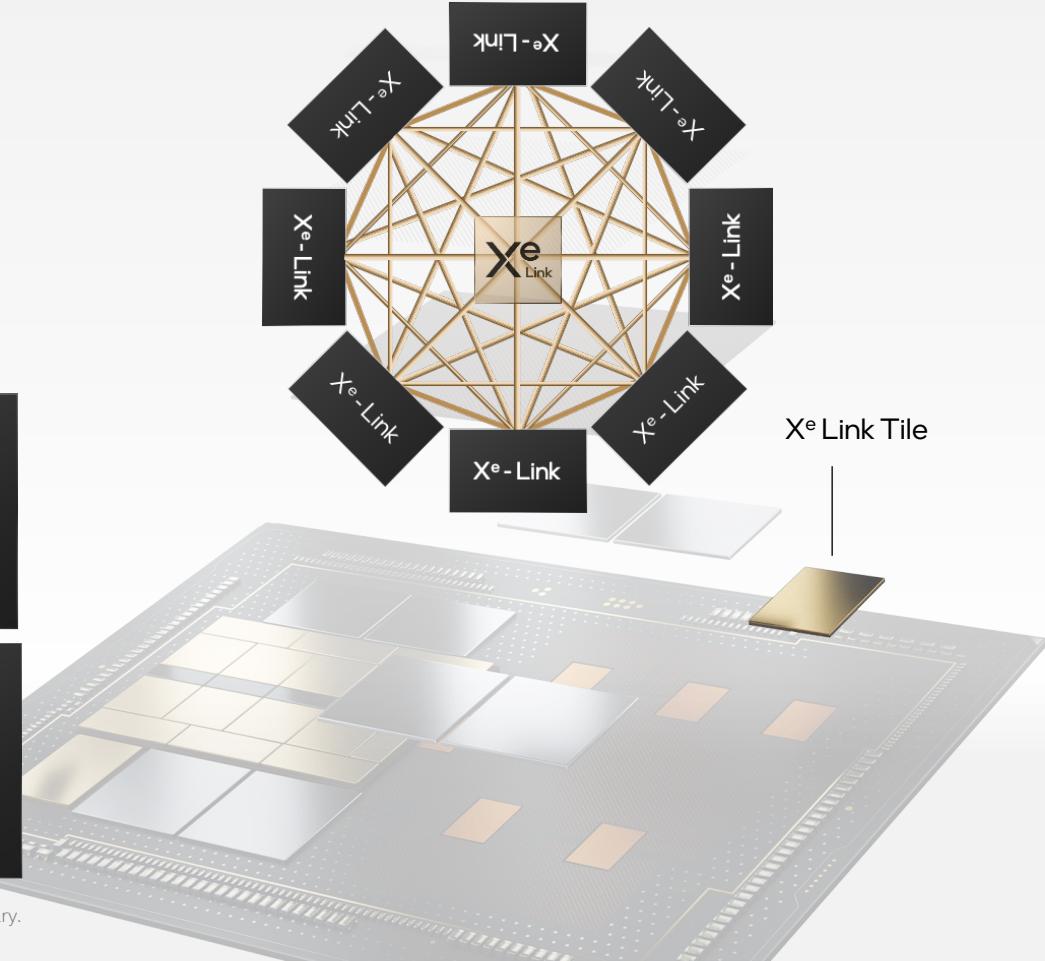
X^e Link Tile

Per Tile
8 X^e Links

8 ports
Embedded Switch

Built on
TSMC N7

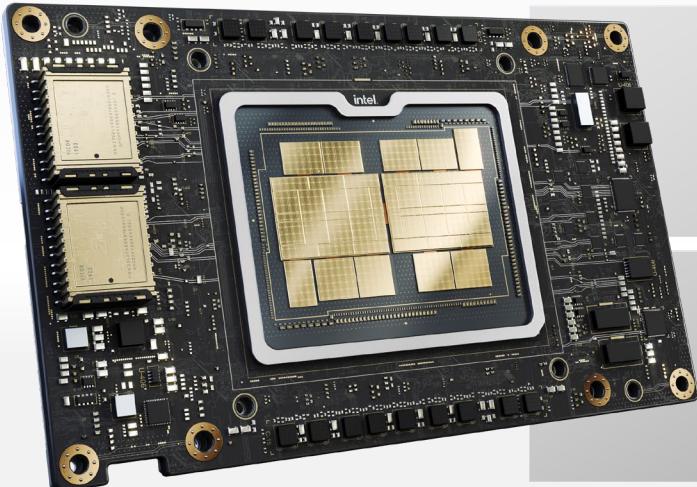
Up to
90G
Serdes



For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Ponte Vecchio

Execution Progress



A0 Silicon Current Status

> 45 TFLOPS

FP32 Throughput

> 5 TBps

Memory Fabric Bandwidth

> 2 TBps

Connectivity Bandwidth

For workloads and configurations visit www.intel.com/ArchDay21claims. Results may vary.

Accelerated Compute Systems

Ponte Vecchio
OAM



Ponte Vecchio
x4 Subsystem
with X^e Links

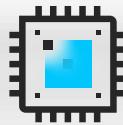
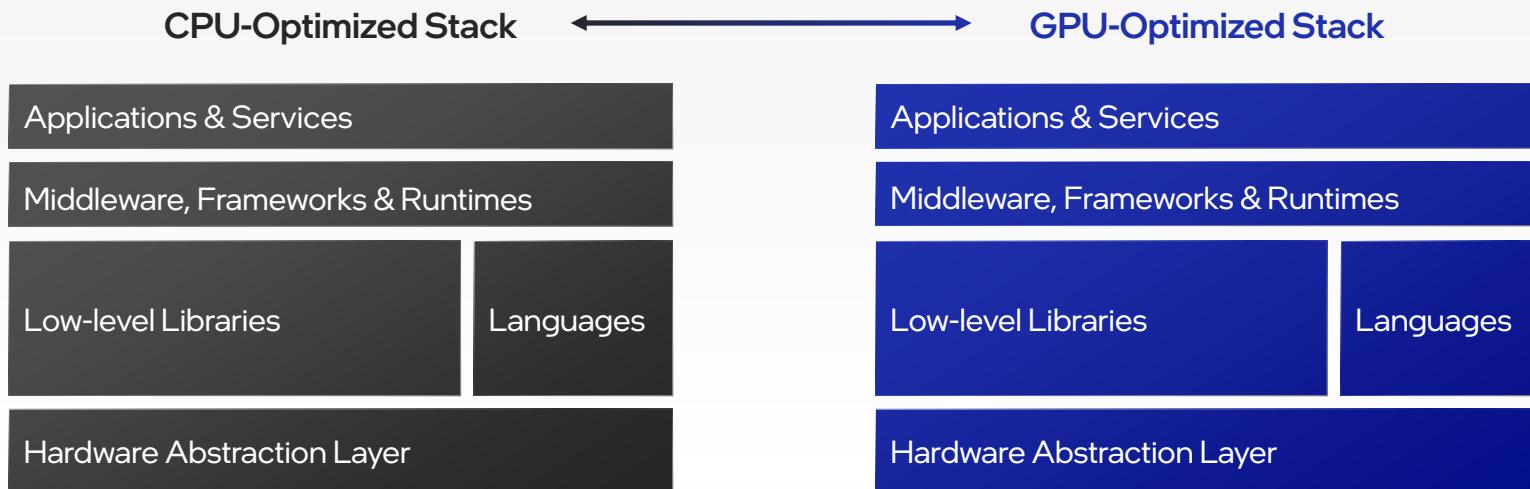


Ponte Vecchio x4 Subsystem
with X^e Links

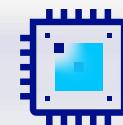
+ 2S Sapphire Rapids



Overcoming Separate CPU and GPU Software Stacks



CPU



GPU

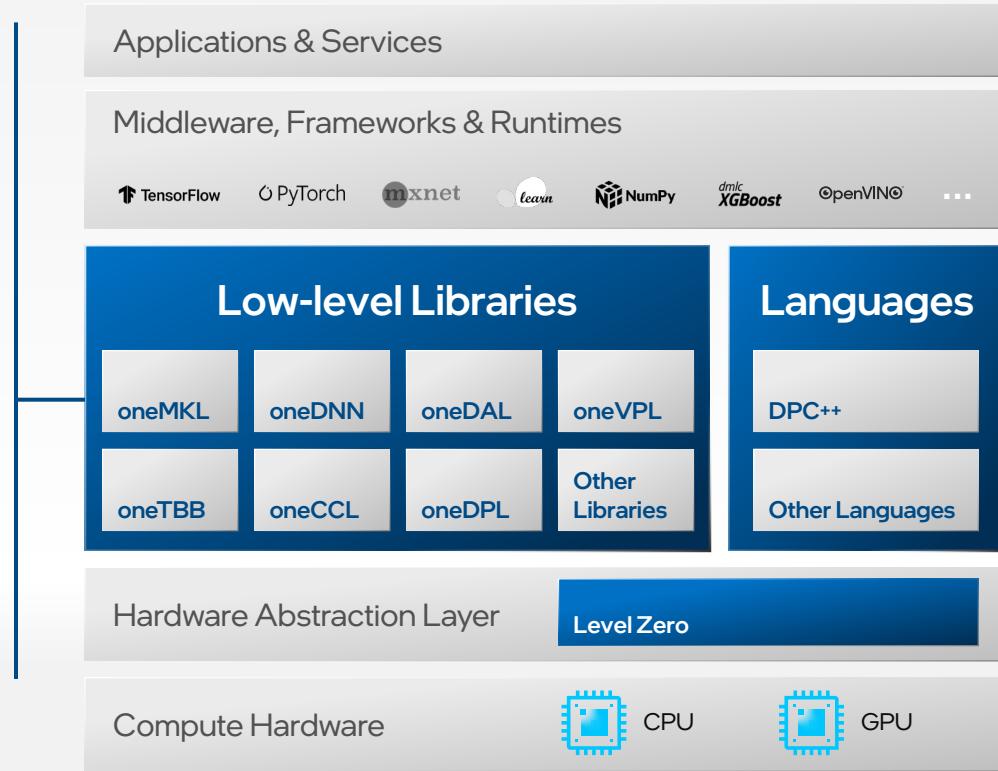


Freedom from proprietary programming models

Full performance from the hardware

Piece of mind for developers

CPU & XPU - Optimized Stack



oneAPI Industry Momentum

Cross-Vendor

3rd-party implementations on

Nvidia GPU

Arm CPU

Huawei ASIC

AMD GPU

Evolving Spec

Provisional spec v1.1 released May'21
with deep industry leader involvement

+ Graph interfaces for Deep Learning workloads

+ Advanced raytracing libraries



Industry Momentum

End Users



National Labs



ISVs & OSVs



OEMs & SIs



Universities & Research Institutes



CSPs & Frameworks



>200K Developers

Unique installs of Intel® oneAPI product since Dec'20 release

>300 Applications

Deployed in market using Intel® oneAPI language & libraries

>80 HPC & AI Applications

Functional on Intel's Xe HPC architecture using Intel® oneAPI



1
oneAPI

Toolkits v2021.3
Available Now

>200K Developers

Unique installs of Intel® oneAPI product since Dec'20 release

>300 Applications

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1
oneAPI

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1
oneAPI

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Deployed in market using Intel® oneAPI language & libraries

>80 HPC & AI Applications

Functional on Intel's Xe HPC architecture using Intel® oneAPI



1
oneAPI



Aurora

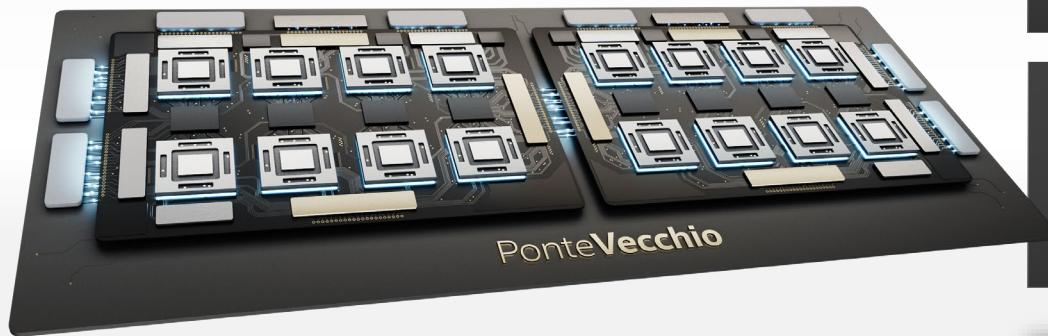
Blade

Building Block for the ExaScale Supercomputer



Ponte Vecchio

The vision 2 years ago...



**Leadership Performance
for HPC/AI**

**Connectivity to drive scaleup
and scale out**

**Unified Programming Model
powered with oneAPI**



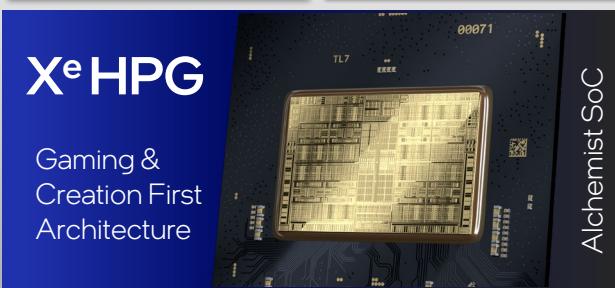
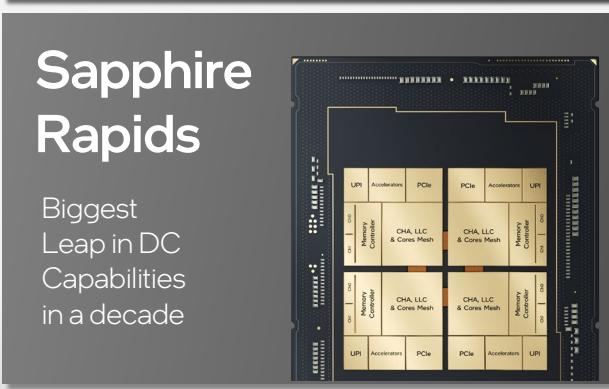
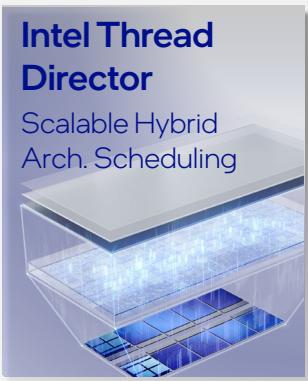
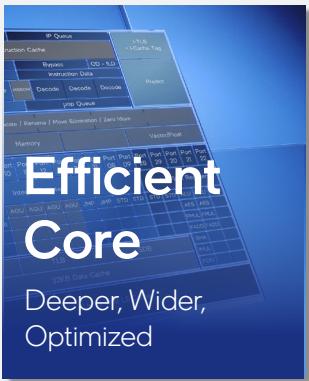
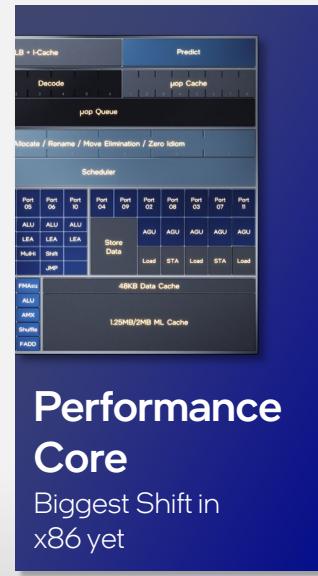
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